SONY

Diagonal 6.3 mm (Type 1 / 2.9) CMOS solid-state Image Sensor with Square Pixel for Color Cameras

IMX273LQR-C

Pregius

Description

The IMX273LQR-C is a diagonal 6.3mm (Type 1 / 2.9) CMOS active pixel type solid-state image sensor with a square pixel array and 1.58 M effective pixels. This chip features a global shutter with variable charge-integration time. This chip operates with analog 3.3 V, digital 1.2 V, and interface 1.8 V triple power supply, and has low power consumption. High sensitivity, low dark current and low PLS characteristics are achieved.
(Applications: FA cameras)

Features

- ◆ CMOS active pixel type dots
- ◆ Built-in timing adjustment circuit, H/V driver and serial communication circuit
- ◆ Global shutter function
- ◆ Input frequency
  37.125 MHz / 74.25 MHz / 54 MHz
- ◆ Number of recommended recording pixels: 1440 (H) × 1080 (V) approx. 1.55 M pixels
  Readout mode
  All-pixel scan mode
  Vertical / Horizontal 1 / 2 Subsampling mode
  ROI mode
  Vertical / Horizontal - Normal / Inverted readout mode
- ◆ Readout rate
  Maximum frame rate in
  All-pixel scan mode: 8 bit 276.0 frame/s, 10 bit: 226.5 frame/s, 12 bit: 165.9 frame/s
- ◆ Variable-speed shutter function (resolution 1 H units)
- ◆ 8-bit / 10-bit / 12-bit A/D converter
- ◆ CDS / PGA function
  0 dB to 24 dB: Analog Gain (0.1 dB step)
  24.1 dB to 48 dB: Analog Gain: 24 dB + Digital Gain: 0.1 dB to 24 dB (0.1 dB step)
- ◆ I/O interface
  Low voltage LVDS (150 mVp-p) serial (2 ch / 4 ch / 8 ch switching) DDR output
- ◆ Recommended lens F number: 2.8 or more (Close side)
- ◆ Recommended exit pupil distance: –100 mm to –∞

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Device Structure

- CMOS image sensor
- Image size
  Diagonal 6.3 mm (Type 1 / 2.9)   Approx. 1.58 M pixels   All-pixel
- Total number of pixels
  1456 (H) × 1098 (V)   Approx. 1.60 M pixels
- Number of effective pixels
  1456 (H) × 1088 (V)   Approx. 1.58 M pixels
- Number of active pixels
  1456 (H) × 1088 (V)   Approx. 1.58 M pixels
- Number of recommended recording pixels
  1440 (H) × 1080 (V)   Approx. 1.56 M pixels   All-pixel
- Unit cell size
  3.45 µm (H) × 3.45 µm (V)
- Optical black
  Horizontal (H) direction: Front 0 pixels, rear 0 pixels
  Vertical (V) direction: Front 10 pixels, rear 0 pixels
- Substrate material
  Silicon

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Absolute Maximum Ratings

Item	Symbol	Rating			Unit	Remarks
Supply voltage (Analog 3.3 V)	AV_{DD}	–0.3	to	+4.0	V	
Supply voltage (Interface 1.8 V)	OV_{DD}	–0.3	to	+3.3	V	
Supply voltage (Digital 1.2 V)	DV_{DD}	–0.3	to	+2.0	V	
Input voltage	VI	–0.3	to	OV_{DD} +0.3	V	Not exceed 3.3 V
Output voltage	VO	–0.3	to	OV_{DD} +0.3	V	Not exceed 3.3 V
Operating temperature	Topr	-30	to	+75	˚C	
Storage temperature	Tstg	-40	to	+85	˚C	
Performance guarantee temperature	Tspec	-10	to	+60	˚C	

Recommended Operating Conditions

Item	Symbol	Min.	Typ.	Max.	Unit
Supply voltage (Analog 3.3 V)	AV_{DD}	3.15	3.30	3.45	V
Supply voltage (Interface 1.8 V)	OV_{DD}	1.70	1.80	1.90	V
Supply voltage (Digital 1.2 V)	DV_{DD}	1.10	1.20	1.30	V

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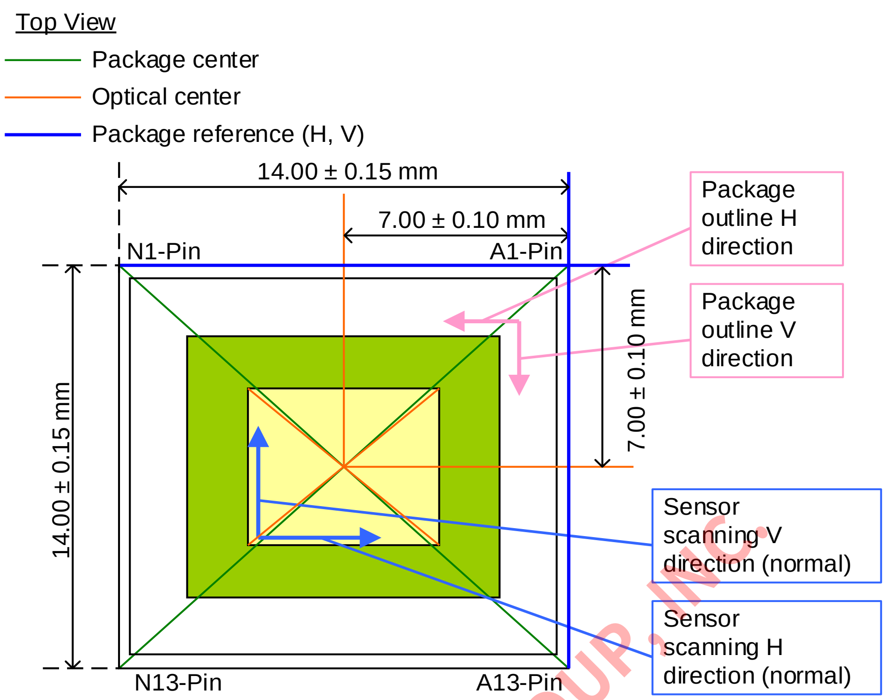
Chip Center and Optical Center



Optical Center

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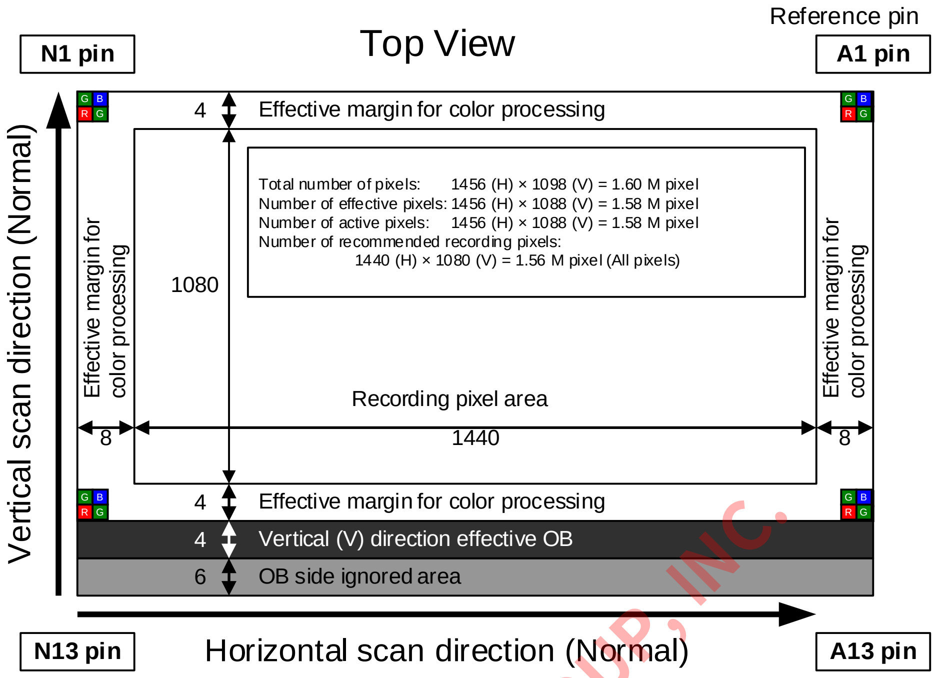
Pixel Arrangement



Pixel Arrangement

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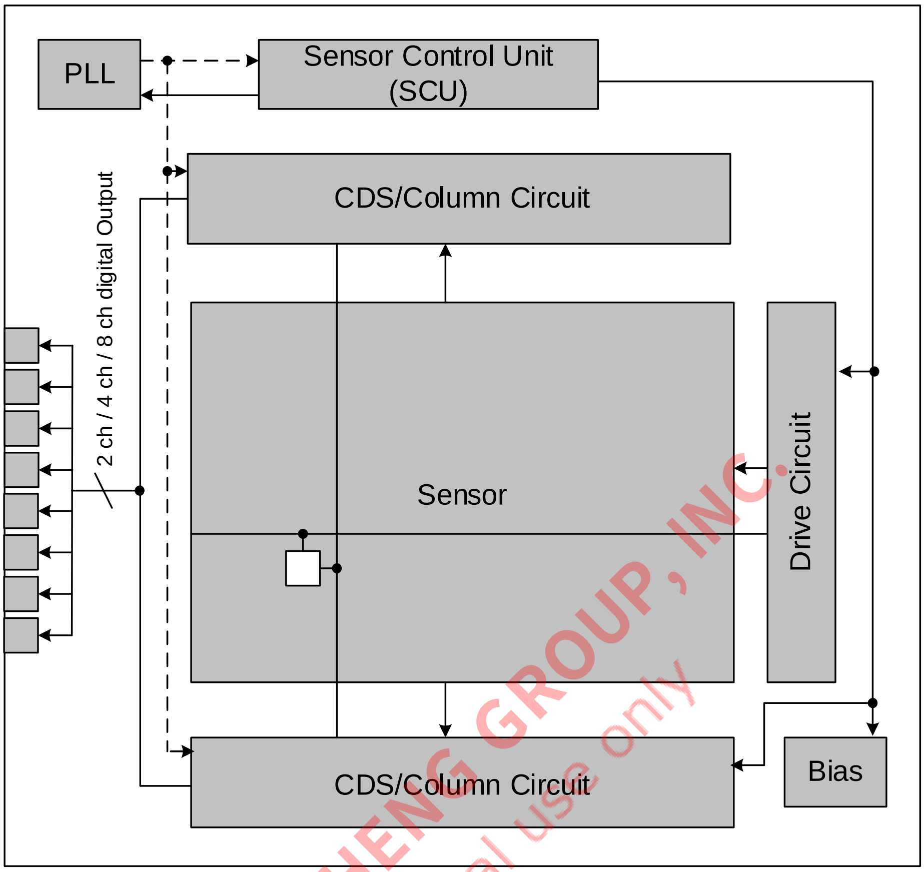
Block Diagram and Pin Configuration

(Top View)



Block Diagram

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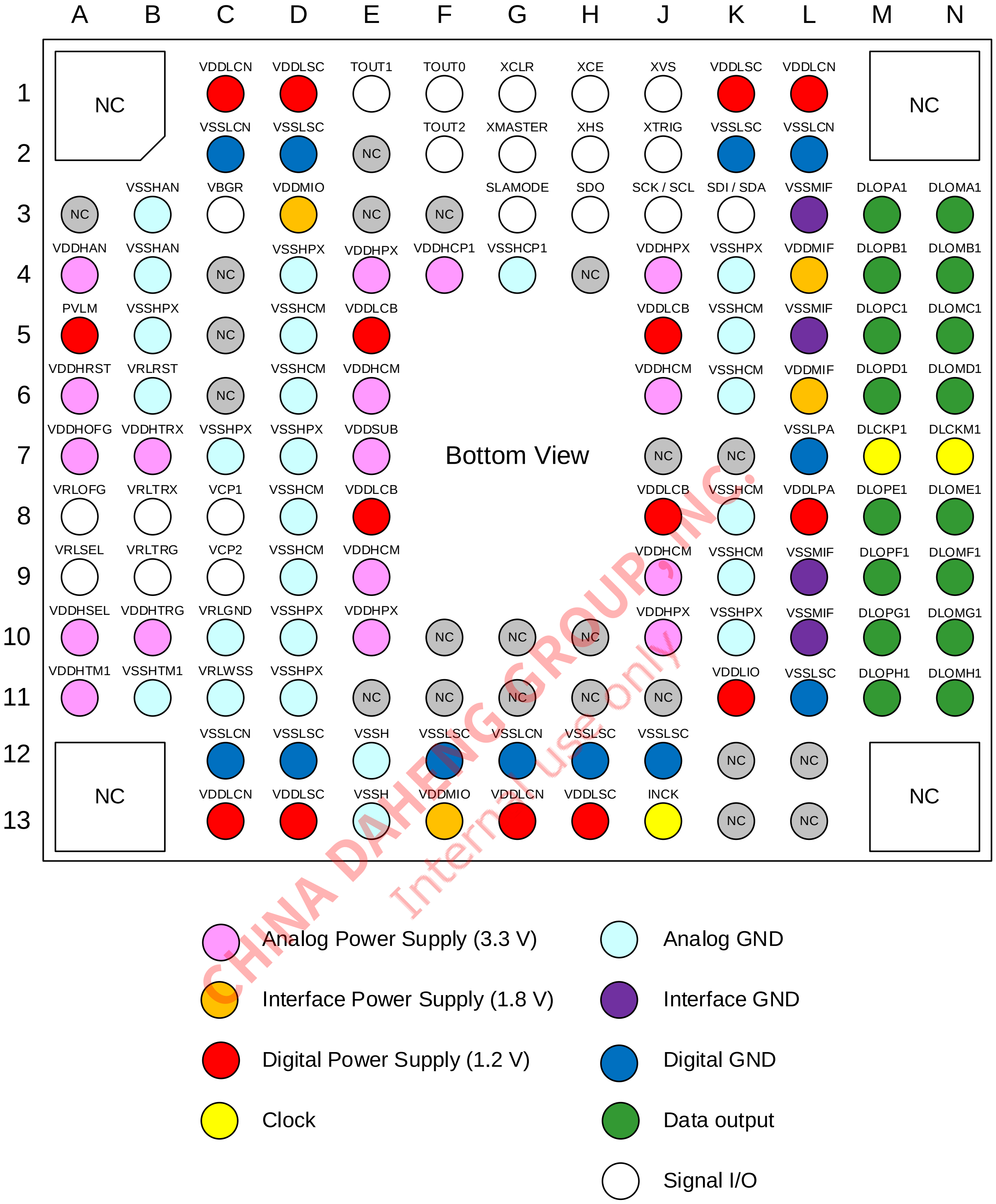

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Pin Configuration

Pin Description

No.	Pin No.	I/O	Analog / Digital	Symbol	Description
1	A1	—	—	N.C.	—
2	A3	—	—	N.C.	—
3	A4	Power	A	VDDHAN	3.3 V power supply
4	A5	Power	A	PVLM	1.2 V power supply
5	A6	Power	A	VDDHRST	3.3 V power supply
6	A7	Power	A	VDDHOFG	3.3 V power supply
7	A8	I	A	VRLOFG	Connect to VCP1
8	A9	I	A	VRLSEL	Connect to VCP1
9	A10	Power	A	VDDHSEL	3.3 V power supply
10	A11	Power	A	VDDHTM1	3.3 V power supply
11	A13	—	—	N.C.	—
12	B3	GND	A	VSSHAN	3.3 V GND
13	B4	GND	A	VSSHAN	3.3 V GND
14	B5	GND	A	VSSHPX	3.3 V GND
15	B6	GND	A	VRLRST	3.3 V GND
16	B7	Power	A	VDDHTRX	3.3 V power supply
17	B8	I	A	VRLTRX	Connect to VCP1
18	B9	I	A	VRLTRG	Connect to VCP2
19	B10	Power	A	VDDHTRG	3.3 V power supply
20	B11	GND	A	VSSHTM1	3.3 V GND
21	C1	Power	D	VDDLCN	1.2 V power supply
22	C2	GND	D	VSSLCN	1.2 V GND
23	C3	O	A	VBGR	Connect to 0.22µF to GND
24	C4	—	—	N.C.	—
25	C5	—	—	N.C.	—
26	C6	—	—	N.C.	—
27	C7	GND	A	VSSHPX	3.3 V GND
28	C8	O	A	VCP1	Connect to VRLSEL, VRLTRX, VRLOFG (Connect to 4.7µF × 2 to GND)
29	C9	O	A	VCP2	Connect to VRLTRG (Connect to 4.7µF × 2 to GND)
30	C10	GND	A	VRLGND	3.3 V GND
31	C11	GND	A	VRLWSS	3.3 V GND
32	C12	GND	D	VSSLCN	1.2 V GND
33	C13	Power	D	VDDLCN	1.2 V power supply
34	D1	Power	D	VDDLSC	1.2 V power supply
35	D2	GND	D	VSSLSC	1.2 V GND
36	D3	Power	D	VDDMIO	1.8 V power supply
37	D4	GND	A	VSSHPX	3.3 V GND
38	D5	GND	A	VSSHCM	3.3 V GND
39	D6	GND	A	VSSHCM	3.3 V GND
40	D7	GND	A	VSSHPX	3.3 V GND
41	D8	GND	A	VSSHCM	3.3 V GND
42	D9	GND	A	VSSHCM	3.3 V GND
43	D10	GND	A	VSSHPX	3.3 V GND
44	D11	GND	A	VSSHPX	3.3 V GND
45	D12	GND	D	VSSLSC	1.2 V GND
46	D13	Power	D	VDDLSC	1.2 V power supply
47	E1	O	D	TOUT1	Pulse1 output pin
48	E2	—	—	N.C.	—
49	E3	—	—	N.C.	—
50	E4	Power	A	VDDHPX	3.3 V power supply
51	E5	Power	A	VDDLCB	1.2 V power supply
52	E6	Power	A	VDDHCM	3.3 V power supply
53	E7	Power	A	VDDSUB	3.3 V power supply
54	E8	Power	A	VDDLCB	1.2 V power supply
55	E9	Power	A	VDDHCM	3.3 V power supply
56	E10	Power	A	VDDHPX	3.3 V power supply
57	E11	—	—	N.C.	—
58	E12	GND	A	VSSH	3.3 V GND
59	E13	GND	A	VSSH	3.3 V GND

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No.	Pin No.	I/O	Analog / Digital	Symbol	Description
60	F1	O	D	TOUT0	Pulse0 output pin
61	F2	O	D	TOUT2	Pulse2 output pin
62	F3	—	—	N.C.	—
63	F4	Power	A	VDDHCP1	3.3 V power supply
64	F10	—	—	N.C.	—
65	F11	—	—	N.C.	—
66	F12	GND	D	VSSLSC	1.2 V GND
67	F13	Power	D	VDDMIO	1.8 V power supply
68	G1	I	D	XCLR	System clear (Normal : High, Clear : Low)
69	G2	I	D	XMASTER	Master / Slave select (Slave Mode : High, Master Mode : Low)
70	G3	I	D	SLAMODE	Slave address select (37 : High, 36 : Low, 1A : both polarities)
71	G4	GND	A	VSSHCP1	3.3 V GND
72	G10	—	—	N.C.	—
73	G11	—	—	N.C.	—
74	G12	GND	D	VSSLCN	1.2 V GND
75	G13	Power	D	VDDLCN	1.2 V power supply
76	H1	I	D	XCE	4-wire : Serial communication I/F XCE pin I^2C : Fixed to High
77	H2	I/O	D	XHS	Horizontal sync signal
78	H3	O	D	SDO	4-wire : Serial communication I/F SDO pin I^2C : OPEN
79	H4	—	—	N.C.	—
80	H10	—	—	N.C.	—
81	H11	—	—	N.C.	—
82	H12	GND	D	VSSLSC	1.2 V GND
83	H13	Power	D	VDDLSC	1.2 V power supply
84	J1	I/O	D	XVS	Vertical sync signal
85	J2	I	D	XTRIG	Trigger input
86	J3	I	D	SCK / SCL	4-wire : Serial communication I/F SCK pin I^2C : Serial clock line
87	J4	Power	A	VDDHPX	3.3 V power supply
88	J5	Power	A	VDDLCB	1.2 V power supply
89	J6	Power	A	VDDHCM	3.3 V power supply
90	J7	—	—	N.C.	—
91	J8	Power	A	VDDLCB	1.2 V power supply
92	J9	Power	A	VDDHCM	3.3 V power supply
93	J10	Power	A	VDDHPX	3.3 V power supply
94	J11	—	—	N.C.	—
95	J12	GND	D	VSSLSC	1.2 V GND
96	J13	I	D	INCK	Maser clock input
97	K1	Power	D	VDDLSC	1.2 V power supply
98	K2	GND	D	VSSLSC	1.2 V GND
99	K3	I/O	D	SDI / SDA	4-wire : Serial communication I/F SDI pin I^2C : Serial data line
100	K4	GND	A	VSSHPX	3.3 V GND
101	K5	GND	A	VSSHCM	3.3 V GND
102	K6	GND	A	VSSHCM	3.3 V GND
103	K7	—	—	N.C.	—
104	K8	GND	A	VSSHCM	3.3 V GND
105	K9	GND	A	VSSHCM	3.3 V GND
106	K10	GND	A	VSSHPX	3.3 V GND
107	K11	Power	D	VDDLIO	1.2 V power supply
108	K12	—	—	N.C.	—
109	K13	—	—	N.C.	—

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No.	Pin No.	I/O	Analog / Digital	Symbol	Description
110	L1	Power	D	VDDLCN	1.2 V power supply
111	L2	GND	D	VSSLCN	1.2 V GND
112	L3	GND	D	VSSMIF	1.8 V GND
113	L4	Power	D	VDDMIF	1.8 V power supply
114	L5	GND	D	VSSMIF	1.8 V GND
115	L6	Power	D	VDDMIF	1.8 V power supply
116	L7	GND	D	VSSLPA	1.2 V GND
117	L8	Power	D	VDDLPA	1.2 V power supply
118	L9	GND	D	VSSMIF	1.8 V GND
119	L10	GND	D	VSSMIF	1.8 V GND
120	L11	GND	D	VSSLSC	1.2 V GND
121	L12	—	—	N.C.	—
122	L13	—	—	N.C.	—
123	M3	O	D	DLOPA1	Low boltage LVDS serial output (Data)
124	M4	O	D	DLOPB1	Low boltage LVDS serial output (Data)
125	M5	O	D	DLOPC1	Low boltage LVDS serial output (Data)
126	M6	O	D	DLOPD1	Low boltage LVDS serial output (Data)
127	M7	O	D	DLCKP1	Low boltage LVDS serial output (Clock)
128	M8	O	D	DLOPE1	Low boltage LVDS serial output (Data)
129	M9	O	D	DLOPF1	Low boltage LVDS serial output (Data)
130	M10	O	D	DLOPG1	Low boltage LVDS serial output (Data)
131	M11	O	D	DLOPH1	Low boltage LVDS serial output (Data)
132	N1	—	—	N.C.	—
133	N3	O	D	DLOMA1	Low boltage LVDS serial output (Data)
134	N4	O	D	DLOMB1	Low boltage LVDS serial output (Data)
135	N5	O	D	DLOMC1	Low boltage LVDS serial output (Data)
136	N6	O	D	DLOMD1	Low boltage LVDS serial output (Data)
137	N7	O	D	DLCKM1	Low boltage LVDS serial output (Clock)
138	N8	O	D	DLOME1	Low boltage LVDS serial output (Data)
139	N9	O	D	DLOMF1	Low boltage LVDS serial output (Data)
140	N10	O	D	DLOMG1	Low boltage LVDS serial output (Data)
141	N11	O	D	DLOMH1	Low boltage LVDS serial output (Data)
142	N13	—	—	N.C.	—

* N.C. pins in the table above should be left open on the board.

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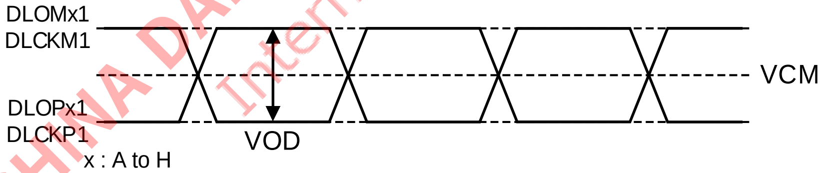
Electrical Characteristics

DC Characteristics

Item		Pins	Symbol	Conditions	Min.	Typ.	Max.	Unit
Supply voltage	Analog	$V_{DD}Hx$	AV_{DD}	—	3.15	3.30	3.45	V
Supply voltage	Interface	$V_{DD}Mx$	OV_{DD}	—	1.70	1.80	1.90	V
Supply voltage	Digital	$V_{DD}Lx$	DV_{DD}	—	1.10	1.20	1.30	V
Digital input voltage		XHS XVS XCLR INCK XMASTER SLAMODE SCK SDI XCE XTRIG	VIH	XVS / XHS in Slave mode	0.8 × OV_{DD}	—	—	V
Digital input voltage		XHS XVS XCLR INCK XMASTER SLAMODE SCK SDI XCE XTRIG	VIL	XVS / XHS in Slave mode	—	—	0.2 × OV_{DD}	V
Digital output voltage		DLOPx1 DLOMx1 DCKP1 DCKM1 x: A to H	VCM	Low voltage LVDS (termination resistance: 100 Ω)	—	$OV_{DD}/2$	—	mV
Digital output voltage		DLOPx1 DLOMx1 DCKP1 DCKM1 x: A to H	VOD	Low voltage LVDS (termination resistance: 100 Ω)	100	150	210	mV
Digital output voltage		XHS XVS SDO TOUT1 TOUT2	VOH	XVS / XHS in Master mode	OV_{DD} -0.4	—	—	V
Digital output voltage		XHS XVS SDO TOUT1 TOUT2	VOL	XVS / XHS in Master mode	—	—	0.4	V

LVDS output



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Power Consumption

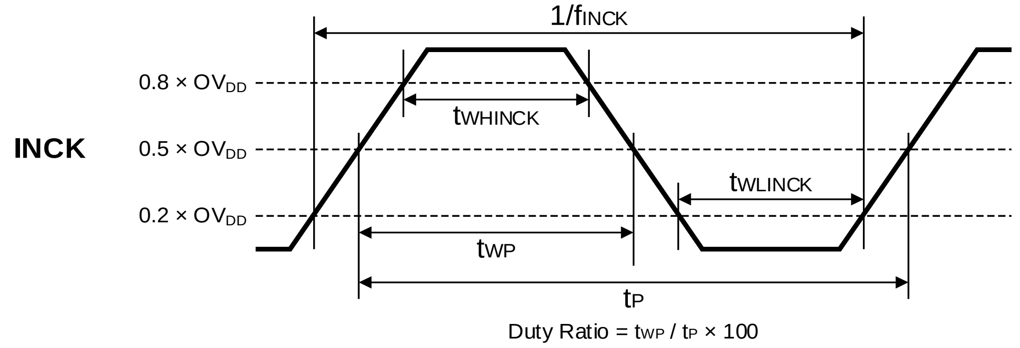
Item	Pins	Symbol	Typ.	Max.	Unit
Operating current Serial LVDS 8 ch 12 bit 165.9 frame/s	$V_{DD}H$	IAV_{DD}	125	200	mA
	$V_{DD}M$	IOV_{DD}	20	35	mA
	$V_{DD}L$	IDV_{DD}	130	185	mA
Standby current	$V_{DD}H$	IAV_{DD}_STB	—	0.6	mA
	$V_{DD}M$	IOV_{DD}_STB	—	0.5	mA
	$V_{DD}L$	IDV_{DD}_STB	—	20	mA

Operating current:
(Typical value condition) : Supply voltage: 3.30 V / 1.80 V / 1.20 V, Tj = 25 °C
(Maximum value condition) : Supply voltage: 3.45 V / 1.90 V / 1.30 V, Tj = 60 °C
Worst state of internal circuit operating current consumption.

Standby current:
(Maximum value condition) : Supply voltage: 3.45 V / 1.90 V / 1.30 V, Tj = 60 °C, INCK = 0 V,
The device in the light-obstructed state.

AC Characteristics

Master Clock (INCK) Waveform Diagram



Item	Symbol	Min.	Typ.	Max.	Unit	Remarks
INCK clock frequency	f_{INCK}	f_{INCK} × 0.96	f_{INCK}	f_{INCK} × 1.02	MHz	f_{INCK} = 37.125 MHz, 74.25 MHz, 54 MHz
INCK Low level pulse width	t_{WLINCK}	4	—	—	ns	
INCK High level pulse width	t_{WHINCK}	4	—	—	ns	
INCK clock duty	—	45.0	50.0	55.0	%	Define with 0.5 × OV_{DD}

* The INCK fluctuation affects the frame rate.

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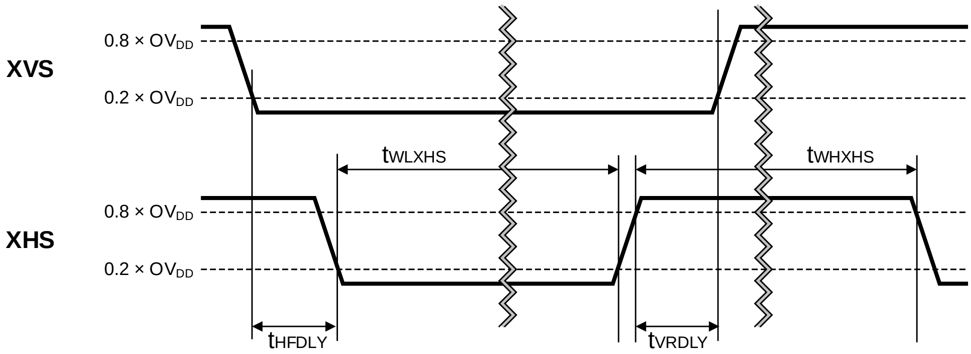
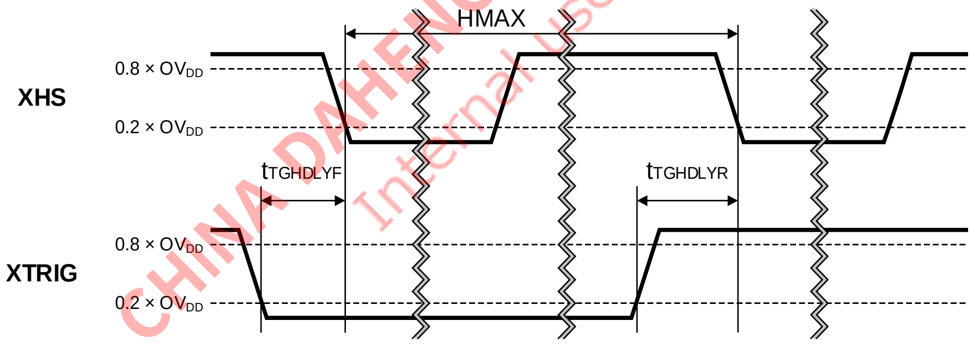
XVS / XHS Input Characteristics in Slave Mode (XMASTER = High)



Item	Symbol	Min.	Typ.	Max.	Unit
XHS Low level pulse width	t_{WLXHS}	$4/f_{INCK}$	—	—	ns
XHS High level pulse width	t_{WHXHS}	$4/f_{INCK}$	—	—	ns
XVS - XHS fall width	t_{HFDLY}	$1/f_{INCK}$	—	—	ns
XHS - XVS rise width	t_{VRDLY}	$1/f_{INCK}$	—	—	ns

Synchronization cannot be performed from XVS and XHS signal in mater mode. Detect the sync code.

XTRIG Input Characteristics in Slave Mode (XMASTER = High) only



Item	Symbol	Min.	Typ.	Max.	Unit
XTRIG fall - XHS fall width	$t_{TGHDLYF}$	10	—	HMAX-10	INCK
XTRIG rise - XHS fall width	$t_{TGHDLYR}$	10	—	HMAX-10	INCK

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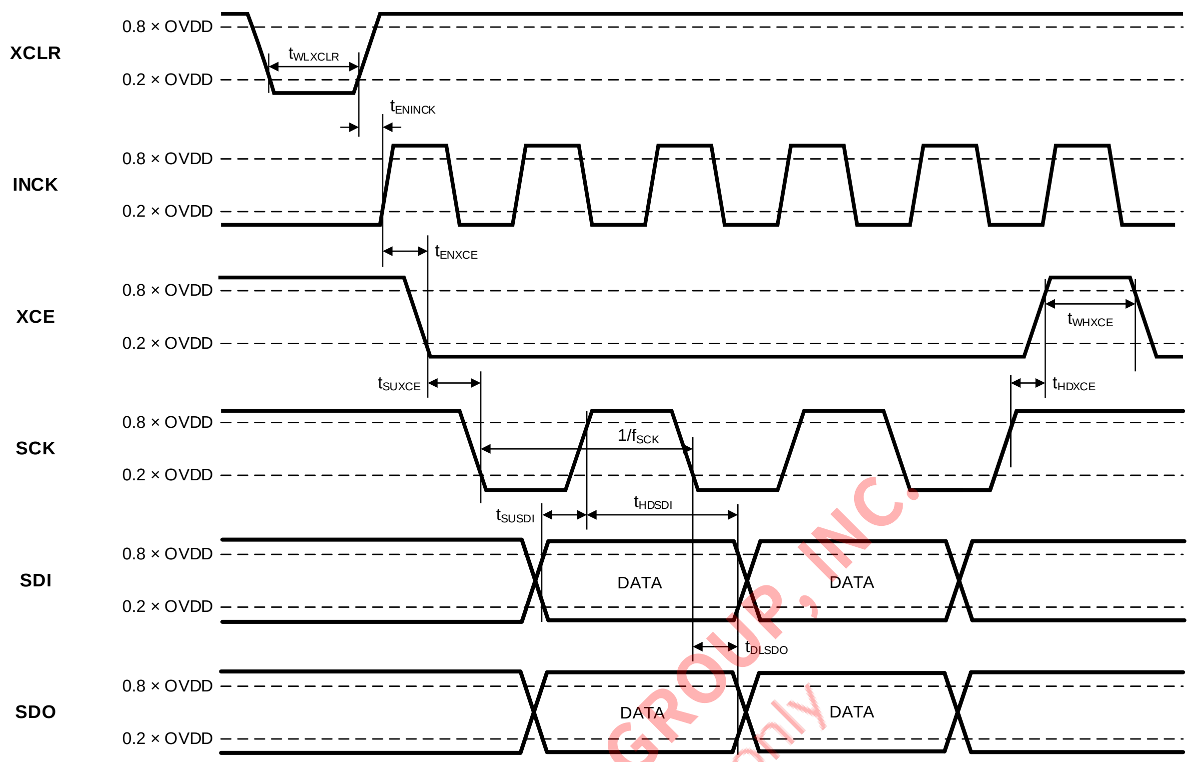
Serial Communication

4-wire



Item	Symbol	Min.	Typ.	Max.	Unit	Remarks
SCK clock frequency	f_{SCK}	—	—	13.5	MHz	
XCLR Low level pulse width	t_{WLXCLR}	$4/f_{INCK}$	—	—	ns	
INCK effective margin	t_{ENINCK}	1	—	—	µs	
XCE effective margin	t_{ENXCE}	20	—	—	µs	
XCE input setup time	t_{SUXCE}	20	—	—	ns	
XCE input hold time	t_{HDXCE}	20	—	—	ns	
XCE High level pulse width	t_{WHXCE}	20	—	—	ns	
SDI input setup time	t_{SUSDI}	10	—	—	ns	
SDI input hold time	t_{HDSDI}	10	—	—	ns	
SDO output delay time	t_{DLSDO}	0	—	25	ns	Output load capacitance: 20 pF

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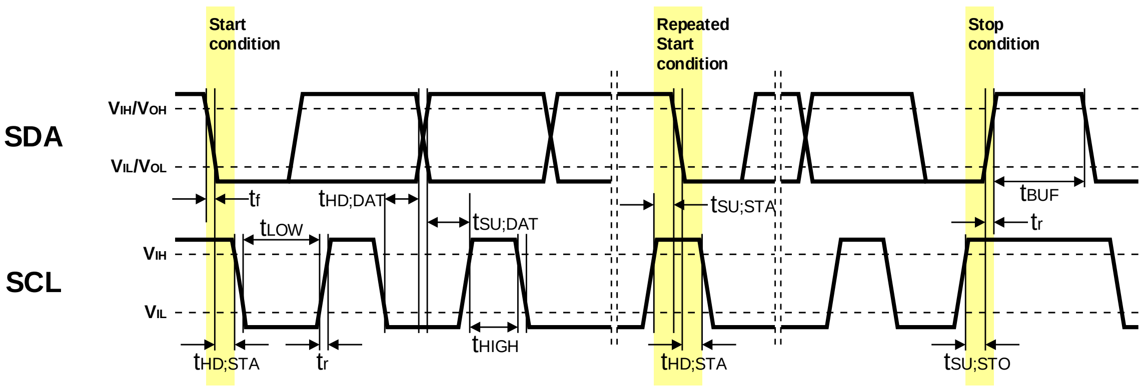

I²C Specification

Item	Symbol	Min.	Typ.	Max.	Unit	Remarks
Low level input voltage	V_{IL}	-0.3	—	0.3 × OV_{DD}	V	
High level input voltage	V_{IH}	0.7 × OV_{DD}	—	1.9	V	
Low level output voltage	V_{OL}	0	—	0.2 × OV_{DD}	V	OV_{DD} < 2 V, Sink 3 mA
High level output voltage	V_{OH}	0.8 × OV_{DD}	—	—	V	
Output fall time	tof	—	—	250	ns	Load 10 pF – 400 pF, 0.7 × OV_{DD} – 0.3 × OV_{DD}
Input current	Ii	-10	—	10	µA	0.1 × OV_{DD} – 0.9 × OV_{DD}
Capacitance for SCK (/SCL) , SDI (/SDA)	Ci	—	—	10	pF	

I²C AC Characteristics

Item	Symbol	Min.	Typ.	Max.	Unit
SCL clock frequency	f_{SCL}	0	—	400	kHz
Hold time (Start Condition)	t_{HDSTA}	0.6	—	—	µs
Low period of the SCL clock	t_{LOW}	1.3	—	—	µs
High period of the SCL clock	t_{HIGH}	0.6	—	—	µs
Set-up time (Repeated Start Condition)	t_{SUSTA}	0.6	—	—	µs
Data hold time	t_{HDDAT}	0	—	0.9	µs
Data set-up time	t_{SUDAT}	100	—	—	ns
Rise time of both SDA and SCL signals	t_R	—	—	300	ns
Fall time of both SDA and SCL signals	t_F	—	—	300	ns
Set-up time (Stop Condition)	t_{SUSTO}	0.6	—	—	µs
Bus free time between a Stop and Start Condition	t_{BUF}	1.3	—	—	µs

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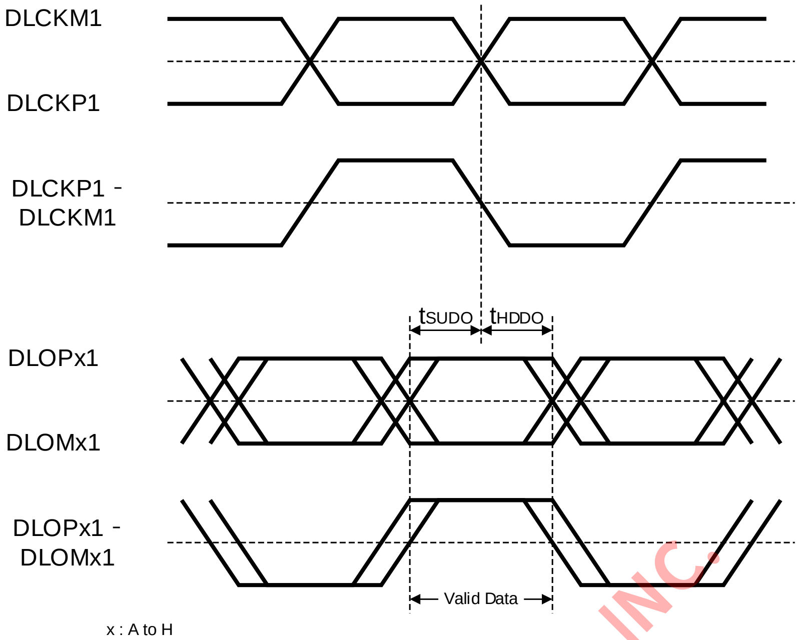
DLCKP1 / DLCKM1, DLOPx1 / DLOMx1



(Output load capacitance: 8 pF)

Item	Symbol	Min.	Typ.	Max.	Unit	Remarks
DLCK clock duty	—	40	50	60	%	DCK freq = 297 MHz (Max.)
DLO setup time	t_{SUDO}	400	—	—	ps	Data Rate 297 MHz DDR
DLO hold time	t_{HDDO}	400	—	—	ps	Data Rate 297 MHz DDR

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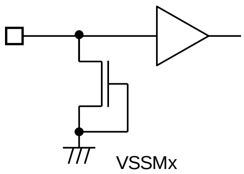
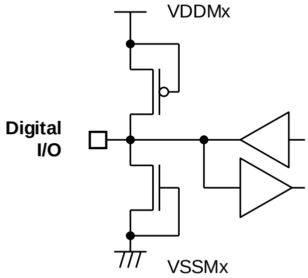
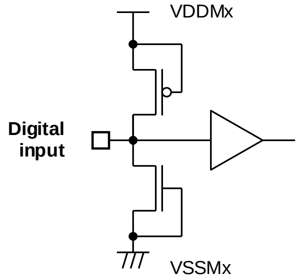
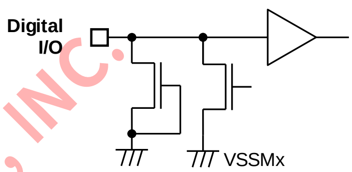
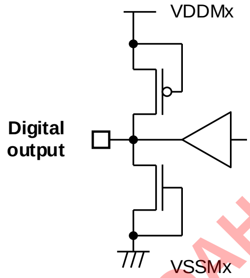
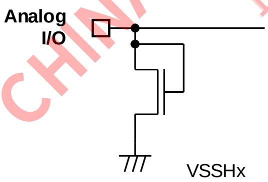
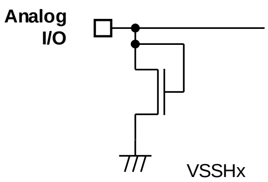
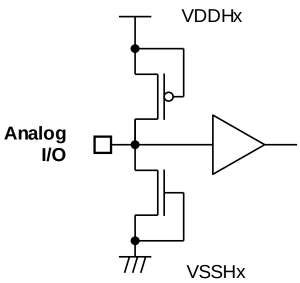
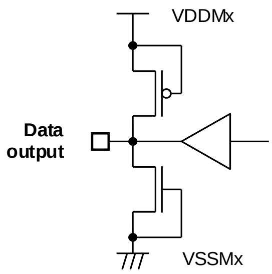
I/O Equivalent Circuit Diagram

□ : External pin

<table>
<tr><th>Symbol</th><th>Equivalent circuit</th><th>Symbol</th><th>Equivalent circuit</th></tr>
<tr><td>INCK</td><td></td><td>XVS
XHS</td><td></td></tr>
<tr><td>XCLR
XCE
XMASTER
XTRIG
SLAMODE</td><td></td><td>SDI / SDA
SCK / SCL</td><td></td></tr>
<tr><td>SDO</td><td></td><td></td><td></td></tr>
<tr><td>VCP1
VCP2</td><td></td><td>VRLOFG
VRLTRX
VRLSEL
VRLTRG</td><td></td></tr>
<tr><td>VBGR</td><td></td><td>DLOPx1
DLOMx1
DCKP1
DCKM1
x : A to H</td><td></td></tr>
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Spectral Sensitivity Characteristics

(Excludes lens characteristics and light source characteristics.)

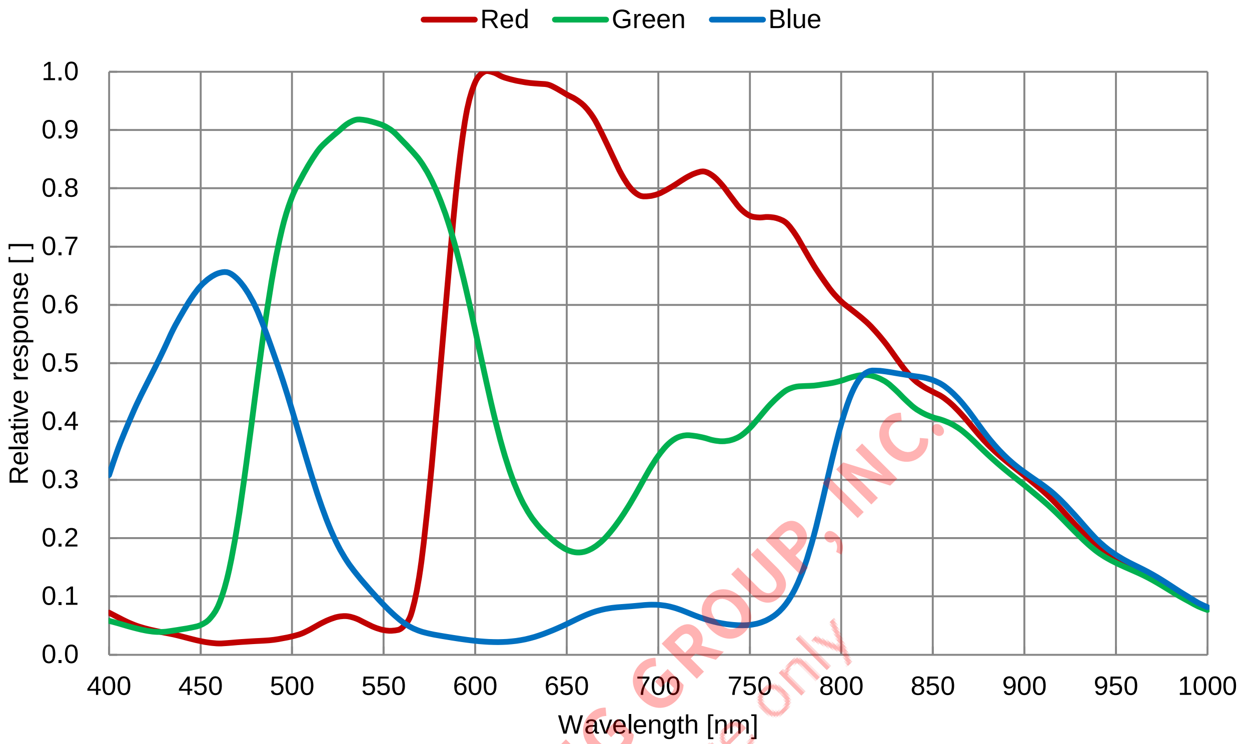

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Image Sensor Characteristics

(AV_{DD} = 3.3 V, OV_{DD} = 1.8 V, DV_{DD} = 1.2 V, All-pixel scan mode, AD: 12 bit, Tj = 60 ˚C, Gain = 0 dB)

Item		Symbol	Min.	Typ.	Max.	Unit	Measurement method	Remarks
Sensitivity		S	3967 (970)	4687 (1146)	—	Digit (mV)	1	1/30 s storage
Sensitivity ratio	R/G	RG	0.47	—	0.62	—	2	
	B/G	BG	0.29	—	0.44	—		
Saturation signal		Vsat2D	4094 (1001*1)	—	—	Digit (mV)	3	Zone 0 to II'
Video signal shading		SH01	—	—	20	%	4	Zone 0, I
		SH2D	—	—	25	%		Zone 0 to II'
Dark signal		Vdt	—	—	0.78 (0.19)	Digit (mV)	5	1/30 s storage
Dark signal shading		ΔVdt	—	—	1.02 (0.25)	Digit (mV)	6	1/30 s storage
PLS (Parasitic Light Sensitivity)		Sm	—	—	-93.9	dB	7	Zone II'

Note) 1. Converted value into mV using 1Digit = 0.2445 mV for 12-bit output, 1Digit = 0.9779 mV for 10-bit output and 1Digit = 0.9779 mV for 8-bit output.
2. The video signal shading is the measured value in the wafer status and does not include characteristics of the seal glass.

*1 In case of 8 bit, Vsat2D becomes 1/4 of it at 12 bit.

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Zone Definition of Video Signal Shading

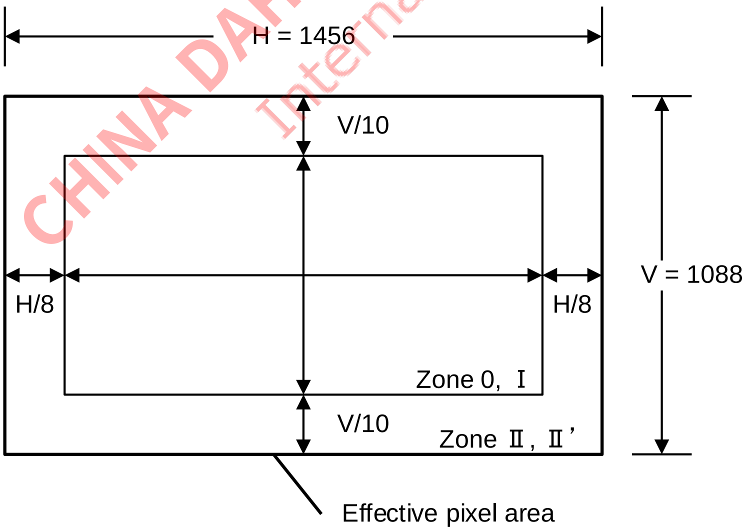

Image Sensor Characteristics Measurement Method

Measurement Conditions

In the following measurements, the device drive conditions are at the typical values of the bias conditions and clock voltage conditions.
In the following measurements, spot pixels are excluded and, unless otherwise specified, the optical black (OB) level is used as the reference for the signal output, which is taken as the value of the signal output of the measurement system.

Color Coding of Physical Pixel Array

The primary color filters of this image sensor are arranged in the layout shown in the figure below. Gr and Gb represent the G signal on the same line as the R and B signals, respectively. The Gb signal and B signal lines and the R signal and Gr signal lines are output successively.

Gb	B	Gb	B
R	Gr	R	Gr
Gb	B	Gb	B
R	Gr	R	Gr

Color Coding Diagram

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Definition of standard imaging conditions

- ◆ Standard imaging condition I:
  Use a pattern box (luminance: 706 cd/m^2, color temperature of 3200 K halogen source) as a subject. (Pattern for evaluation is not applicable.) Use a testing standard lens with CM500S (t = 1.0 mm) as an IR cut filter and image at F5.6. The luminous intensity to the sensor receiving surface at this point is defined as the standard sensitivity testing luminous intensity.

- ◆ Standard image condition II:
  Image a light source (color temperature of 3200 K) with a uniformity of brightness within 2 % at all angles. Use a testing standard lens with CM500S (t = 1.0 mm) as an IR cut filter. The luminous intensity is adjusted to the value indicated in each testing item by the lens diaphragm.

- ◆ Standard image condition III:
  Image a light source (color temperature of 3200 K) with a uniformity of brightness within 2 % at all angles. Use a testing standard lens (exit pupil distance -100 mm) with CM500S (t = 1.0 mm) as an IR cut filter. The luminous intensity is adjusted to the value indicated in each testing item by the lens diaphragm.

Measurement Method

1. Sensitivity
   Set the measurement condition to the standard imaging condition I. After setting the electronic shutter mode with a shutter speed of 1/100 s, measure the Gr and Gb signal outputs (VGr, VGb) at the center of the screen, and substitute the values into the following formula.

   S = (VGr + VGb) / 2 × 100 / 30 [mV]

2. Sensitivity ratio
   Set the measurement condition to the standard imaging condition II. After adjusting the average value of the Gr and Gb signal outputs to 580 mV, measure the R signal output (VR [mV]), the Gr and Gb signal outputs (VGr, VGb [mV]) and the B signal output (VB [mV]) at the center of the screen in frame readout mode, and substitute the values into the following formulas.

   VG = (VGr + VGb) / 2
   RG = VR / VG
   BG = VB / VG

3. Saturation signal
   Set the measurement condition to the standard imaging condition II. After adjusting the luminous intensity to 20 times the intensity with the average value of the Gr and Gb signal outputs, 580 mV, measure the minimum values of the Gr, Gb, R and B signal outputs.

4. Video signal shading
   Set the measurement condition to the standard imaging condition III. With the lens diaphragm at F2.8, adjust the luminous intensity so that the average value of the Gr and Gb signal outputs are 580 mV. Then measure the maximum value (Gmax [mV]) and the minimum value (Gmin [mV]) of the Gr and Gb signal outputs, and substitute the values into the following formula.

   SH = (Gmax – Gmin) / 580 × 100 [%]

5. Dark signal
   With the device junction temperature of 60 ˚C and the device in the light-obstructed state, divide the output difference between 1/3 s integration at 3 frame/s and 1/30 s integration at 30 frame/s by 9, and calculate the signal output converted to 1/30 s integration. Measure the average value of this output (Vdt [mV]).

6. Dark signal shading
   Measure the maximum value (Vdmax [mV]) and the minimum value (Vdmin [mV]) of the dark signal output with the device junction temperature of 60 ˚C and the device in the light-obstructed state and 1/30 s integration. The measuring values substitute into the following formula.

   ΔVdt = Vdmax – Vdmin [mV]

7. PLS
   Set the measurement condition to the standard imaging condition II, the Gr and Gb output signal Vave measured by standard image condition. Then, adjust the luminous intensity to 500 times the intensity with average value of the Gr and Gb signal output, Vave. When the charge drain is executed be the electronic shutter and the condition that not be readout from photo diode to analog memory, readout by dropping to 1/113 frame rate.

   Sm = 20 × log ((Vsm/Vave) × (1/500) × (1/113)) [dB]

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Setting Registers Using Serial Communication

Description of Setting Registers (4-wire)

The serial data input order is LSB-first transfer. The table below shows the various data types and descriptions.

Serial Data Transfer Order

Chip ID	Start address	Data	Data	Data	…
(8 bit)	(8 bit)	(8 bit)	(8 bit)	(8 bit)	(8 bit)

Type and Description

Type	Description
Chip ID	Chip ID: 02 Write: 02h / Read: 82h
	Chip ID: 03 Write: 03h / Read: 83h
	Chip ID: 04 Write: 04h / Read: 84h
	Chip ID: 05 Write: 05h / Read: 85h
	Chip ID: 06 Write: 06h / Read: 86h
	Chip ID: 07 Write: 07h / Read: 87h
	Chip ID: 08 Write: 08h / Read: 88h
	Chip ID: 09 Write: 09h / Read: 89h
	Chip ID: 0A Write: 0Ah / Read: 8Ah
	Chip ID: 0B Write: 0Bh / Read: 8Bh
	Chip ID: 0C Write: 0Ch / Read: 8Ch
	Chip ID: 0D Write: 0Dh / Read: 8Dh
	Chip ID: 0E Write: 0Eh / Read: 8Eh
	Chip ID: 0F Write: 0Fh / Read: 8Fh
	Chip ID: 10 Write: 10h / Read: 90h
	Chip ID: 11 Write: 11h / Read: 91h
	Chip ID: 12 Write: 12h / Read: 92h
Address	Designate the address according to the Register Map. When using a communication method that designates continuous addresses, the address is automatically incremented from the previously transmitted address.
Data	Input the setting values according to the Register Map.

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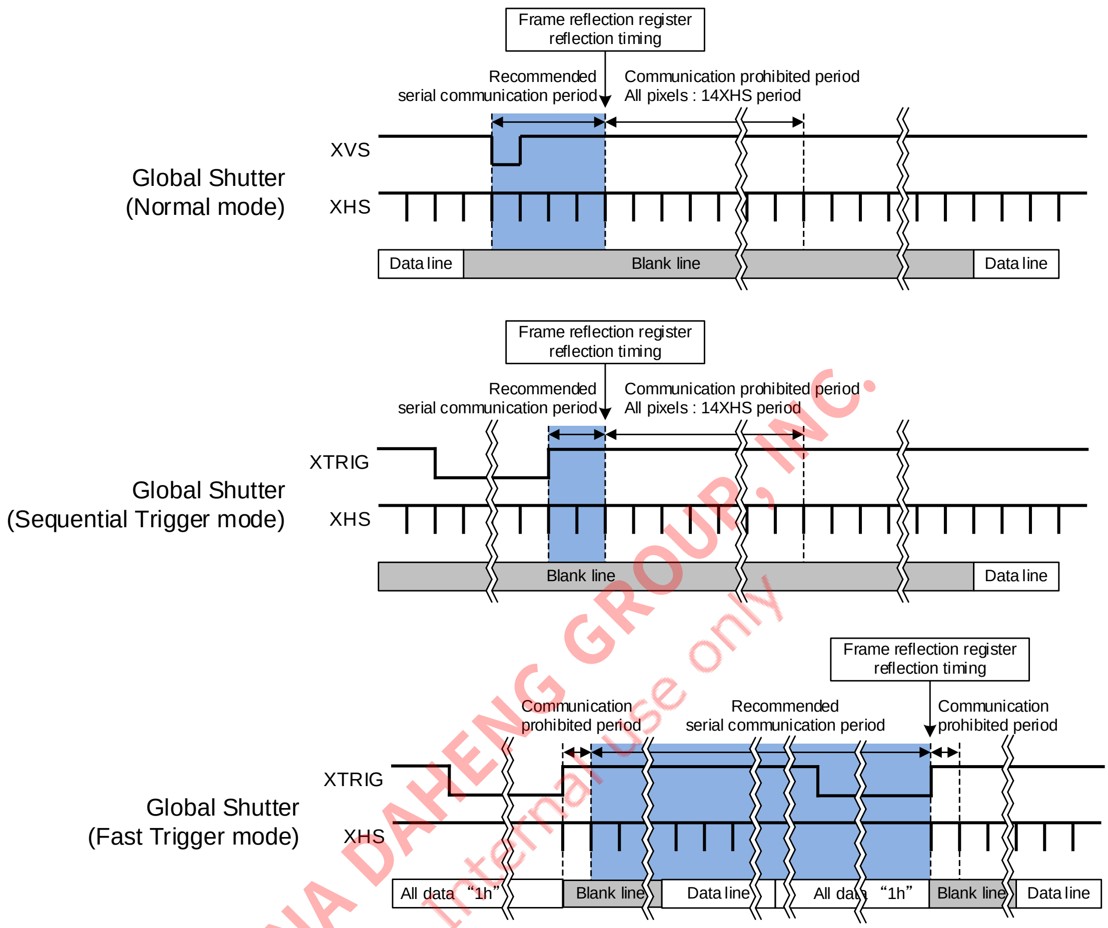
Register Communication Timing (4-wire)

Perform serial communication in sensor standby mode or within communication period. For the registers marked "V" in the item of Reflection timing, when the communication is performed in the communication period shown in the figure below they are reflected by frame reflection timing. For the registers noted “Immediately” in the item of Reflection timing, the settings are reflected when the communication is performed.



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Register Write and Read (4-wire)

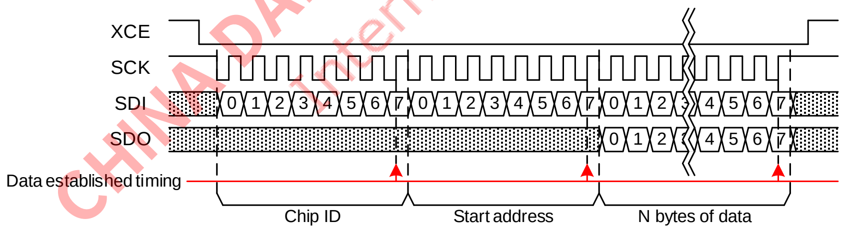
◆ Follow the communication procedure below when writing registers.

(1) Set XCE Low to enable the chip's communication function. Serial data input is executed using SCK and SDI.
(2) Transmit data in sync with SCK 1 bit at a time from the LSB using SDI. Transfer SDI in sync with the falling edge of SCK. (The data is loaded at the rising edge of SCK.)
(3) Input the Chip ID (CID = 02h to 12h) to the first byte. If the Chip ID differs, subsequent data is ignored.
(4) Input the start address to the second byte. The address is automatically incremented.
(5) Input the data to the third and subsequent bytes. The data in the third byte is written to the register address designated by the second byte, and the register address is automatically incremented thereafter when writing the data for the fourth and subsequent bytes. Normal register data is loaded to the inside of the sensor and established in 8-bit units.
(6) The register values starting from the register address designated by the second byte are output from the SDO pin. The register values before the write operation are output. The actual register values are the input data.
(7) Set XCE High to end communication.

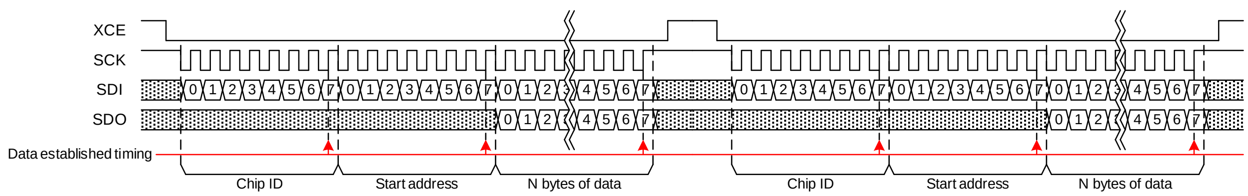
◆ Follow the communication procedure below when reading registers.

(1) Set XCE Low to enable the chip's communication function. Serial data input is executed using SCK and SDI.
(2) Transmit data in sync with SCK 1 bit at a time from the LSB using SDI. Transfer SDI in sync with the falling edge of SCK. (The data is loaded at the rising edge of SCK.)
(3) Input Chip ID (CID = 82h to 92h) to the first byte. If the Chip ID differs, subsequent data is ignored.
(4) Input the start address to the second byte. The address is automatically incremented.
(5) Input data to the third and subsequent bytes. Input dummy data in order to read the registers. The dummy data is not written to the registers. To read continuous data, input the necessary number of bytes of dummy data.
(6) The register values starting from the register address designated by the second byte are output from the SDO pin. The input data is not written, so the actual register values are output.
(7) Set XCE High to end communication.

Note) When writing data to multiple registers with discontinuous addresses, access to undesired registers can be avoided by repeating the above procedure multiple times.



Serial Communication (Continuous Addresses)



Serial Communication (Discontinuous Addresses)

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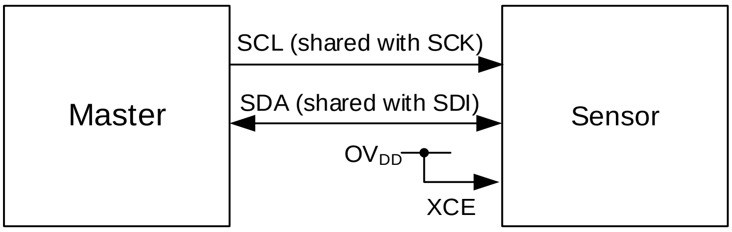
Description of Setting Registers (I^2C)

The serial data input order is MSB-first transfer. The table below shows the various data types and descriptions.



Pin connection of serial communication

The sensor can use two kinds of slave addresses by switching the polarity of SLAMODE Pin for one I^2C bus, and can use a common slave address in both polarities of SLAMODE Pin for one I^2C bus.

SLAVE Address (SLAMODE = 0)

MSB							LSB
0	1	1	0	1	1	0	R / W

SLAVE Address (SLAMODE = 1)

MSB							LSB
0	1	1	0	1	1	1	R / W

SLAVE Address (SLAMODE = 0 / 1 common)

MSB							LSB
0	0	1	1	0	1	0	R / W

* R/W is data direction bit

R/W

R / W bit	Data direction
0	Write (Master → Sensor)
1	Read (Sensor → Master)

I^2C pin description

Symbol	Pin No.	Description
SCL (common to SCK)	J3	Serial clock input
SDA (common to SDI)	K3	Serial data communication

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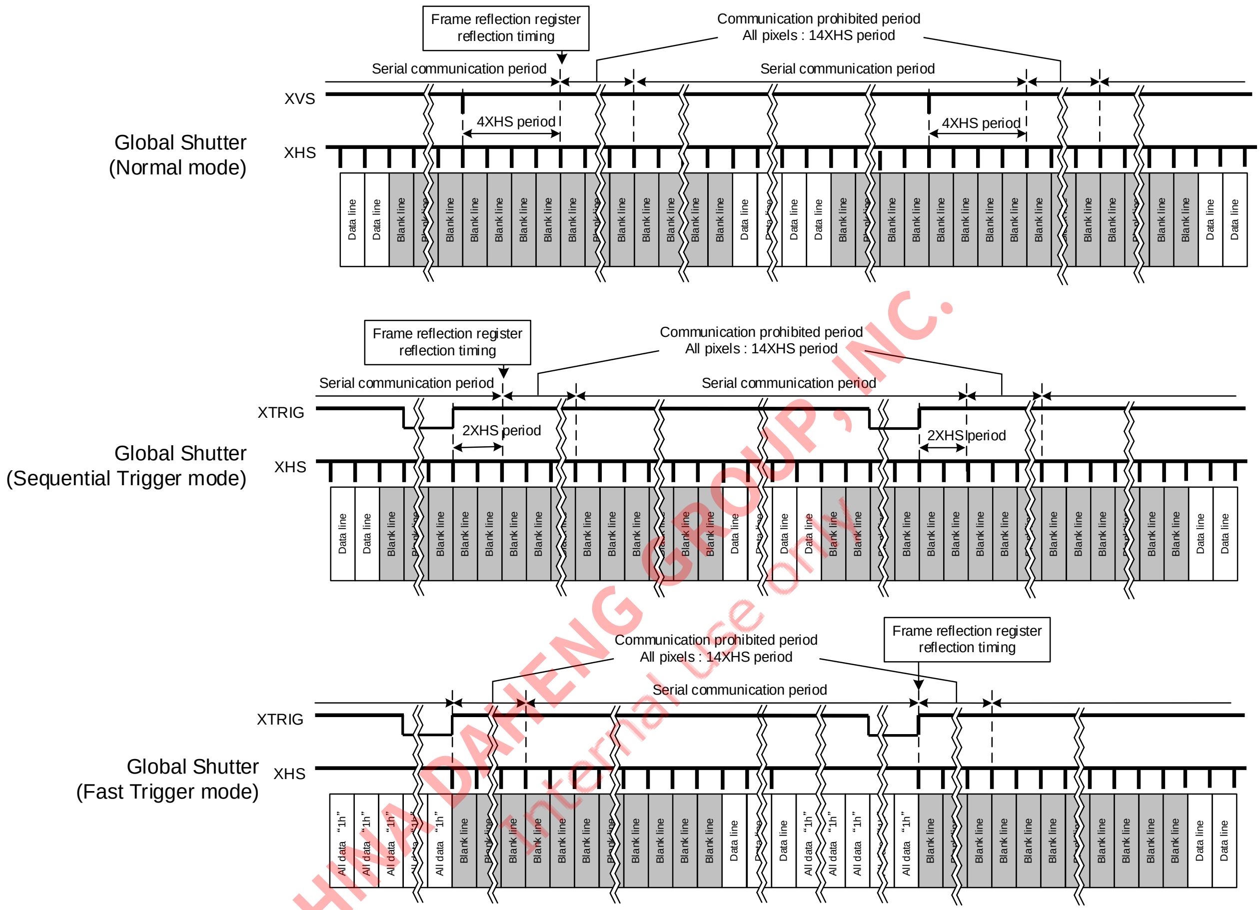
Register Communication Timing (I²C)

In I²C communication system, communication can be performed excluding the prohibited period as described in the below figure.
For the registers marked "V" in the item of Reflection timing, when the communication is performed in the communication period shown in the figure below they are reflected by frame reflection timing. For the registers noted “Immediately” in the item of Reflection timing, the settings are reflected when the communication is performed. Using REG_HOLD function is recommended for register setting using I²C communication. For REG_HOLD function, see “Register Transmission Setting” in “Description of Functions”.



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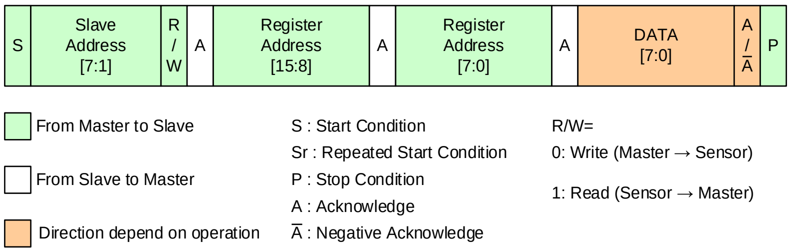
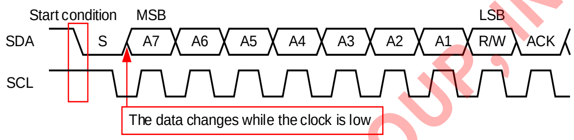
I²C Communication Protocol

I²C serial communication supports a 16-bit register address and 8-bit data message type.

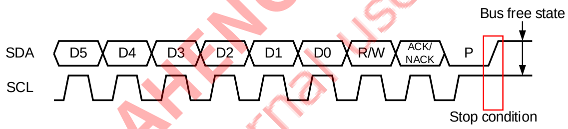


Communication protocol

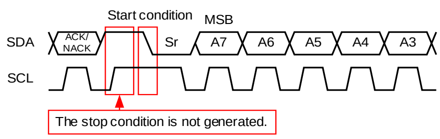
Data is transferred serially, MSB first in 8-bit units. After each data byte is transferred, A (Acknowledge) / Ā (Negative Acknowledge) is transferred. Data (SDA) is transferred at the clock (SDL) cycle. SDA can change only while SCL is Low, so the SDA value must be held while SCL is High. The Start Condition is defined by SDA changing from High to Low while SCL is High. When the Stop Condition is not generated in the previous communication phase and Start Condition for the next communication is generated, that Start Condition is recognized as a Repeated Start Condition.



Start Condition

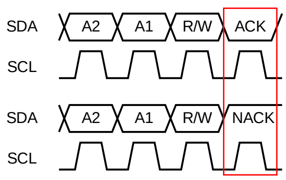


Stop Condition



Repeated Start Condition

After transfer of each data byte, the Master or the sensor transmits an Acknowledge / Negative Acknowledge and release (does not drive) SDA. When Negative Acknowledge is generated, the Master must immediately generate the Stop Condition and end the communication.



Acknowledge and Negative Acknowledge

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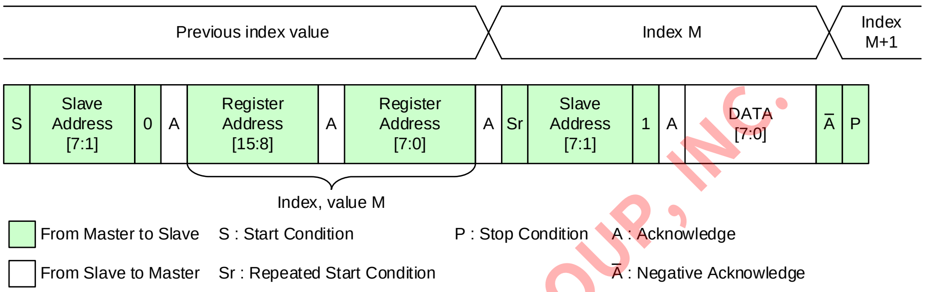
I²C Serial Communication Read/Write Operation

This sensor supports the following four read operations and two write operations.

Single Read from Random Location

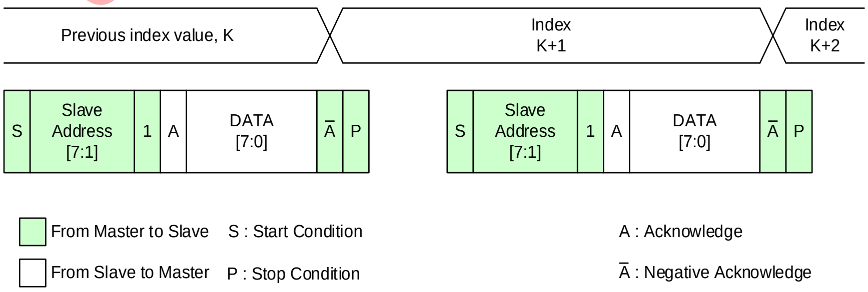
The sensor has an index function that indicates which address it is focusing on. In reading the data at an optional single address, the Master must set the index value to the address to be read. For this purpose it performs dummy write operation up to the register address. The upper level of the figure below shows the sensor internal index value, and the lower level of the figure shows the SDA I/O data flow. The Master sets the sensor index value to M by designating the sensor slave address with a write request, then designating the address (M). Then, the Master generates the Start Condition. The Start Condition is generated without generating the Stop Condition, so it becomes the Repeated Start Condition. Next, when the Master sends the slave address with a read request, the sensor outputs an Acknowledge immediately followed by the index address data on SDA. After the Master receives the data, it generates a Negative Acknowledge and the Stop Condition to end the communication.



Single Read from Random Location

Single Read from Current Location

After the slave address is transmitted by a write request, that address is designated by the next communication and the index holds that value. In addition, when data read/write is performed, the index is incremented by the subsequent Acknowledge/Negative Acknowledge timing. When the index value is known to indicate the address to be read, sending the slave address with a read request allows the data to be read immediately after Acknowledge. After receiving the data, the Master generates a Negative Acknowledge and the Stop Condition to end the communication, but the index value is incremented, so the data at the next address can be read by sending the slave address with a read request.



Single Read from Current Location

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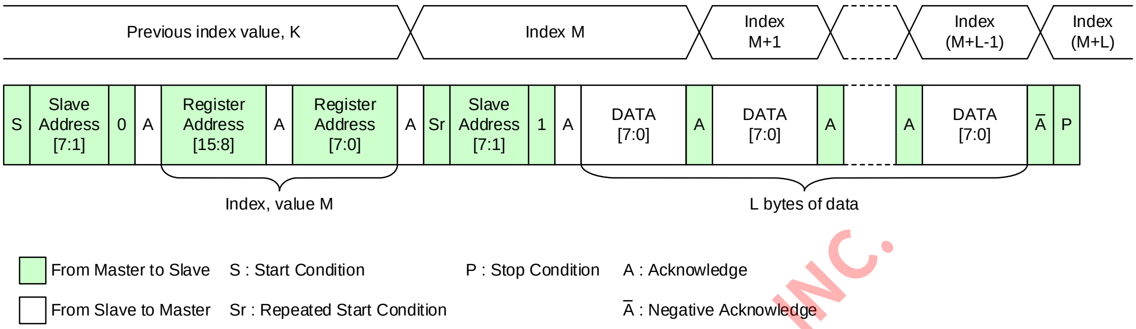
Sequential Read Starting from Random Location

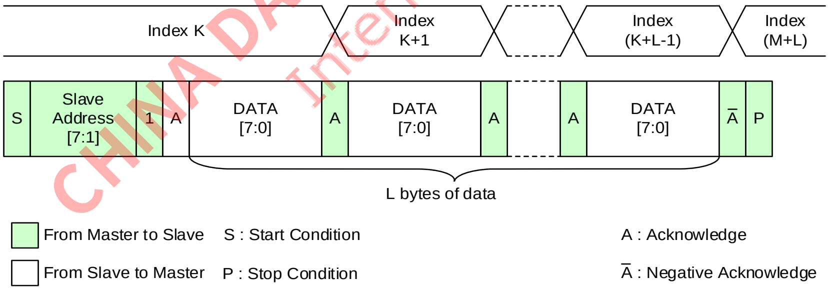
In reading data sequentially, which is starting from an optional address, the Master must set the index value to the start of the addresses to be read. For this purpose, dummy write operation includes the register address setting. The Master sets the sensor index value to M by designating the sensor slave address with a read request, then designating the address (M). Then, the Master generates the Repeated Start Condition. Next, when the Master sends the slave address with a read request, the sensor outputs an Acknowledge followed immediately by the index address data on SDA. When the Master outputs an Acknowledge after it receives the data, the index value inside the sensor is incremented and the data at the next address is output on SDA. This allows the Master to read data sequentially. After reading the necessary data, the Master generates a Negative Acknowledge and the Stop Condition to end the communication.



Sequential Read Starting from Random Location

Sequential Read Starting from Current Location

When the index value is known to indicate the address to be read, sending the slave address with a read request allows the data to be read immediately after the Acknowledge. When the Master outputs an Acknowledge after it receives the data, the index value inside the sensor is incremented and the data at the next address is output on SDA. This allows the Master to read data sequentially. After reading the necessary data, the Master generates a Negative Acknowledge and the Stop Condition to end the communication.



Sequential Read Starting from Current Location

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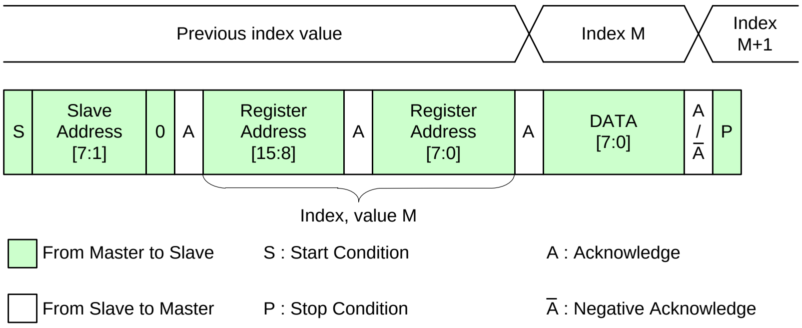
Single Write to Random Location

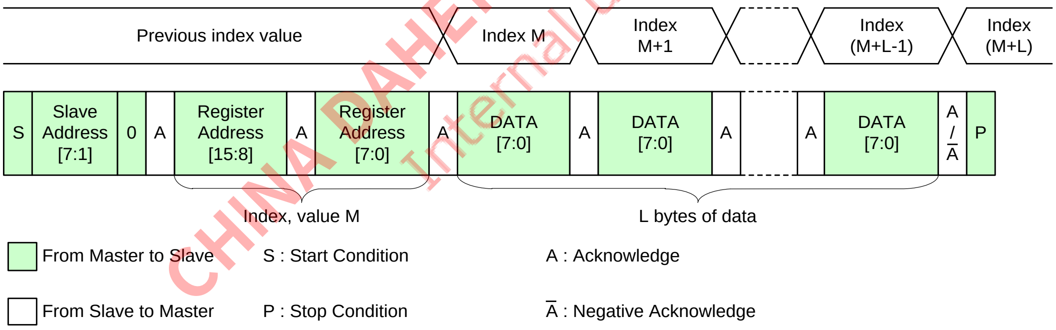
The Master sets the sensor index value to M by designating the sensor slave address with a write request, and designating the address (M). After that the Master can write the value in the designated register by transmitting the data to be written. After writing the necessary data, the Master generates the Stop Condition to end the communication.



Single Write to Random Location

Sequential Write Starting from Random Location

The Master can write a value to register address M by designating the sensor slave address with a write request, designating the address (M), and then transmitting the data to be written. After the sensor receives the write data, it outputs an Acknowledge and at the same time increments the register address, so the Master can write to the next address simply by continuing to transmit data. After the Master writes the necessary number of bytes, it generates the Stop Condition to end the communication.



Sequential Write Starting from Random Location

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Register Map

This sensor has a total of 4352 bytes of registers, composed of registers with address 00h to FFh that correspond to Chip ID = 02h to 12h. Use the initial values for empty address. Some registers must be change from the initial values, so the sensor control side should be capable of setting 4352 bytes.

There are three different register reflection timings.
About the Reflection timing column of the Register Map, registers noted as "I" are reflected immediately after writing to register, registers noted as "S" are set during standby mode and reflected after standby canceled, registers noted as "V" are reflected at “Fame reflection register reflection timing” on the figure described in the section of “Setting Registers with Serial Communication”.

Do not perform communication to addresses not listed in the Register Map. Doing so may result in operation errors.

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Chip ID = 02 (Write: Chip ID = 02h, Read: Chip ID = 82h, I²C: 30**h)

Please refer to the other register map file for the register that has not been described.

Address 4-wire	Address I²C	bit	Register Name	Description	Default value after reset By register	Default value after reset By address	Reflection timing
00h	3000h	0	STANDBY [0]	Standby mode 0: Normal operation 1: Standby	1	01h	I
		1		Fixed to 0	0		—
		2		Fixed to 0	0		—
		3		Fixed to 0	0		—
		4		Fixed to 0	0		—
		5		Fixed to 0	0		—
		6		Fixed to 0	0		—
		7		Fixed to 0	0		—
05h	3005h	0		Fixed to 1	1	01h	—
		1		Fixed to 0	0		—
		2		Fixed to 0	0		—
		3		Fixed to 0	0		—
		4	STBLVDS	LVDS channels that not using be standby 0h: 8 ch active 2h: 4 ch active 3h: 2 ch active Others: Setting prohibited	0h		S
		5					
		6					
		7					
08h	3008h	0	REGHOLD [0]	Register hold (Function not to update V reflection registers) 0: Invalid 1: Valid	0	00h	I
		1		Fixed to 0	0		—
		2		Fixed to 0	0		—
		3		Fixed to 0	0		—
		4		Fixed to 0	0		—
		5		Fixed to 0	0		—
		6		Fixed to 0	0		—
		7		Fixed to 0	0		—
0Ah	300Ah	0	XMSTA [0]	Setting of master mode operation 0: Master mode operation start 1: Master mode operation stop	1	01h	I
		1		Fixed to 0	0		—
		2		Fixed to 0	0		—
		3		Fixed to 0	0		—
		4		Fixed to 0	0		—
		5		Fixed to 0	0		—
		6		Fixed to 0	0		—
		7		Fixed to 0	0		—
0Bh	300Bh	0	TRIGEN [0]	Global shutter mode setting 0: Normal mode 1: Trigger mode	0	00h	I*1
		1		Fixed to 0	0		—
		2		Fixed to 0	0		—
		3		Fixed to 0	0		—
		4		Fixed to 0	0		—
		5		Fixed to 0	0		—
		6		Fixed to 0	0		—
		7		Fixed to 0	0		—

*1 Refer to “Mode Transitions of Global Shutter Operation”

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Address 4-wire	Address I²C	bit	Register Name	Description	Default value after reset: By register	Default value after reset: By address	Reflection timing
0Ch	300Ch	0	ADBIT [1:0]	AD conversion bits setting 0h: 10 bit 1h: 12 bit 2h: 8 bit 3h: Setting prohibited	0h	00h	S
		1					
		2		Fixed to 0	0		—
		3		Fixed to 0	0		—
		4		Fixed to 0	0		—
		5		Fixed to 0	0		—
		6		Fixed to 0	0		—
		7		Fixed to 0	0		—
0Dh	300Dh	0	WINMODE [3:0]	Drive mode setting of V direction 0h: All-pixel mode. 1h: 1/2 Subsampling mode Others: Setting prohibited	0	00h	S
		1			0		
		2			0		
		3			0		
		4	HMODE [0]	Drive mode setting of H direction 0: All-pixel 1: 1/2 Subsampling mode	0		S
		5		Fixed to 0	0		—
		6		Fixed to 0	0		—
		7		Fixed to 0	0		—
0Eh	300Eh	0	VREVERSE [0]	Vertical (V) direction readout inversion control 0: Normal 1: Inverted	0	00h	V
		1	HREVERSE [0]	Horizontal (H) direction readout inversion control 0: Normal 1: Inverted	0		V
		2		Fixed to 0	0		—
		3		Fixed to 0	0		—
		4		Fixed to 0	0		—
		5		Fixed to 0	0		—
		6		Fixed to 0	0		—
		7		Fixed to 0	0		—
10h	3010h	0	VMAX [19:0]	LSB When sensor master mode vertical span setting. (Number of operation lines count from 1) MSB	0046Ah	6Ah	V
		1					
		2					
		3					
		4					
		5					
		6					
		7					
11h	3011h	0				04h	
		1					
		2					
		3					
		4					
		5					
		6					
		7					
12h	3012h	0				00h	
		1					
		2					
		3					
		4		Fixed to 0	0		—
		5		Fixed to 0	0		—
		6		Fixed to 0	0		—
		7		Fixed to 0	0		—

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Address		bit	Register Name	Description	Default value after reset		Reflection timing
4-wire	I^2C				By register	By address	
14h	3014h	0	HMAX [15:0]	LSB	0122h	22h	S
		1					
		2					
		3					
		4					
		5					
		6					
		7		When sensor master mode horizontal span setting. (Number of operation clocks count from 1)			
15h	3015h	0				01h	
		1					
		2					
		3					
		4					
		5					
		6					
		7		MSB			
16h	3016h	0	ODBIT [1:0]	Number of output bit setting 0h: 10 bit 1h: 12 bit 2h: 8 bit 3h: Setting prohibited	0h	00h	S
		1					
		2		Fixed to 0	0		—
		3		Fixed to 0	0		—
		4		Fixed to 0	0		—
		5		Fixed to 0	0		—
		6		Fixed to 0	0		—
		7		Fixed to 0	0		—
1Bh	301Bh	0	FREQ [1:0]	Set to data rate. 0h: Normal 1h: Data rate 1/2	0h	00h	S
		1					
		2		Fixed to 0	0		—
		3		Fixed to 0	0		—
		4		Fixed to 0	0		—
		5		Fixed to 0	0		—
		6		Fixed to 0	0		—
		7		Fixed to 0	0		—
1Ch	301Ch	0		Fixed to 0	0	10h	—
		1		Fixed to 0	0		—
		2		Fixed to 0	0		—
		3		Fixed to 0	0		—
		4	OPORTSEL [3:0]	Output channel selection 1h: 8 ch 3h: 4 ch 4h: 2 ch Others: Setting prohibited	1h		S
		5					
		6					
		7					
26h	3026h	0	TOUT1SEL [1:0]	TOUT1 pin setting 0h: Low fixed 3h: Pulse output	0h	00h	S
		1					
		2	TOUT2SEL [1:0]	TOUT2 pin setting 0h: Low fixed 3h: Pulse output	0h		S
		3					
		4		Fixed to 0	0		—
		5		Fixed to 0	0		—
		6		Fixed to 0	0		—
		7		Fixed to 0	0		—

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Address 4-wire	Address I²C	bit	Register Name	Description	Default value after reset By register	Default value after reset By address	Reflection timing
29h	3029h	0	TRIG_TOUT1_SEL [2:0]	TOUT1 pin setting 0h: Low fixed 1h: Pulse1 output	0h	00h	S
		1					
		2					
		3		Fixed to 0	0		—
		4	TRIG_TOUT2_SEL [2:0]	TOUT2 pin setting 0h: Low fixed 2h: Pulse2 output	0h		S
		5					
		6					
		7		Fixed to 0	0		—
36h	3036h	0		Fixed to 0	0	C0h	—
		1		Fixed to 0	0		—
		2		Fixed to 0	0		—
		3		Fixed to 0	0		—
		4	SYNCSEL	XHS, XVS pin setting 0h: Normal Output 3h: Hi-Z	0h		S
		5					
		6		Fixed to 1	1		—
		7		Fixed to 1	1		—
6Dh	306Dh	0	PULSE1_EN_NOR [0]	Pulse1 output in normal mode 0: Disable 1: Enable	0	00h	S
		1	PULSE1_EN_TRIG [0]	Pulse1 output in trigger mode 0: Disable 1: Enable	0		S
		2	PULSE1_POL	Pulse1 polarity selection 0: High active 1: Low active	0		S
		3		Fixed to 0	0		—
		4		Fixed to 0	0		—
		5		Fixed to 0	0		—
		6		Fixed to 0	0		—
		7		Fixed to 0	0		—
70h	3070h	0	PULSE1_UP [19:0]	LSB Pulse1 active period start timing setting Designated in line units from reference point (For details, see the "Pulse Output Function") MSB	00000h	00h	S
		1					
		2					
		3					
		4					
		5					
		6					
		7					
71h	3071h	0				00h	
		1					
		2					
		3					
		4					
		5					
		6					
		7					
72h	3072h	0				00h	
		1					
		2					
		3					
		4		Fixed to 0	0		—
		5		Fixed to 0	0		—
		6		Fixed to 0	0		—
		7		Fixed to 0	0		—

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Address 4-wire	Address I²C	bit	Register Name	Description	Default value after reset By register	Default value after reset By address	Reflection timing
74h	3074h	0		LSB		00h	
		1					
		2					
		3					
		4					
		5					
		6					
		7					
75h	3075h	0				00h	
		1	PULSE1_DN [19:0]	Pulse1 active period end timing setting Designated in line units from readout start (For details, see the "Pulse Output Function")	00000h		S
		2					
		3					
		4					
		5					
		6					
		7					
76h	3076h	0				00h	
		1					
		2					
		3		MSB			
		4		Fixed to 0	0		—
		5		Fixed to 0	0		—
		6		Fixed to 0	0		—
		7		Fixed to 0	0		—
79h	3079h	0	PULSE2_EN_NOR [0]	Pulse2 output in normal mode 0: Disable 1: Enable	0	00h	S
		1	PULSE2_EN_TRIG [0]	Pulse2 output in trigger mode 0: Disable 1: Enable	0		S
		2	PULSE2_POL [0]	Pulse2 polarity selection 0: High active 1: Low active	0		S
		3		Fixed to 1	0		S
		4		Fixed to 0	0		—
		5		Fixed to 0	0		—
		6		Fixed to 0	0		—
		7		Fixed to 0	0		—
7Ch	307Ch	0		LSB		00h	
		1					
		2					
		3					
		4					
		5					
		6					
		7					
7Dh	307Dh	0				00h	
		1	PULSE2_UP [19:0]	Pulse2 active period start timing setting Designated in line units from reference point (For details, see the "Pulse Output Function")	00000h		S
		2					
		3					
		4					
		5					
		6					
		7					
7Eh	307Eh	0				00h	
		1					
		2					
		3		MSB			
		4		Fixed to 0	0		—
		5		Fixed to 0	0		—
		6		Fixed to 0	0		—
		7		Fixed to 0	0		—

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Address 4-wire	Address I²C	bit	Register Name	Description	Default value after reset By register	Default value after reset By address	Reflection timing
80h	3080h	0	PULSE2_DN [19:0]	LSB	00000h	00h	S
		1					
		2					
		3					
		4					
		5					
		6					
		7					
81h	3081h	0		Pulse2 active period end timing setting Designated in line units from reference point (For details, see the "Pulse Output Function")		00h	
		1					
		2					
		3					
		4					
		5					
		6					
		7					
82h	3082h	0				00h	
		1					
		2					
		3		MSB			
		4		Fixed to 0	0		—
		5		Fixed to 0	0		—
		6		Fixed to 0	0		—
		7		Fixed to 0	0		—
89h	3089h	[7:0]	INCKSEL0 [7:0]	Set according to INCK frequency and drive mode.	80h	80h	S
8Ah	308Ah	[7:0]	INCKSEL1 [7:0]	Set according to INCK frequency and drive mode.	0Fh	0Fh	S
8Bh	308Bh	[7:0]	INCKSEL2 [7:0]	Set according to INCK frequency and drive mode.	80h	80h	S
8Ch	308Ch	[7:0]	INCKSEL3 [7:0]	Set according to INCK frequency and drive mode.	0Ch	0Ch	S
8Dh	308Dh	0	SHS [19:0]	LSB	0000Eh	0Eh	V
		1					
		2					
		3					
		4					
		5					
		6					
		7					
8Eh	308Eh	0		Storage time adjustment Designated in line unit		00h	
		1					
		2					
		3					
		4					
		5					
		6					
		7					
8Fh	308Fh	0				00h	
		1					
		2					
		3		MSB			
		4		Fixed to 0	0		—
		5		Fixed to 0	0		—
		6		Fixed to 0	0		—
		7		Fixed to 0	0		—

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Address		bit	Register Name	Description	Default value after reset		Reflection timing
4-wire	I²C				By register	By address	
AAh	30AAh	0	VINT_EN	Setting of Interrupt mode in Trigger Mode 0: V interrupt is disable 1: V interrupt is enable	1	01h	S
		1		Fixed to 0	0		—
		2		Fixed to 0	0		—
		3		Fixed to 0	0		—
		4		Fixed to 0	0		—
		5		Fixed to 0	0		—
		6		Fixed to 0	0		—
		7		Fixed to 0	0		—
AEh	30AEh	0	LOWLAGTRG	Selection of trigger mode 0: Except for Fast trigger mode 1: Fast trigger mode	0	00h	S
		1		Fixed to 0	0		—
		2		Fixed to 0	0		—
		3		Fixed to 0	0		—
		4		Fixed to 0	0		—
		5		Fixed to 0	0		—
		6		Fixed to 0	0		—
		7		Fixed to 0	0		—
B0h	30B0h	0		Fixed to 0	0	00h	—
		1	OVERLAP_ROI_EN	ROI mode setting 0: ROI Mode 1: Overlap ROI Mode	0		S
		[7:2]		Fixed to 0	00h		—

Chip ID = 03 (Write: Chip ID = 03h, Read: Chip ID = 83h, I²C: 31h)**

Please refer to the other register map file for the register that has not been described.

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Chip ID = 04 (Write: Chip ID = 04h, Read: Chip ID = 84h, I²C: 32**h)

Please refer to the other register map file for the register that has not been described.

Address 4-wire	Address I²C	bit	Register Name	Description	Default value after reset By register	Default value after reset By address	Reflection timing
04h	3204h	0	GAIN [8:0]	LSB Gain setting 0 dB (000d) to 48 dB (480d) 0.1 dB Step (Refer to Adderss 12h about detail of Reflection Timing.)	000h	00h	V
		1					
		2					
		3					
		4					
		5					
		6					
		7					
05h	3205h	0		MSB		00h	
		1		Fixed to 0	0		—
		2		Fixed to 0	0		—
		3		Fixed to 0	0		—
		4		Fixed to 0	0		—
		5		Fixed to 0	0		—
		6		Fixed to 0	0		—
		7		Fixed to 0	0		—
12h	3212h	[7:0]	GAINDLY	Setting of Gain Reflection Timing at Nomal mode. 08h: Gain reflect at the frame 09h: Gain reflect at the next frame (Same timing as SHS reflecting output.) Others: Setting prohibited	00h	00h	S
54h	3254h	0	BLKLEVEL [11:0]	LSB Black level offset value setting Recommended value. 00Fh: 8 bit 03Ch: 10 bit 0F0h: 12 bit	03Ch	3Ch	V
		1					
		2					
		3					
		4					
		5					
		6					
		7					
55h	3255h	0				00h	
		1					
		2					
		3		MSB			
		4		Fixed to 0	0		—
		5		Fixed to 0	0		—
		6		Fixed to 0	0		—
		7		Fixed to 0	0		—
74h	3274h	0	VOPB_VBLK_HWIDTH [12:0]	LSB VOPB effective area and V Blank width setting	05B0h	B0h	S
		1					
		2					
		3					
		4					
		5					
		6					
		7					
75h	3275h	0				05h	
		1					
		2					
		3					
		4		MSB			
		5		Fixed to 0	0		—
		6		Fixed to 0	0		—
		7		Fixed to 0	0		—

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<table>
<tr><th colspan="2">Address</th><th rowspan="2">bit</th><th rowspan="2">Register Name</th><th rowspan="2">Description</th><th colspan="2">Default value after reset</th><th rowspan="2">Reflection timing</th></tr>
<tr><th>4-wire</th><th>I2C</th><th>By register</th><th>By address</th></tr>
<tr><td rowspan="8">76h</td><td rowspan="8">3276h</td><td>0</td><td rowspan="13">FINFO_HWIDTH [12:0]</td><td rowspan="13">LSB
FINFO width setting
MSB</td><td rowspan="13">0500h</td><td rowspan="8">00h</td><td rowspan="13">S</td></tr>
<tr><td>1</td></tr>
<tr><td>2</td></tr>
<tr><td>3</td></tr>
<tr><td>4</td></tr>
<tr><td>5</td></tr>
<tr><td>6</td></tr>
<tr><td>7</td></tr>
<tr><td rowspan="8">77h</td><td rowspan="8">3277h</td><td>0</td><td rowspan="8">05h</td></tr>
<tr><td>1</td></tr>
<tr><td>2</td></tr>
<tr><td>3</td></tr>
<tr><td>4</td></tr>
<tr><td>5</td><td></td><td>Fixed to 0</td><td>0</td><td>—</td></tr>
<tr><td>6</td><td></td><td>Fixed to 0</td><td>0</td><td>—</td></tr>
<tr><td>7</td><td></td><td>Fixed to 0</td><td>0</td><td>—</td></tr>
</table>

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Chip ID = 05 (Write: Chip ID = 05h, Read: Chip ID = 85h, I^2C: 33**h)

Please refer to the other register map file for the register that has not been described.

Address 4-wire	Address I^2C	bit	Register Name	Description	Default value after reset By register	Default value after reset By address	Reflection timing
00h	3300h	0	FID0_ROIH1ON [0]	The horizontal setting of FID0 ROI area (1, y) (y = 1 to 2) 0: Disable 1: Enable	0	00h	V
		1	FID0_ROIV1ON [0]	The vertical setting of FID0 ROI area (x, 1) (x = 1 to 2) 0: Disable 1: Enable	0		I
		2	FID0_ROIH2ON [0]	The horizontal setting of FID0 ROI area (2, y) (y = 1 to 2) 0: Disable 1: Enable	0		V
		3	FID0_ROIV2ON [0]	The vertical setting of FID0 ROI area (x, 2) (x = 1 to 2) 0: Disable 1: Enable	0		I
		4		Fixed to 0	0		—
		5		Fixed to 0	0		—
		6		Fixed to 0	0		—
		7		Fixed to 0	0		—
10h	3310h	[7:0]	FID0_ROIPH1 [12:0]	Designation of horizontal cropping position for FID0 on area (1, y) (y = 1 to 2) *Set the value of multiple of 4	0000h	00h	V
11h	3311h	[4:0]				00h	
		[7:5]		Fixed to 0h	0h		—
12h	3312h	[7:0]	FID0_ROIPV1 [11:0]	Designation of vertical cropping position for FID0 on area (x, 1) (x = 1 to 2) *Set the value of multiple of 4	000h	00h	I
13h	3313h	[3:0]				00h	
		[7:4]		Fixed to 0h	0h		—
14h	3314h	[7:0]	FID0_ROIWH1 [12:0]	Designation of horizontal cropping size for FID0 on area (1, y) (y = 1 to 2) *Set the value of multiple of 4	0000h	00h	V
15h	3315h	[4:0]				00h	
		[7:5]		Fixed to 0h	0h		—
16h	3316h	[7:0]	FID0_ROIWV1 [11:0]	Designation of vertical cropping size for FID0 on area (x, 1) (x = 1 to 2) *Set the value of multiple of 4	000h	00h	I
17h	3317h	[3:0]				00h	
		[7:4]		Fixed to 0h	0h		—
18h	3318h	[7:0]	FID0_ROIPH2 [12:0]	Designation of horizontal cropping position for FID0 on area (2, y) (y = 1 to 2) *Set the value of multiple of 4	0000h	00h	V
19h	3319h	[4:0]				00h	
		[7:5]		Fixed to 0h	0h		—
1Ah	331Ah	[7:0]	FID0_ROIPV2 [11:0]	Designation of vertical cropping position for FID0 on area (x, 2) (x = 1 to 2) *Set the value of multiple of 4	000h	00h	I
1Bh	331Bh	[3:0]				00h	
		[7:4]		Fixed to 0h	0h		—
1Ch	331Ch	[7:0]	FID0_ROIWH2 [12:0]	Designation of horizontal cropping size for FID0 on area (2, y) (y = 1 to 2) *Set the value of multiple of 4	0000h	00h	V
1Dh	331Dh	[4:0]				00h	
		[7:5]		Fixed to 0h	0h		—
1Eh	331Eh	[7:0]	FID0_ROIWV2 [11:0]	Designation of vertical cropping size for FID0 on area (x, 2) (x = 1 to 2) *Set the value of multiple of 4	000h	00h	I
1Fh	331Fh	[3:0]				00h	
		[7:4]		Fixed to 0h	0h		—

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Chip ID = 06 (Write: Chip ID = 06h, Read: Chip ID = 86h, I^2C: 34h)**

Please refer to the other register map file for the register that has not been described.

Chip ID = 07 (Write: Chip ID = 07h, Read: Chip ID = 87h, I^2C: 35h)**

Please refer to the other register map file for the register that has not been described.

Chip ID = 08 (Write: Chip ID = 08h, Read: Chip ID = 88h, I^2C: 36h)**

Please refer to the other register map file for the register that has not been described.

Chip ID = 09 (Write: Chip ID = 09h, Read: Chip ID = 89h, I^2C: 37h)**

Please refer to the other register map file for the register that has not been described.

Chip ID = 0A (Write: Chip ID = 0Ah, Read: Chip ID = 8Ah, I^2C: 38h)**

Please refer to the other register map file for the register that has not been described.

Chip ID = 0B (Write: Chip ID = 0Bh, Read: Chip ID = 8Bh, I^2C: 39h)**

Please refer to the other register map file for the register that has not been described.

Chip ID = 0C (Write: Chip ID = 0Ch, Read: Chip ID = 8Ch, I^2C: 3Ah)**

Please refer to the other register map file for the register that has not been described.

Chip ID = 0D (Write: Chip ID = 0Dh, Read: Chip ID = 8Dh, I^2C: 3Bh)**

Please refer to the other register map file for the register that has not been described.

Chip ID = 0E (Write: Chip ID = 0Eh, Read: Chip ID = 8Eh, I^2C: 3Ch)**

Please refer to the other register map file for the register that has not been described.

Chip ID = 0F (Write: Chip ID = 0Fh, Read: Chip ID = 8Fh, I^2C: 3Dh)**

Please refer to the other register map file for the register that has not been described.

Chip ID = 10 (Write: Chip ID = 10h, Read: Chip ID = 90h, I^2C: 3Eh)**

Please refer to the other register map file for the register that has not been described.

Chip ID = 11 (Write: Chip ID = 11h, Read: Chip ID = 91h, I^2C: 3Fh)**

Please refer to the other register map file for the register that has not been described.

Chip ID = 12 (Write: Chip ID = 12h, Read: Chip ID = 92h, I^2C: 40h)**

Please refer to the other register map file for the register that has not been described.

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Readout Drive Modes

The table below lists the operating modes available with this sensor. (Each value is the Max. frame rate of the each number of ch.)

FREQ (CID = 02h, Address = 1Bh, [1:0]) = 0h

Drive mode	Frame rate [frame/s]	Data rate [Gbps]	Serial LVDS ch*1	A/D conversion	Number of recording pixels		Total number of pixels*2		Number of INCK in 1H		
					H	V	H	V	INCK: 37.125 MHz	INCK: 74.25 MHz	INCK: 54 MHz
All pixel	276.0	4.752	8	8	1440	1080	1904	1130	119.0	238.0	173.1
	154.9	2.376	4				1696		212.0	424.0	308.4
	82.5	1.188	2				1592		398.0	796.0	578.9
	226.5	4.752	8	10			1856		145.0	290.0	210.9
	126.3	2.376	4				1664		260.0	520.0	378.2
	66.3	1.188	2				1584		495.0	990.0	720.0
	165.9	4.752	8	12			2112		198.0	396.0	288.0
	107.3	2.376	4				1632		306.0	612.0	445.1
	56.1	1.188	2				1560		585.0	1170.0	850.9
All pixel (Vertical / Horizontal 1/2 subsampling)	581.2	4.752	8	8	720	540	1744	586	109.0	218.0	158.5
	523.5	2.376	4				968		121.0	242.0	176.0
	293.3	1.188	2				864		216.0	432.0	314.2
	506.8	4.752	8	10			1600		125.0	250.0	181.8
	436.9	2.376	4				928		145.0	290.0	210.9
	239.0	1.188	2				848		265.0	530.0	385.5
	319.9	4.752	8	12			2112		198.0	396.0	288.0
	319.9	2.376	4				1056		198.0	396.0	288.0
	203.0	1.188	2				832		312.0	624.0	453.8
ROI	*4	4.752	8	8	*3	*3	1904	*4	119.0	238.0	173.1
	*4	2.376	4				1696		212.0	424.0	308.4
	*4	1.188	2				1592		398.0	796.0	578.9
	*4	4.752	8	10			1856		145.0	290.0	210.9
	*4	2.376	4				1664		260.0	520.0	378.2
	*4	1.188	2				1584		495.0	990.0	720.0
	*4	4.752	8	12			2112		198.0	396.0	288.0
	*4	2.376	4				1632		306.0	612.0	445.1
	*4	1.188	2				1560		585.0	1170.0	850.9

*1 The data rate of each output channel is value that is obtained by total data rate divided by the number of channels.
Example) In All-pixel 276.0 [frame/s] mode: 4.752 [Gbps] / 8 = 594 [Mbps]

*2 For the setting value to register HMAX / VMAX, see the section of each drive mode settings

*3 Designated cropping area (ROI)

*4 See the section of "ROI mode"

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FREQ (CID = 02h, Address = 1Bh, [1:0]) = 1h

Drive mode	Frame rate [frame/s]	Data rate [Gbps]	Serial LVDS ch*1	A/D conversion	Number of recording pixels		Total number of pixels*2		Number of INCK in 1H		
					H	V	H	V	INCK: 37.125 MHz	INCK: 74.25 MHz	INCK: 54 MHz
All pixel	150.7	2.376	8	8	1440	1080	1744	1130	218.0	436.0	317.1
	81.3	1.188	4				1616		404.0	808.0	587.6
	42.3	0.594	2				1552		776.0	1552.0	1128.7
	123.9	2.376	8	10			1696		265.0	530.0	385.5
	65.7	1.188	4				1600		500.0	1000.0	727.3
	34.0	0.594	2				1544		965.0	1930.0	1403.6
	105.3	2.376	8	12			1664		312.0	624.0	453.8
	55.5	1.188	4				1576		591.0	1182.0	859.6
	28.5	0.594	2				1536		1152.0	2304.0	1675.6
All pixel (Vertical / Horizontal 1/2 subsampling)	498.8	2.376	8	8	720	540	1016	586	127.0	254.0	184.7
	285.3	1.188	4				888		222.0	444.0	322.9
	153.7	0.594	2				824		412.0	824.0	599.3
	408.7	2.376	8	10			992		155.0	310.0	225.5
	234.6	1.188	4				864		270.0	540.0	392.7
	124.2	0.594	2				816		510.0	1020.0	741.8
	319.9	2.376	8	12			1056		198.0	396.0	288.0
	199.2	1.188	4				848		318.0	636.0	462.5
	104.5	0.594	2				808		606.0	1212.0	881.5
ROI	*4	2.376	8	8	*3	*3	1744	*4	218.0	436.0	317.1
	*4	1.188	4				1616		404.0	808.0	587.6
	*4	0.594	2				1552		776.0	1552.0	1128.7
	*4	2.376	8	10			1696		265.0	530.0	385.5
	*4	1.188	4				1600		500.0	1000.0	727.3
	*4	0.594	2				1544		965.0	1930.0	1403.6
	*4	2.376	8	12			1664		312.0	624.0	453.8
	*4	1.188	4				1576		591.0	1182.0	859.6
	*4	0.594	2				1536		1152.0	2304.0	1675.6

*1 The data rate of each output channel is value that is obtained by total data rate divided by the number of channels.
Example) In All-pixel 150.7 [frame/s] mode: 2.376 [Gbps] / 8 = 297 [Mbps]

*2 For the setting value to register HMAX / VMAX, see the section of each drive mode settings

*3 Designated cropping area (ROI)

*4 See the section of “ROI mode”

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Sync code

The sync code is added immediately before and after "dummy signal + OB signal + effective pixel data" and then output. The sync code is output in order of 1st, 2nd, 3rd and 4th. The fixed value is output for 1st to 3rd. (BLK: Blanking period)

Sync Code Output Timing

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List of Sync Code

Sync code	1st code			2nd code			3rd code			4th code		
	8 bit	10 bit	12 bit	8 bit	10 bit	12 bit	8 bit	10 bit	12 bit	8 bit	10 bit	12 bit
SAV (Valid line)	FFh	3FFh	FFFh	00h	000h	000h	00h	000h	000h	80h	200h	800h
EAV (Valid line)	FFh	3FFh	FFFh	00h	000h	000h	00h	000h	000h	9Dh	274h	9D0h
SAV (Invalid line)	FFh	3FFh	FFFh	00h	000h	000h	00h	000h	000h	ABh	2ACh	AB0h
EAV (Invalid line)	FFh	3FFh	FFFh	00h	000h	000h	00h	000h	000h	B6h	2D8h	B60h

Sync Code Output Timing

The sensor output signal passes through the internal circuits and is output with a latency time (system delay) relative to the horizontal sync signal. This system delay value is undefined for each line, so refer to the sync codes output from the sensor and perform synchronization.

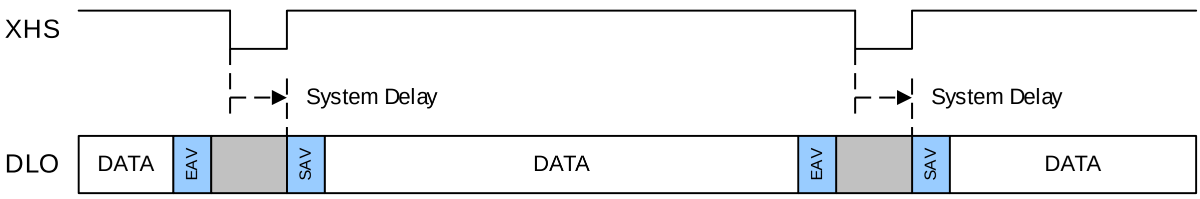

Image Data Output Format

All-pixel scan

Register List of All-pixel scan mode

Please refer to the other register map file for the register that has not been described.

Address	bit	Register name	Initial Value	Setting value									Remarks
				AD = 8 bit			AD = 10 bit			AD = 12 bit			
				276.0 [frame/s]	154.9 [frame/s]	82.5 [frame/s]	226.5 [frame/s]	126.3 [frame/s]	66.3 [frame/s]	165.9 [frame/s]	107.3 [frame/s]	56.16 [frame/s]	FREQ = 0h
				150.7 [frame/s]	81.3 [frame/s]	42.3 [frame/s]	123.9 [frame/s]	65.7 [frame/s]	34.0 [frame/s]	105.3 [frame/s]	55.9 [frame/s]	28.5 [frame/s]	FREQ = 1h
Chip ID = 02h													
05h	[7:4]	STBLVDS	0h	0h	N/A	N/A	0h	N/A	N/A	0h	N/A	N/A	8 ch LVDS
				N/A	2h	N/A	N/A	2h	N/A	N/A	2h	N/A	4 ch LVDS
				N/A	N/A	3h	N/A	N/A	3h	N/A	N/A	3h	2 ch LVDS
0Ch	[1:0]	ADBIT	0h	2h			0h			1h			0: 10 bit 1: 12 bit 2: 8 bit
0Dh	[3:0]	WINMODE	0h	0h									All-pixel mode
	[4]	HMODE	0	0									All-pixel
10h	[7:0]	VMAX	46Ah	46Ah									1130 line
11h	[7:0]												
12h	[3:0]												
14h	[7:0]	HMAX	122h	0EEh	1A8h	31Ch	122h	208h	3DEh	18Ch	264h	492h	FREQ = 0h
15h	[7:0]			1B4h	328h	610h	212h	3E8h	78Ah	270h	49Eh	900h	FREQ = 1h
16h	[1:0]	ODBIT	0h	2h			0h			1h			0: 10 bit 1: 12 bit 2: 8 bit
1Bh	[1:0]	FREQ	0h	0h / 1h									
1Ch	[7:4]	OPORTSEL	1h	1h	N/A	N/A	1h	N/A	N/A	1h	N/A	N/A	8 ch LVDS
				N/A	3h	N/A	N/A	3h	N/A	N/A	3h	N/A	4 ch LVDS
				N/A	N/A	4h	N/A	N/A	4h	N/A	N/A	4h	2 ch LVDS
89h	[7:0]	INCKSEL0	80h	INCK = 37.125 MHz: 80h INCK = 54 MHz: B0h INCK = 74.25 MHz: 80h									
8Ah	[7:0]	INCKSEL1	0Fh	INCK = 37.125 MHz: 0Bh INCK = 54 MHz: 0Fh INCK = 74.25 MHz: 0Fh									
8Bh	[7:0]	INCKSEL2	80h	INCK = 37.125 MHz: 80h INCK = 54 MHz: B0h INCK = 74.25 MHz: 80h									
8Ch	[7:0]	INCKSEL3	0Ch	INCK = 37.125 MHz: 08h INCK = 54 MHz: 0Ch INCK = 74.25 MHz: 0Ch									
Chip ID = 04h													
54h	[7:0]	BLKLEVEL	03Ch	00Fh			03Ch			0F0h			Recommended value
55h	[3:0]												

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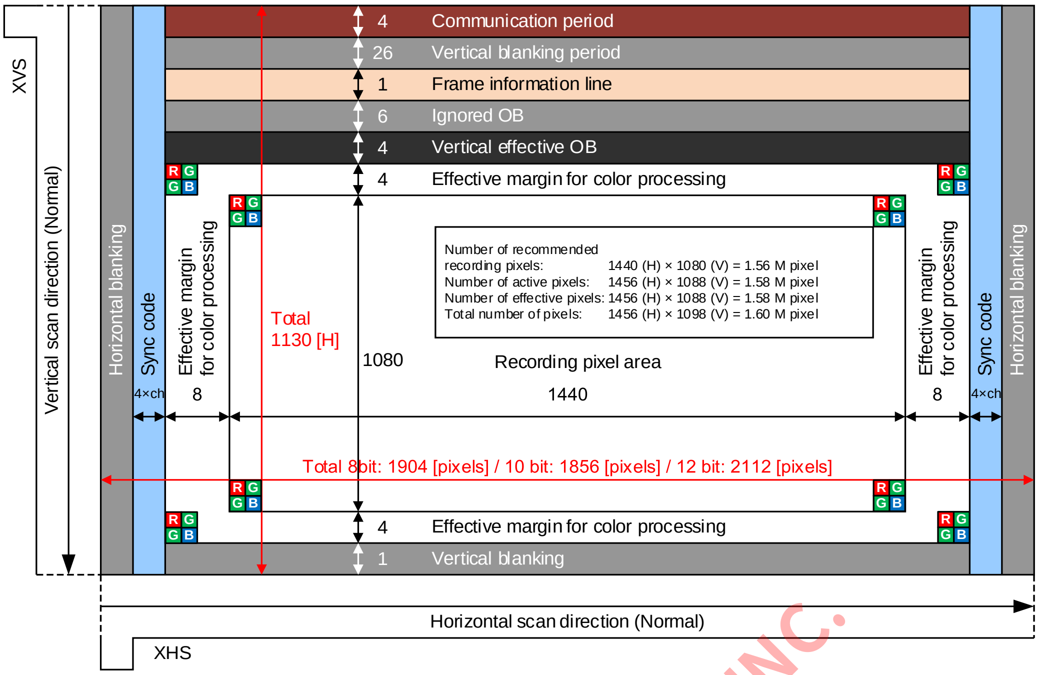

Pixel Array Image Drawing in All-pixel scan Mode (FREQ = 0, 8 ch LVDS)

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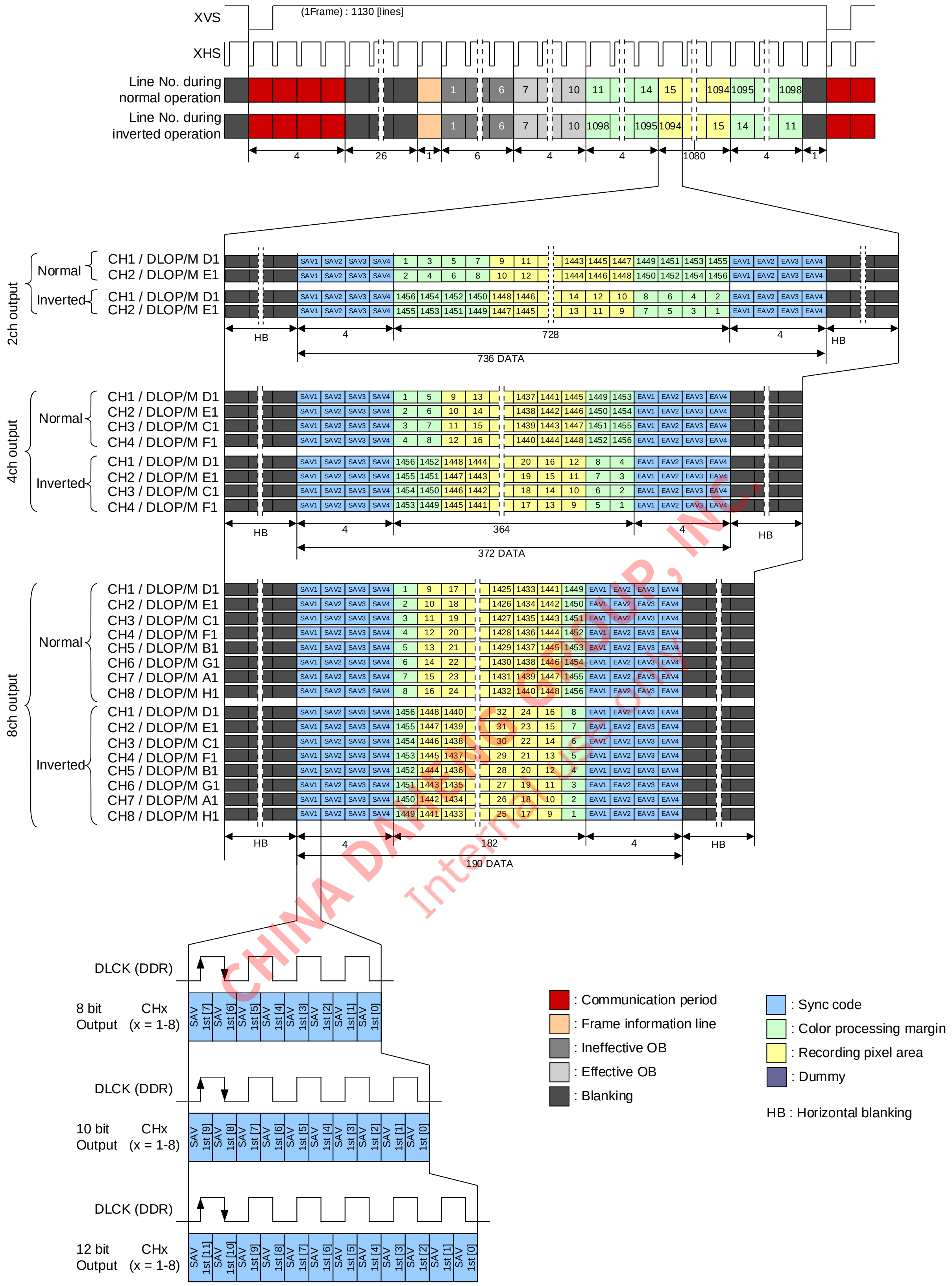


Drive Timing Chart for Serial Output in All-pixel Scan Mode

ROI mode

This Sensor has ROI function that signals are cut out and read out in multi arbitrary positions.
Cropping position can set maximum 4 areas that specified by horizontal 2 points and vertical 2 points, regarding effective pixel start position as origin (0, 0) in all pixel scan mode. Cropping is available from All-pixel scan mode and horizontal period are fixed to the value for this mode.
These cropped areas by horizontal cropping setting (ROI (1, y) to ROI (2, y)) are output with left justified and that extends the horizontal blanking period. In vertical cropping area (ROI (x, 1) to ROI (x, 2)), the number of image data is also output from cropping start line and the frame rate can be adjusted by changing the number of input XVS lines in slave mode or changing register VMAX in master mode.
One invalid frame is generated when the ROI area changing size or cropping address.
ROI image is shown in the figure below.
In case of Vertical / Horizontal 1/2 subsampling mode, this sensor doesn't support ROI mode.
This section is written in case of all-pixel scan mode for example on this document.

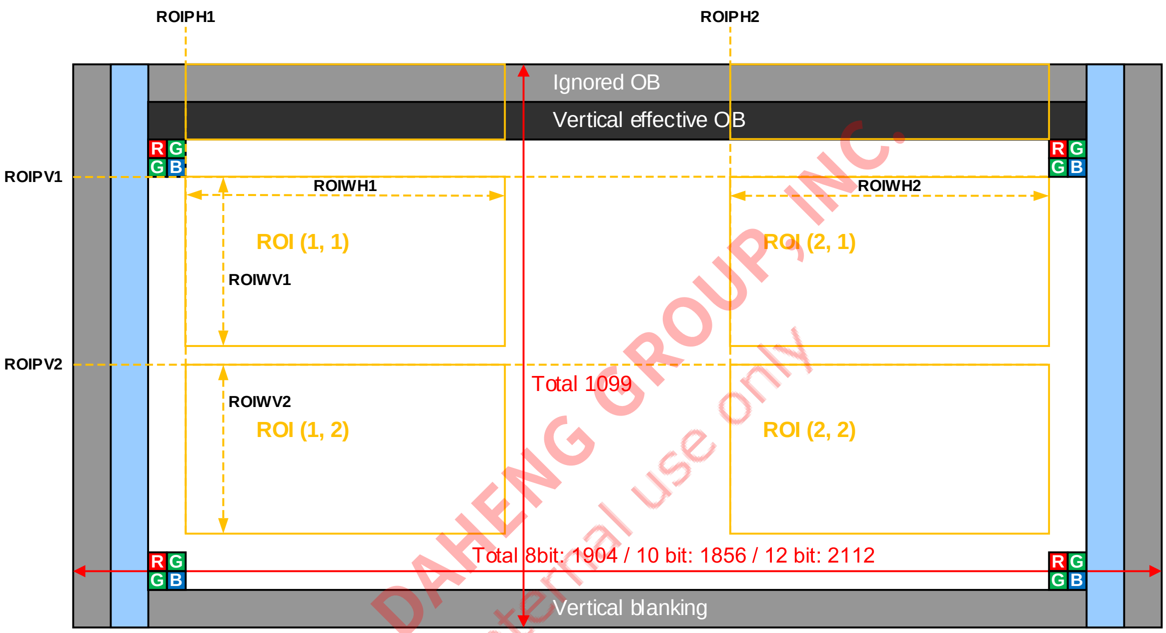
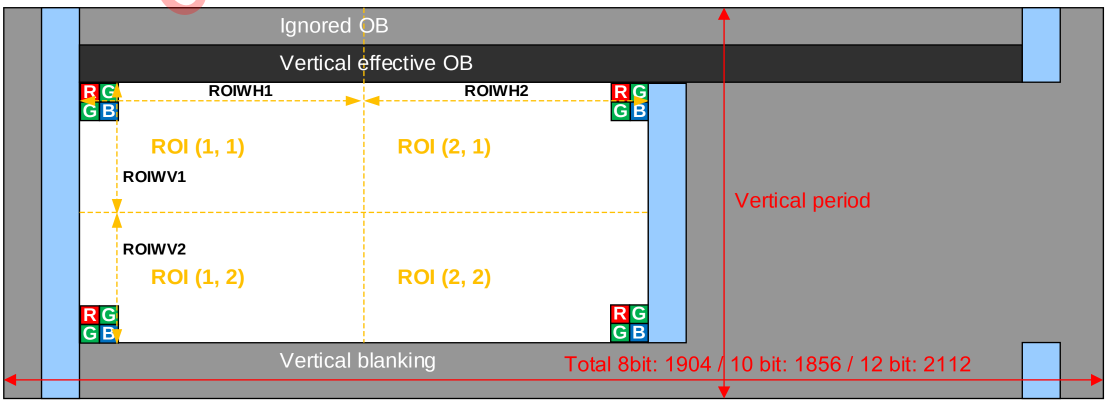


Image Drawing of Designated Areas in ROI Mode (FREQ = 0, 8 ch LVDS)



Details of Image Drawing (FREQ = 0, 8 ch LVDS)

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Register List of ROI mode

Please set All-pixel scan mode to the settings other than the following.

Address	bit	Register name	Initial Value	Setting value									Remarks
				AD = 8 bit			AD = 10 bit			AD = 12 bit			
				*1 [frame/s]	*2 [frame/s]	*3 [frame/s]	*4 [frame/s]	*5 [frame/s]	*6 [frame/s]	*7 [frame/s]	*8 [frame/s]	*9 [frame/s]	
Chip ID = 02h													
05h	[7:4]	STBLVDS	0h	0h	N/A	N/A	0h	N/A	N/A	0h	N/A	N/A	8 ch LVDS
				N/A	2h	N/A	N/A	2h	N/A	N/A	2h	N/A	4 ch LVDS
				N/A	N/A	3h	N/A	N/A	3h	N/A	N/A	3h	2 ch LVDS
0Ch	[1:0]	ADBIT	0h	2h			0h			1h			0: 10 bit 1: 12 bit 2: 8 bit
0Dh	[3:0]	WINMODE	0h	0h									All-pixel mode
	[4]	HMODE	0	0									All-pixel
10h	[7:0]	VMAX	46Ah	*1	*2	*3	*4	*5	*6	*7	*8	*9	
11h	[7:0]												
12h	[3:0]												
14h	[7:0]	HMAX	122h	0EEh	1A8h	31Ch	122h	208h	3DEh	18Ch	264h	492h	FREQ = 0h
15h	[7:0]			1B4h	328h	610h	212h	3E8h	78Ah	270h	49Eh	900h	FREQ = 1h
16h	[1:0]	ODBIT	0h	2h			0h			1h			0: 10 bit 1: 12 bit 2: 8 bit
1Bh	[1:0]	FREQ	0h	0h / 1h									
1Ch	[7:4]	OPORTSEL	1h	1h	N/A	N/A	1h	N/A	N/A	1h	N/A	N/A	8 ch LVDS
				N/A	3h	N/A	N/A	3h	N/A	N/A	3h	N/A	4 ch LVDS
				N/A	N/A	4h	N/A	N/A	4h	N/A	N/A	4h	2 ch LVDS
89h	[7:0]	INCKSEL0	80h	INCK = 37.125 MHz: 80h INCK = 54 MHz: B0h INCK = 74.25 MHz: 80h									
8Ah	[7:0]	INCKSEL1	0Fh	INCK = 37.125 MHz: 0Bh INCK = 54 MHz: 0Fh INCK = 74.25 MHz: 0Fh									
8Bh	[7:0]	INCKSEL2	80h	INCK = 37.125 MHz: 80h INCK = 54 MHz: B0h INCK = 74.25 MHz: 80h									
8Ch	[7:0]	INCKSEL3	0Ch	INCK = 37.125 MHz: 08h INCK = 54 MHz: 0Ch INCK = 74.25 MHz: 0Ch									
B0h	[1]	OVERLAP_ROI_EN	0h	0									
Chip ID = 04h													
54h	[7:0]	BLKLEVEL	03Ch	00Fh			03Ch			0F0h			Recommended value
55h	[3:0]												

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Address	bit	Register name	Initial Value	Setting value									Remarks
				AD = 8 bit			AD = 10 bit			AD = 12 bit			
				*1 [frame/s]	*2 [frame/s]	*3 [frame/s]	*4 [frame/s]	*5 [frame/s]	*6 [frame/s]	*7 [frame/s]	*8 [frame/s]	*9 [frame/s]	
Chip ID = 05h													
00h	[0]	FID0_ROIH1ON	0	The horizontal setting of FID0 ROI area (1, y) (y = 1 to 2) 0: Disable 1: Enable									
	[1]	FID0_ROIV1ON	0	The vertical setting of FID0 ROI area (x, 1) (x = 1 to 2) 0: Disable 1: Enable									
	[2]	FID0_ROIH2ON	0	The horizontal setting of FID0 ROI area (2, y) (y = 1 to 2) 0: Disable 1: Enable									
	[3]	FID0_ROIV2ON	0	The vertical setting of FID0 ROI area (x, 2) (x = 1 to 2) 0: Disable 1: Enable									
10h	[7:0]	FID0_ROIPH1	0000h	Designation of horizontal cropping position for FID0 on area (1, y) (y = 1 to 2) *Set the value of multiple of 4									
11h	[4:0]												
12h	[7:0]	FID0_ROIPV1	000h	Designation of vertical cropping position for FID0 on area (x, 1) (x = 1 to 2) *Set the value of multiple of 4									
13h	[3:0]												
14h	[7:0]	FID0_ROIWH1	0000h	Designation of horizontal cropping size for FID0 on area (1, y) (y = 1 to 2) *Set the value of multiple of 4									
15h	[4:0]												
16h	[7:0]	FID0_ROIWV1	000h	Designation of vertical cropping size for FID0 on area (x, 1) (x = 1 to 2) *Set the value of multiple of 4									
17h	[3:0]												
18h	[7:0]	FID0_ROIPH2	0000h	Designation of horizontal cropping position for FID0 on area (2, y) (y = 1 to 2) *Set the value of multiple of 4									
19h	[4:0]												
1Ah	[7:0]	FID0_ROIPV2	000h	Designation of vertical cropping position for FID0 on area (x, 2) (x = 1 to 2) *Set the value of multiple of 4									
1Bh	[3:0]												
1Ch	[7:0]	FID0_ROIWH2	0000h	Designation of horizontal cropping size for FID0 on area (2, y) (y = 1 to 2) *Set the value of multiple of 4									
1Dh	[4:0]												
1Eh	[7:0]	FID0_ROIWV2	000h	Designation of vertical cropping size for FID0 on area (x, 2) (x = 1 to 2) *Set the value of multiple of 4									
1Fh	[3:0]												

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Restrictions on ROI mode

The register settings should satisfy following conditions:

* Do not designate area like be overlap.
  ROIPH1 + ROIWH1 < ROIPH2
  ROIPH2 + ROIWH2 ≤ 1456d

  ROIPV1 + ROIWV1 < ROIPV2
  ROIPV2 + ROIWV2 ≤ 1088d

* Set the horizontal and vertical setting in multiple of 4.

* Minimum width of the window is as below.
  10 / 12 bit mode
  ROIWH1 + ROIWH2 ≥ 260d

  8 bit mode
  ROIWH1 + ROIWH2 ≥ 516d

  8 / 10 / 12 bit mode
  ROIWV1 + ROIWV2 ≥ 4d

Frame rate on ROI mode

Frame rate [frame/s] = 1 / ((“Number of lines per frame” or VMAX) × (1 H period))

* Number of lines per frame or VMAX = ROIWV1 + ROIWV2 + 42
* 1 H period: Change according to the data rate settings and the number of LVDS channels.
  Calculate by number of INCK in 1 H and the period of INCK.

The example of ROI setting is shown below.
ROIWV1 + ROIWV2 = 600
ROIWV1 + ROIWV2 = 4 (minimum value)

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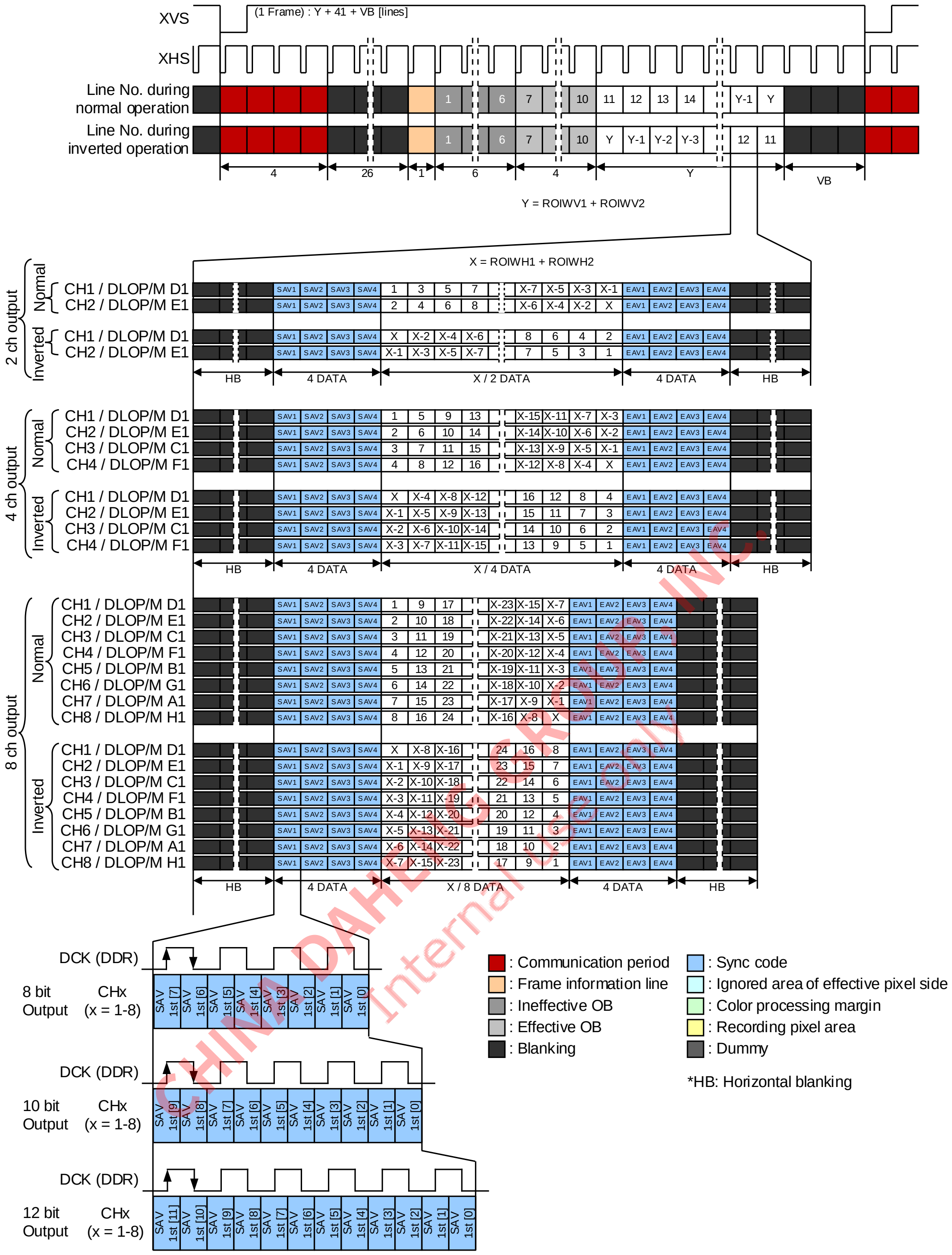
Frame rate List of each setting

Register settings No. in register list	1 H period [µs]		Frame rate [frame/s]			
			Total number of ROI: 600 [line]		Total number of ROI: 4 [line]	
	FREQ 0h	FREQ 1h	FREQ = 0h	FREQ = 1h	FREQ = 0h	FREQ = 1h
*1	3.21	5.87	485.94	265.26	6782.06	3702.13
*2	5.71	10.88	272.77	143.14	3806.91	1997.69
*3	10.72	20.90	145.29	74.52	2027.80	1040.03
*4	3.91	7.14	398.81	218.22	5565.97	3045.53
*5	7.00	13.47	222.41	115.65	3104.10	1614.13
*6	13.33	25.99	116.82	59.92	1630.43	836.34
*7	5.33	8.40	292.06	185.34	4076.09	2586.75
*8	8.24	15.92	188.98	97.85	2637.47	1365.59
*9	15.76	31.03	98.85	50.20	1379.60	700.58



Drive Timing Chart for Serial Output in ROI Mode

ROI Overlap mode

This Sensor has ROI function that signals are cut out and read out in multi arbitrary positions.
Cropping position can set maximum 2 areas, regarding effective pixel start position as origin (0, 0) in all pixel scan mode. Cropping is available from All-pixel scan mode and horizontal period are fixed to the value for this mode.
These cropped areas by horizontal cropping setting (ROI (1, y) to ROI (2, y)) are output with left justified and that extends the horizontal blanking period. In vertical cropping area (ROI (x, 1) to ROI (x, 2)), the number of image data is also output from cropping start line and the frame rate can be adjusted by changing the number of input XVS lines in slave mode or changing register VMAX in master mode.
One invalid frame is generated when the ROI area changing size or cropping address.
ROI image is shown in the figure below.
In case of Vertical / Horizontal 1/2 subsampling mode, this sensor doesn't support ROI mode.
This section is written in case of all-pixel scan mode for example on this document.

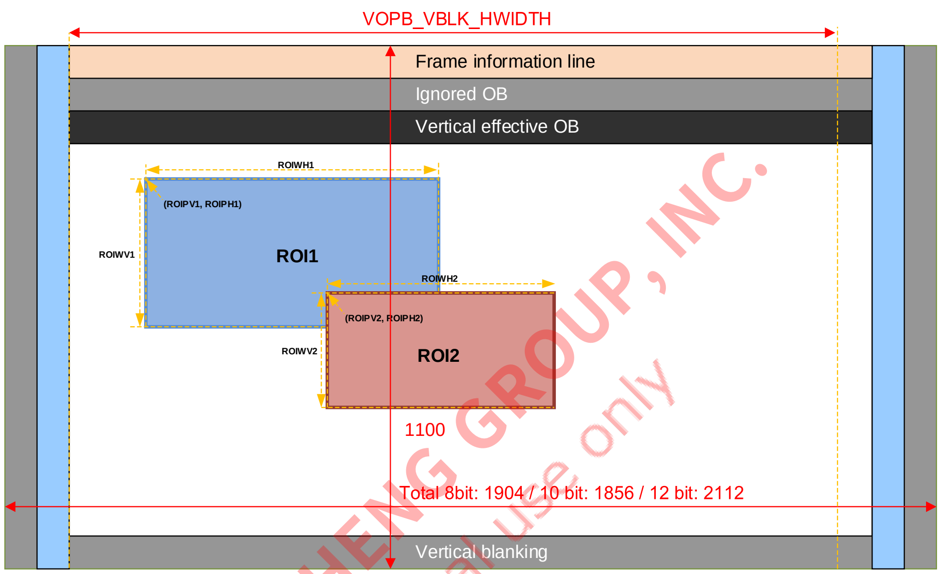


Image Drawing of Designated Areas in ROI Overlap Mode (FREQ = 0, 8 ch LVDS)

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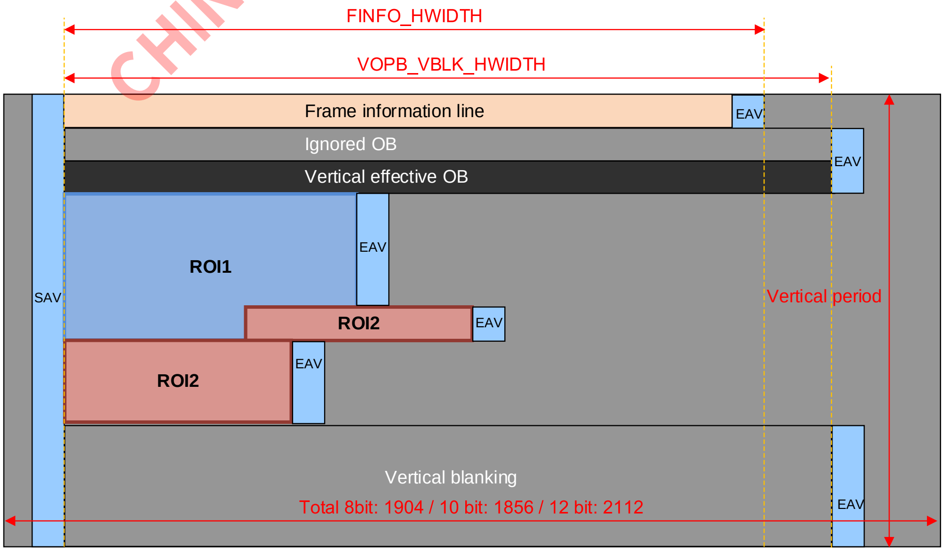

Details of Image Drawing (FREQ = 0, 8 ch LVDS)

Register List of ROI Overlap mode

Please set ROI mode to the settings other than the following.

Address	bit	Register name	Initial Value	Setting value									Remarks
				AD = 8 bit			AD = 10 bit			AD = 12 bit			
				*1 [frame/s]	*2 [frame/s]	*3 [frame/s]	*4 [frame/s]	*5 [frame/s]	*6 [frame/s]	*7 [frame/s]	*8 [frame/s]	*9 [frame/s]	
Chip ID = 02h													
B0h	[1]	OVERLAP_ROI_EN	0h	1h									
Chip ID = 04h													
74h	[7:0]	VOPB_VBLK_HWIDTH	05B0h	VOPB effective area and V Blank width setting									
75h	[4:0]												
76h	[7:0]	FINFO_HWIDTH	0500h	FINFO width setting									
77h	[4:0]												

Restrictions on ROI mode

The register settings should satisfy following conditions:

* Do not designate area like be overlap.
ROIPH1 + ROIWH1 ≤ 1456d
ROIPH2 + ROIWH2 ≤ 1456d

ROIPV1 + ROIWV1 ≤ 1088d
ROIPV2 + ROIWV2 ≤ 1088d

16d ≤ VOPB_VBLK_HWIDTH ≤ 1504d

FINFO_HWIDTH ≤ 1504d

* Set the horizontal, vertical, VOPB width and FINFO width setting in multiple of 4.

* Minimum output width is as below.
10 / 12 bit mode
Minimum horizontal output width ≥ 260d
FINFO_HWIDTH ≥ 260d

8 bit mode
Minimum horizontal output width ≥ 516d
FINFO_HWIDTH ≥ 516d

8 / 10 / 12 bit mode
Minimum vertical output width ≥ 4d

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Frame rate on ROI mode

Frame rate [frame/s] = 1 / ((“Number of lines per frame” or VMAX) × (1 H period))
When the maximum vertical output width is 600 or 4 lines, refer to ROI mode.

Vertical / Horizontal 1/2 Subsampling mode

V direction and H direction must be set in this mode.

Register List of Vertical / Horizontal 1/2 subsampling mode

Please set All-pixel scan mode to the settings other than the following.

Address	bit	Register name	Initial Value	Setting value									Remarks
				AD = 8 bit			AD = 10 bit			AD = 12 bit			
				581.2 [frame/s]	523.5 [frame/s]	293.3 [frame/s]	506.8 [frame/s]	436.9 [frame/s]	239.0 [frame/s]	319.9 [frame/s]	319.9 [frame/s]	203.0 [frame/s]	FREQ = 0h
				498.8 [frame/s]	285.3 [frame/s]	153.7 [frame/s]	408.7 [frame/s]	234.6 [frame/s]	124.2 [frame/s]	319.9 [frame/s]	199.2 [frame/s]	104.5 [frame/s]	FREQ = 1h
Chip ID = 02h													
05h	[7:4]	STBLVDS	0h	0h	N/A	N/A	0h	N/A	N/A	0h	N/A	N/A	8 ch LVDS
				N/A	2h	N/A	N/A	2h	N/A	N/A	2h	N/A	4 ch LVDS
				N/A	N/A	3h	N/A	N/A	3h	N/A	N/A	3h	2 ch LVDS
0Dh	[3:0]	WINMODE	0h	1h									Subsampling mode
	[4]	HMODE	0	1									Subsampling mode
10h	[7:0]	VMAX	46Ah	24Ah									586 line
11h	[7:0]												
12h	[3:0]												
14h	[7:0]	HMAX	122h	0DAh	0F2h	1BCh	0FAh	122h	212h	18Ch	18Ch	270h	FREQ = 0h
15h	[7:0]			0FEh	1B0h	338h	136h	21Ch	3FCh	18Ch	27Ch	4BCh	FREQ = 1h
1Bh	[1:0]	FREQ	0h	0h / 1h									
1Ch	[7:4]	OPORTSEL	1h	1h	N/A	N/A	1h	N/A	N/A	1h	N/A	N/A	8 ch LVDS
				N/A	3h	N/A	N/A	3h	N/A	N/A	3h	N/A	4 ch LVDS
				N/A	N/A	4h	N/A	N/A	4h	N/A	N/A	4h	2 ch LVDS

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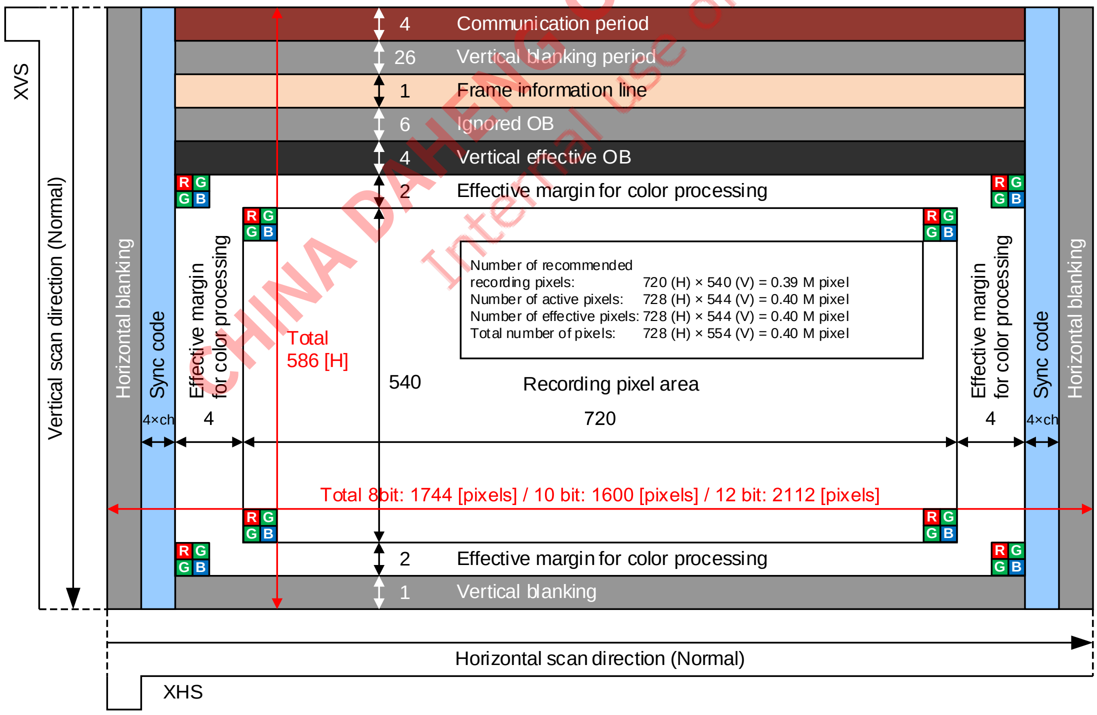


Pixel Array Image Drawing in Vertical / Horizontal 1/2 subsampling mode (FREQ = 0, 8 ch LVDS)

Description of Various Function

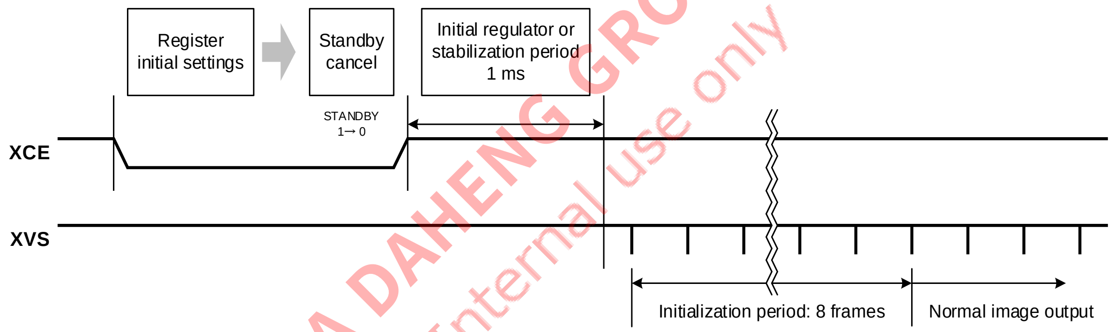
Standby mode

This sensor stops its operation and goes into standby mode which reduces the power consumption by writing “1” to the standby control register STANDBY. Standby mode is also established after power-on or other system reset operation.

Register List of Standby setting

Register	Register details			Initial value	Setting value	Remarks
	Chip ID	Address ( ) : I^2C	bit			
STANDBY	02h	00h (3000h)	[0]	1h	1h: Standby 0h: Operating	Register communication is executed even in standby mode.

The serial communication registers hold the previous values. However, the address registers transmitted in standby mode are overwritten. The serial communication block operates even in standby mode, so standby mode can be canceled by setting the STANDBY register to “0”. Some time is required for sensor internal circuit stabilization after standby mode is canceled. For details on the sequence of setting and cancel of standby mode, see the sensor setting flow after power on.
After standby mode is canceled, a normal image is output from the 9 frames after internal regulator stabilization (1 ms or more).



Sequence from Standby Cancel to Stable Image Output

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Slave Mode and Master Mode

The sensor can be switched between slave mode and master mode.
The switching is made by the XMASTER pin. Establish the XMASTER pin status before canceling the system reset. (Do not switch this pin status during operation.)
Input a vertical sync signal to XVS and input a horizontal sync signal to XHS when a sensor is in slave mode.
For sync signal interval, input data lines to output for vertical sync signal and 1H period designated in each operating mode for horizontal sync signal. See the section of "Readout Drive mode" for the number of output data line and 1H period.
Set the XMSTA register to “0” in order to start the operation after setting to master mode. In addition, set the count number of sync signal in vertical direction by the VMAX [19:0] register and the clock number in horizontal direction by the HMAX [15:0] register. See the description of operation mode for details of the section of “Readout Drive Modes”.

Pin Processing

Pin name	Pin processing	Operation mode	Remarks
XMASTER pin	Low fixed	Master mode	High: OV_{DD} Low: GND
	High fixed	Slave mode	

Register List of Slave Mode and Master Mode

Register	Register details			Initial value	Setting value	Remarks
	Chip ID	Address ( ) : I^2C	Bit			
XMSTA	02h	0Ah (300Ah)	[0]	1h	1h: Master operation ready (Initial value) 0h: Master operation start	The master operation starts by setting 0.
VMAX [19:0]		10h (3010h)	[7:0]	0046Ah	See the item of each drive mode	Line number per frame designated (Master mode and Slave mode common setting.)
		11h (3011h)	[7:0]			
		12h (3012h)	[3:0]			
HMAX [15:0]		14h (3014h)	[7:0]	0122h	See the item of each drive mode	Clock number per line designated (Master mode and Slave mode common setting.)
		15h (3015h)	[7:0]			

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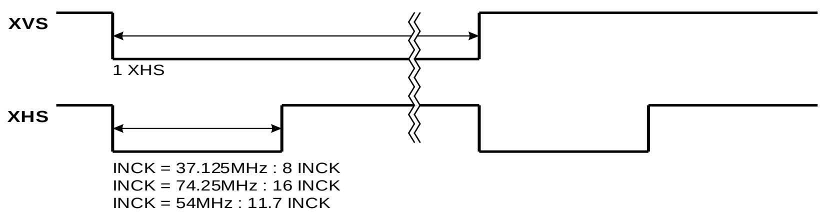
XVS / XHS Output Waveform in Master Mode



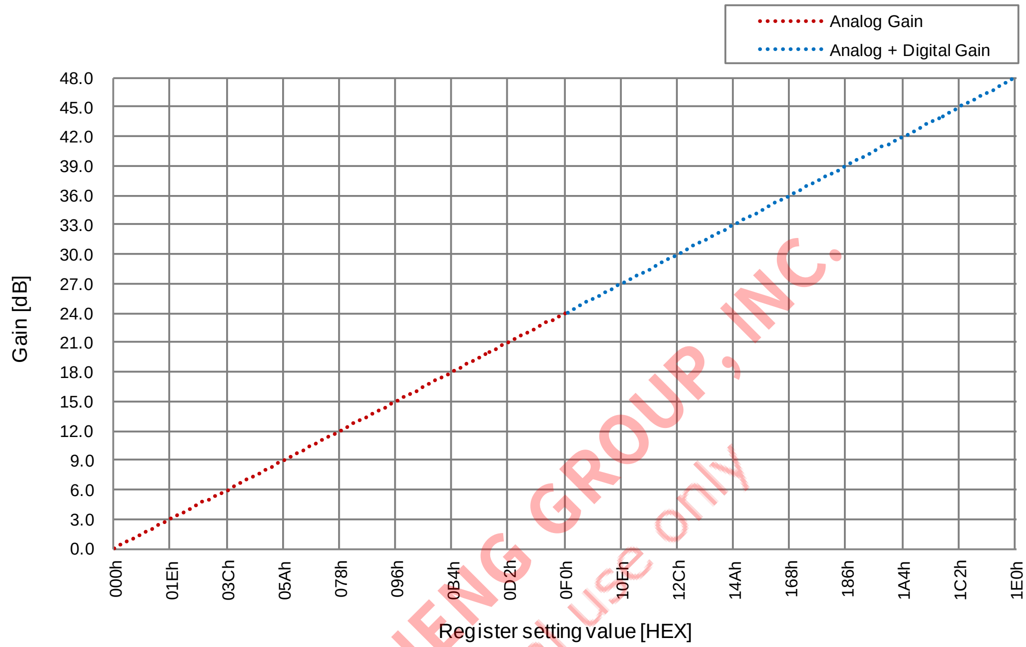
Gain Adjustment Function

PGC

The Programmable Gain Control (PGC) of this device consists of the analog block and digital block.
The total of analog gain and digital gain can be set up to 48 dB by the GAIN [8:0] register setting.
The value which is ten times the gain is set to register.

Example)
When set to 6 dB:

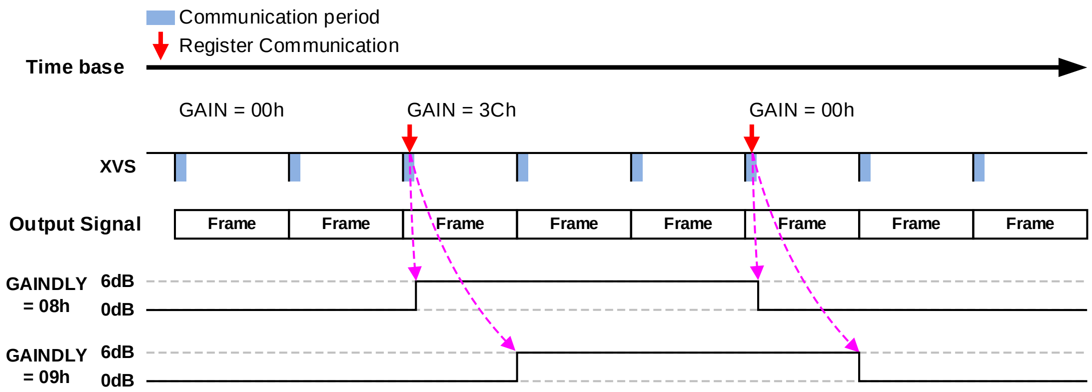
6 × 10 = 60d, GAIN = 03Ch



Register List of Gain setting

Register	Register details			Initial value	Setting value	Remarks
	Chip ID	Address ( ) : I²C	bit		Setting range	
GAIN [8:0]	04h	04h (3204h)	[7:0]	000h	000h to 1E0h (0d to 480d)	Setting value: Gain [dB] × 10
		05h (3205h)	[0]			

Gain Reflection Timing is changed by the set value of GAINDLY as shown below.



Gain Reflection Timing

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Black Level Adjustment Function

The black level offset (offset variable range: 000h to 1FFh) can be added relative to the data in which the digital gain modulation was performed by the BLKLEVEL [11:0] register. When the BLKLEVEL [11:0] setting is increased by 1 LSB, the black level is increased by 1 LSB.

* Use with values shown below is recommended.
8 bit output: 00Fh (15 d)
10 bit output: 03Ch (60 d)
12 bit output: 0F0h (240 d)

Register List of Black level adjustment

<table>
<tr><th rowspan="2">Register</th><th colspan="3">Register details</th><th rowspan="2">Initial value</th><th rowspan="2">Setting value</th></tr>
<tr><th>Chip ID</th><th>Address ( ) : I²C</th><th>bit</th></tr>
<tr><td rowspan="2">BLKLEVEL [11:0]</td><td rowspan="2">04h</td><td>54h (3254h)</td><td>[7:0]</td><td rowspan="2">03Ch</td><td rowspan="2">000h to FFFh</td></tr>
<tr><td>55h (3255h)</td><td>[3:0]</td></tr>
</table>

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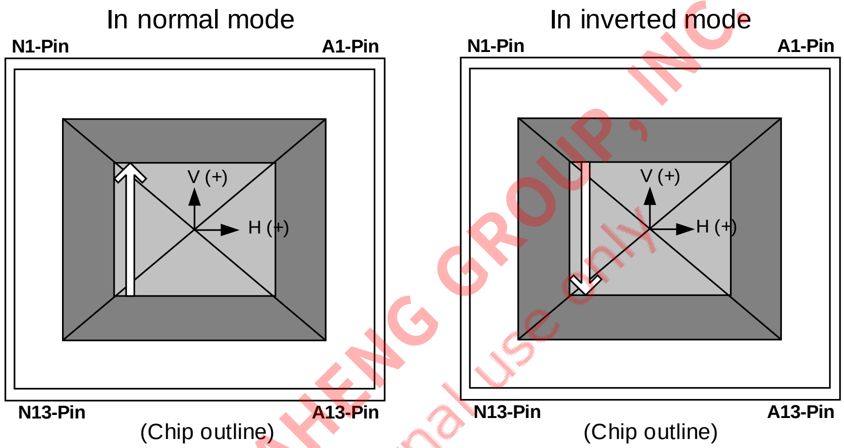
Horizontal / Vertical Normal Operation and Inverted Operation

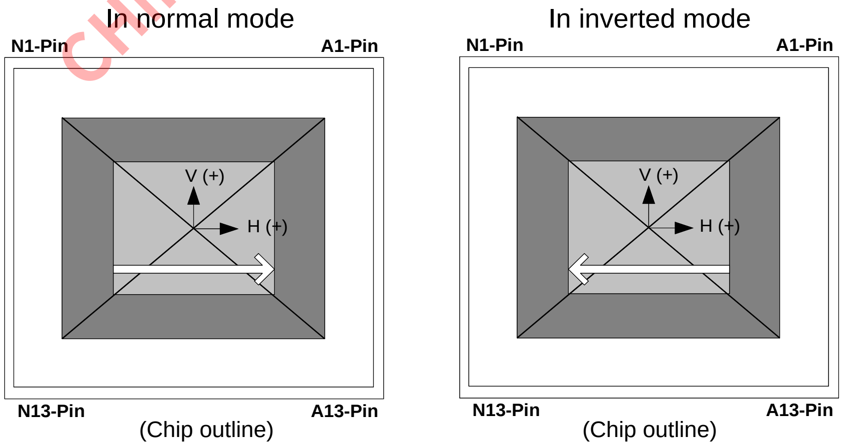
The sensor readout direction (normal / inverted) in vertical direction can be switched by the VREVERSE register setting and sensor readout direction (normal / inverted) in horizontal direction can be switched by the HREVERSE register setting. See the section of “Readout Drive Modes” for the order of readout lines in normal and inverted modes.

Register List of Readout Drive Direction setting

Register	Register details			Initial value	Setting value
	Chip ID	Address ( ) : I^2C	bit		
VREVERSE	02h	0Eh (300Eh)	[0]	0h	0h: Normal (Initial value) 1h: Inverted
HREVERSE			[1]	0h	0h: Normal (Initial value) 1h: Inverted



Normal and Inverted Drive Outline in Vertical Direction (TOP VIEW)



Normal and Inverted Drive Outline in Horizontal Direction (TOP VIEW)

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Shutter and Integration Time Settings

This sensor has a global shutter function that integrates to all line collectively by using memory in each pixel.
This sensor has a variable electronic shutter function that can control the integration time in line units for adjust the exposure time. This sensor transferred signal to memory in pixel after the exposure (memory transfer), then this sensor performs output in which readout operation is performed sequentially for each line in sync with the XHS signal.
This sensor has trigger mode that can be controlled exposure start timing and memory transfer timing by trigger.

Note) For integration time control, an image which reflects the setting is output from the frame after the setting changes.

In this item, the shutter operation and storage time are shown as in the figure below with the time sequence on the horizontal axis and the vertical address on the vertical axis. For simplification, shutter and readout operation are noted in line units.

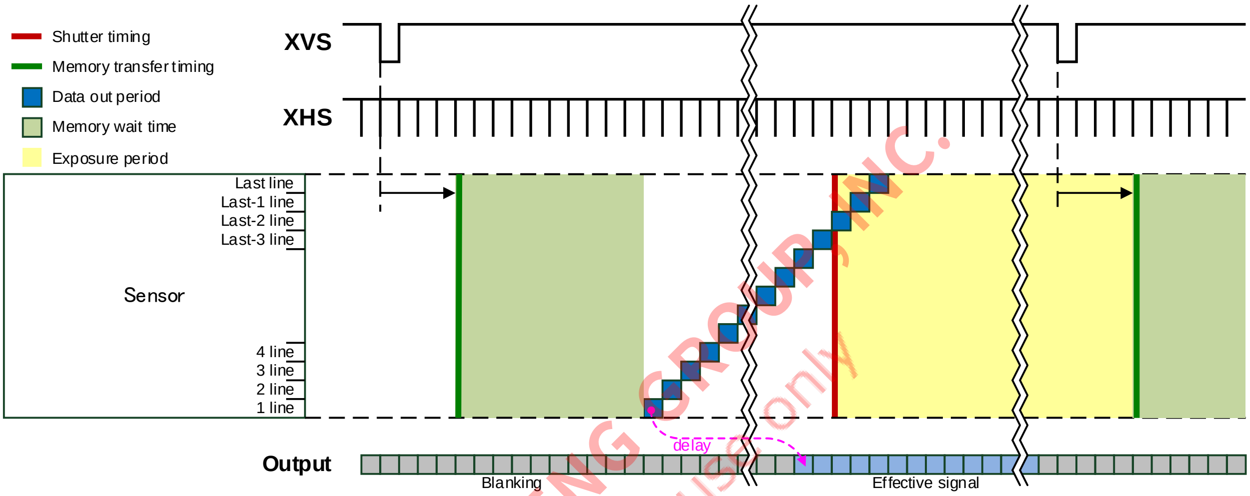

Image Drawing of Global Shutter (Normal mode) Operation

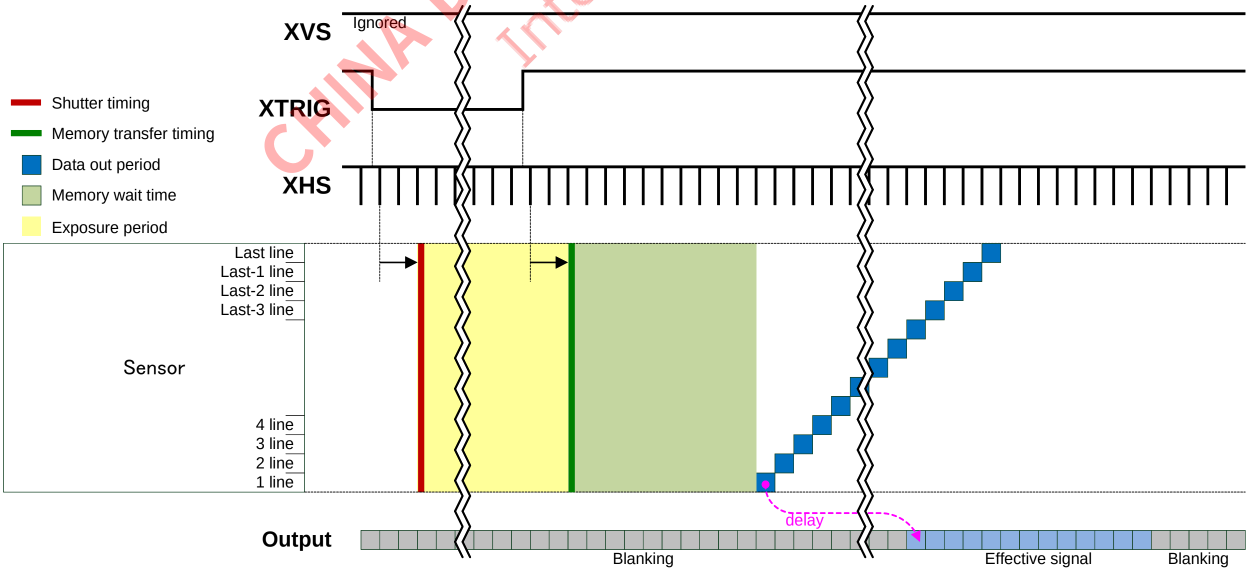

Image Drawing of Global Shutter (Sequential Trigger mode) Operation

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Global Shutter (Normal Mode) Operation

The integration time can be controlled by varying the electronic shutter timing. In the electronic shutter settings, the integration time is controlled by the SHS [19:0] register. For setting value of SHS [19:0], see the table "List of Exposure Setting". When the sensor is operating in slave mode, the number of lines per frame is determined by the XVS interval (number of lines), using the input XHS interval as the line unit. When the sensor is operating in master mode, the number of lines per frame is determined by the VMAX [19:0] register. The number of lines per frame differs according to the operating mode.

Calculation Formula of Exposure Time

Exposure time [s] = (1 H period) × (Number of lines per frame - SHS) + 14.26 [μs]*1

*1: Exposure time error (t_{OFFSET})

Register List of Shutter setting

Register	Register details			Initial value	Setting value
	Chip ID	Address ( ) : I^2C	bit		
VMAX [19:0]	02h	10h (3010h)	[7:0]	0046Ah	Set the number of lines per frame (only in master mode)
		11h (3011h)	[7:0]		
		12h (3012h)	[3:0]		
SHS [19:0]		8Dh (308Dh)	[7:0]	0000Eh	Sets the shutter sweep time. memory wait time to (Number of lines per frame - 1)
		8Eh (308Eh)	[7:0]		
		8Fh (308Fh)	[3:0]		

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List of Exposure Setting

Drive mode	memory wait time [H]	Number of lines per frame [DEC]	SHS Setting value [DEC]	Exposure Setting value [H]	8 ch LVDS / Maximum frame rate					
					Frame rate [frame/s]			Actually exposure [ms][*4]		
					8 bit	10 bit	12 bit	8 bit	10 bit	12 bit
All-pixel	14	1130	1129	1	276.0	226.5	165.9	0.017	0.018	0.020
			1128	2				0.021	0.022	0.025
			…	…				…	…	…
			15	1115				3.588	4.369	5.961
			14	1116				3.591	4.373	5.966
ROI Overlap ROI	14	V_{TR}[*1]	V_{TR}-1	1	*2			0.017	0.018	0.020
			V_{TR}-2	2				0.021	0.022	0.025
			…	…				…		
			15	V_{TR}-15				*3		
			14	V_{TR}-14						

*1 V_{TR} = ROIWV1 + ROIWV2 + 42
*2 For the frame rate, see the section “ROI mode” in “Readout Drive Mode”.
*3 Conform to the calculation formula of exposure time. (Number of lines per frame = V_{TR})
*4 INCK frequency is input by typical value, and t_{OFFSET} (14.26 [μs]) is included.

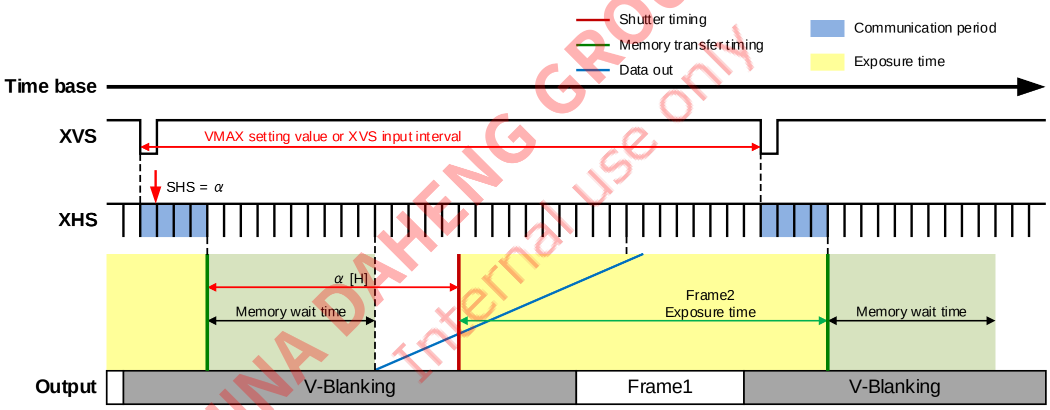

Image Drawing of Global Shutter (Normal Mode)

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Global Shutter (Sequential Trigger Mode) Operation

The integration time can be controlled by varying the pulse width that is input to XTRIG pin. The pulse width designated in XHS unit [H]. For the transition from normal mode to trigger mode, set 1 to the register TRIGEN. The XVS input signal is ignored during trigger mode operating. In case of inputting trigger continuously, there are period which prohibit the trigger rise input (t_{TGPD}) and fall input (t_{TGES}) based on the previous trigger rise. When the trigger rise is input before the rise input prohibited period (t_{TGPD}), interrupt operation starts.
This function is slave mode only. The number of lines per frame differs according to the operating mode.

Calculation Formula of Exposure Time

Exposure time [s] = (XTRIG low level pulse width [H][*2]) + 14.26 [μs][*1]

[*1]: Exposure time error (t_{OFFSET})

[*2]: Low level pulse width is counted by XHS pulse.

Register List of shutter setting

Register	Register details			Initial value	Setting value
	Chip ID	Address ( ) : I²C	bit		
XMSTA	02h	0Ah (300Ah)	[0]	1h	Setting of master mode operation 0: Master mode operation start 1: Master mode operation stop
TRIGEN	02h	0Bh (300Bh)	[0]	0h	0h: Global shutter (normal mode) 1h: Global shutter (trigger mode)
VINT_EN	02h	AAh (30AAh)	[0]	1h	Setting of Interrupt mode in Trigger Mode 0: V interrupt is disable 1: V interrupt is enable

Parameter List of Global Shutter (Sequential Trigger Mode)

Item	Symbol	Min.	Typ.	Max.	Unit
Integration start delay	t_{TGST}	2	—	3	H
Integration end delay	t_{TGED}	2 + t_{OFFSET}	—	3 + t_{OFFSET}	H
Pulse width	t_{TGSE}	1	—	—	H
Next trigger fall prohibited period (All-pixel, ROI, 1/2 Subsampling)	t_{TGES}	17	—	—	H
Next trigger rise prohibited period (All-pixel)	t_{TGPD}	1130	—	—	H
Next trigger rise prohibited period (1/2 Subsampling)		586	—	—	
Next trigger rise prohibited period (ROI)		V_{TR}[*1]	—	—	
Data output delay (All-pixel / ROI)	t_{TGDLY}	—	29	—	H

[*1] V_{TR} = ROIWV1 + ROIWV2 + 42

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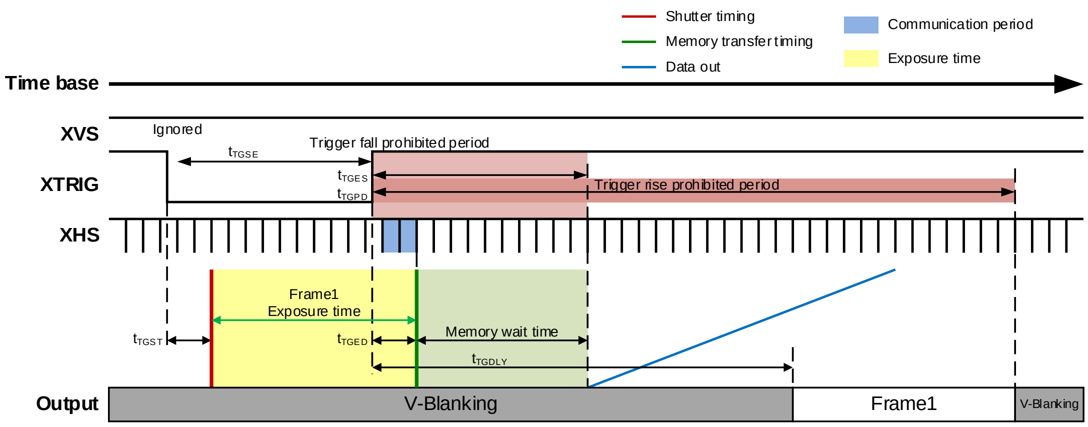

Image Drawing of Global Shutter (Sequential Trigger Mode)

Interrupt Operation

In case of VINT_EN = 1h, the image drawing when the interrupt operation is generated is shown below. When the trigger is raised again and the next frame is output during read of the frame for which read was started by a trigger rise (Frame 1 in the figure below), Frame 1 becomes an invalid frame. Trigger timing of interrupt generating corresponds to t_{TGPD} in Parameter List of Global Shutter (Trigger Mode)
In case of VINT_EN = 0h, both of the rising edge and the falling edge of the trigger signal are ignored in t_{TGPD} (Prohibit period).

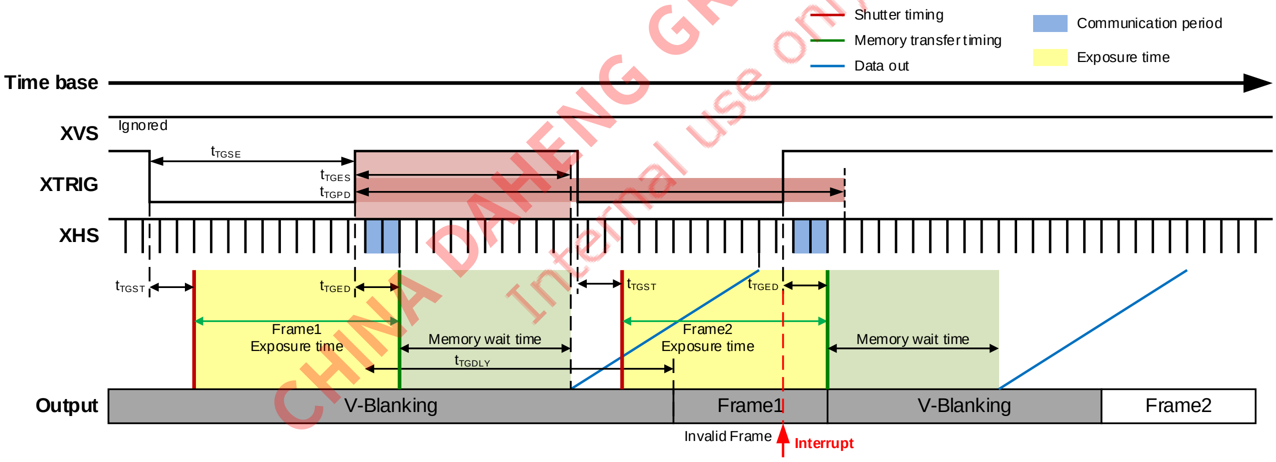

Image Drawing of Interrupt Operation in Global Shutter (Sequential Trigger Mode)

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Global Shutter (Fast Trigger Mode) Operation

Fast trigger mode is the trigger mode that starts exposure at fall of XTRIG immediately.
This mode supports Master mode only.

Calculation Formula of Exposure Time

Exposure time [s] = (XTRIG low level pulse width [μs]) + 14.26 [μs][*1]
[*1]: Exposure time error (t_{OFFSET})

Register List of shutter setting

Register	Register details			Initial value	Setting value
	Chip ID	Address ( ) : I²C	bit		
XMSTA	02h	0Ah (300Ah)	[0]	1h	Setting of master mode operation 0: Master mode operation start 1: Master mode operation stop
TRIGEN		0Bh (300Bh)	[0]	0h	0h: Global shutter (normal mode) 1h: Global shutter (trigger mode)
SYNCSEL		36h (3036h)	[5:4]	0h	XHS, XVS pin setting 0h: Normal Output 3h: Hi-Z
LOWLAGTRG		AEh (30AEh)	[0]	0h	Selection of trigger mode 0: Except for Fast trigger mode 1: Fast trigger mode

Parameter List of Global Shutter (Fast Trigger Mode)

Item	Symbol	Min.	Typ.	Max.	Unit
Integration start delay	t_{TGST}	—	—	0.05	μs
Integration end delay	t_{TGED}	—	—	0.05 + t_{OFFSET}	μs
Pulse width	t_{TGSE}	0.05	—	—	μs
Next trigger rise / fall prohibited period (All-pixel)	t_{TGPD}	1142	—	—	H
Next trigger rise / fall prohibited period (1/2 Subsampling)		598			
Next trigger rise / fall prohibited period (ROI)		V_{TR} [*1]	—	—	
Data output delay (All-pixel / ROI)	t_{TGDLY}	—	29	—	H

[*1] V_{TR} = ROIWV1 + ROIWV2 + 54

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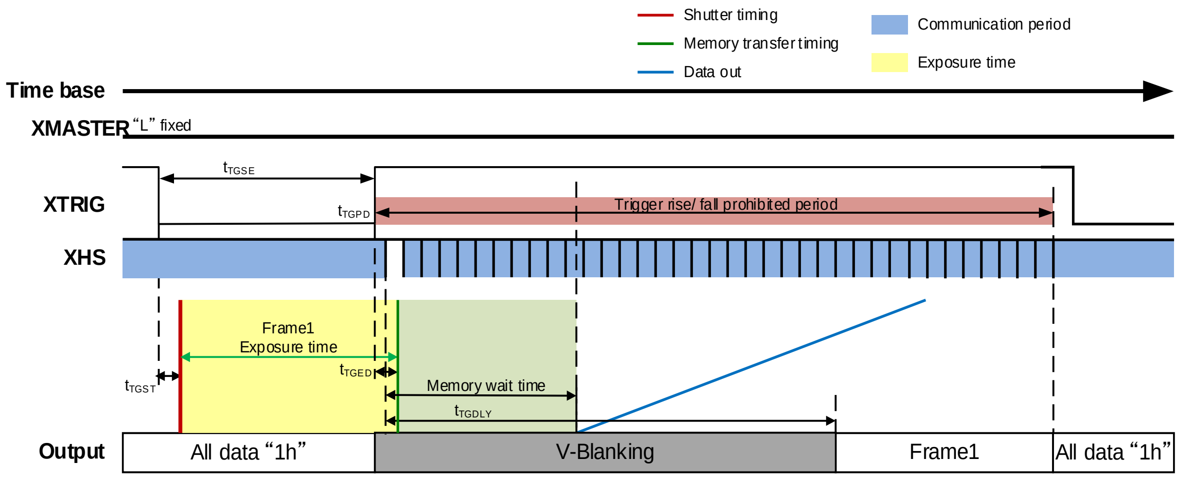

Image Drawing of Global Shutter (Fast Trigger Mode) (4-wire)

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Mode Transitions of Global Shutter Operation

The sensor can be switched between normal mode and trigger mode in global shutter operation by setting the register TRIGEN. The sensor will transition to normal mode or trigger mode 14H after the register TRIGEN is set. (The XVS and XTRIG input during transition are prohibited.)
In case of Fast Trigger mode, the mode transition must be done via sensor standby.

Transition from Normal Mode to Sequential Trigger Mode

The sensor will transition from normal mode to trigger mode after setting 1d to register TRIGEN. The XVS input is ignored after transition to trigger mode. Trigger input is prohibited for a 14H period after the register TRIGEN is set. When TRIGEN is set during data read, read operation is stopped and that frame becomes an invalid frame.
* The communication is available till 9 H period only when sensor transition to the Trigger mode.

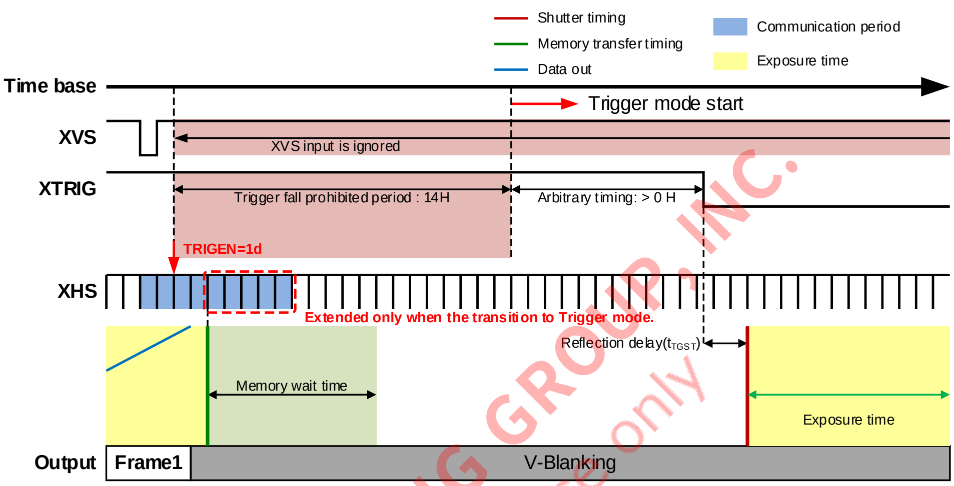

Image Drawing of Transition from Normal Mode to Sequential Trigger Mode

Transition from Sequential Trigger Mode to Normal Mode

The sensor will transition from trigger mode to normal mode after setting 0d to register TRIGEN. Start XVS input after transition to normal mode. Set TRIGEN after Next trigger rise prohibited period (t_{TGPD}) has passed. When TRIGEN is set before t_{TGPD}, read operation is stopped and that frame becomes an invalid frame.

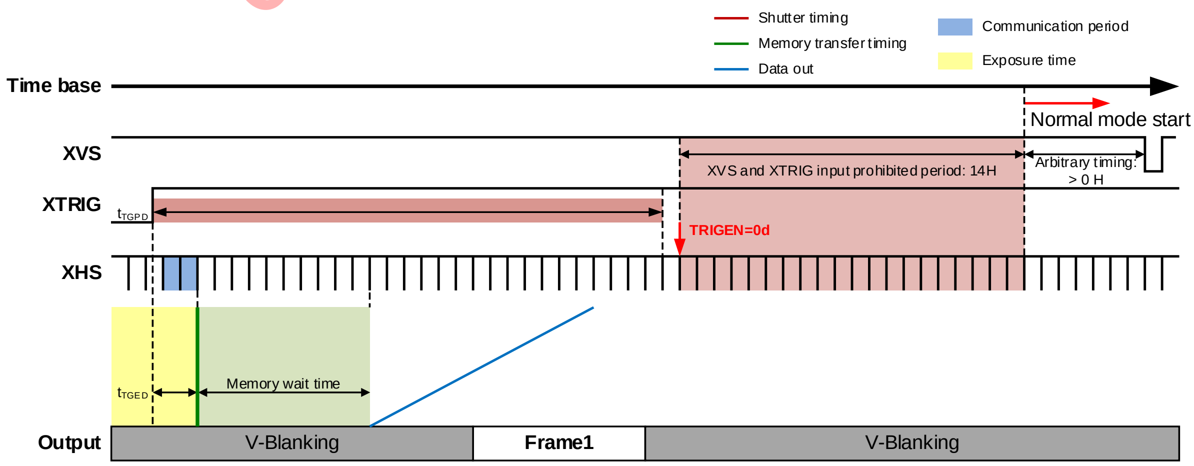

Image Drawing of Transition from Sequential Trigger Mode to Normal Mode

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Pulse Output Function

This sensor has a pulse output function that indicates each state of shutter operation. The pulse output from TOUT1 pin and TOUT2 pin. The rise timing and fall timing of pulse are set by Register. For the reference point (The timing when register value set to 0) to be set, see the table "List of Reference point". The pulse is output asynchronously with other signals on the basis of the sensor internal timing shown in the "List of Reference point". This function doesn't support Fast Trigger mode.

Register List of Pulse Output Function

Register	Register details: Chip ID	Register details: Address ( ) : I^2C	Register details: bit	Initial value	Setting value
TOUT1SEL [1:0]	02h	26h (3026h)	[1:0]	0h	TOUT1 pin setting 0h: Low fixed 3h: Pulse output
TOUT2SEL [1:0]			[3:2]	0h	TOUT2 pin setting 0h: Low fixed 3h: Pulse output
TRIG_TOUT1_SEL [2:0]		29h (3029h)	[2:0]	0h	TOUT1 pin output selection 0h: Low fixed 1h: Pulse1 output
TRIG_TOUT2_SEL [2:0]			[6:4]	0h	TOUT2 pin output selection 0h: Low fixed 2h: Pulse2 output
PULSE1_EN_NOR		6Dh (306Dh)	[0]	0	Pulse1 enable in normal mode 0: disable 1: enable
PULSE1_EN_TRIG			[1]	0	Pulse1 enable in trigger mode 0: disable 1: enable
PULSE1_POL			[2]	0	Pulse1 polarity selection 0: High active 1: Low active
PULSE1_UP [19:0]		70h (3070h)	[7:0]	00000h	Pulse1 active period start timing setting Designated in line units from reference point
		71h (3071h)	[7:0]		
		72h (3072h)	[3:0]		
PULSE1_DN [19:0]		74h (3074h)	[7:0]	00000h	Pulse1 active period end timing setting Designated in line units from reference point
		75h (3075h)	[7:0]		
		76h (3076h)	[3:0]		
PULSE2_EN_NOR		79h (3079h)	[0]	0	Pulse2 enable in normal mode 0: disable 1: enable
PULSE2_EN_TRIG			[1]	0	Pulse2 enable in trigger mode 0: disable 1: enable
PULSE2_POL			[2]	0	Pulse2 polarity selection 0: High active 1: Low active
			[3]	0	Fixed to 1
PULSE2_UP [19:0]		7Ch (307Ch)	[7:0]	00000h	Pulse2 active period start timing setting Designated in line units from reference point
		7Dh (307Dh)	[7:0]		
		7Eh (307Eh)	[3:0]		
PULSE2_DN [19:0]		80h (3080h)	[7:0]	00000h	Pulse2 active period end timing setting Designated in line units from reference point
		81h (3081h)	[7:0]		
		82h (3082h)	[3:0]		

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List of Reference Point

	Normal mode	Trigger mode
Reference point of Pulse1	XVS fall edge in N frame	Fall edge of input trigger
Reference point of Pulse2	XVS fall edge in N +1 frame	Rise edge of input trigger

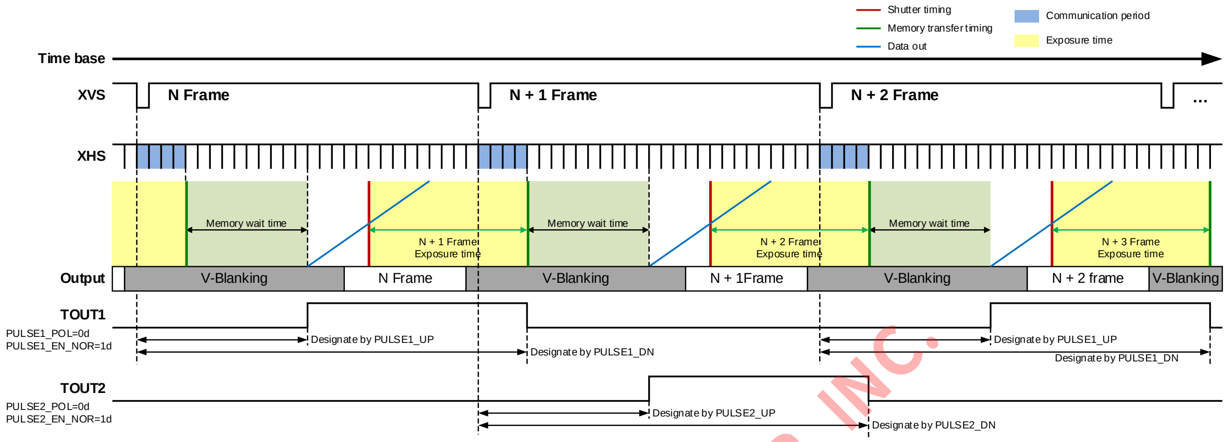

Image Drawing of Pulse Output Function in Global Shutter (Normal Mode)

In normal mode, TOUT1 and TOUT2 are output alternately each time inputting XVS.

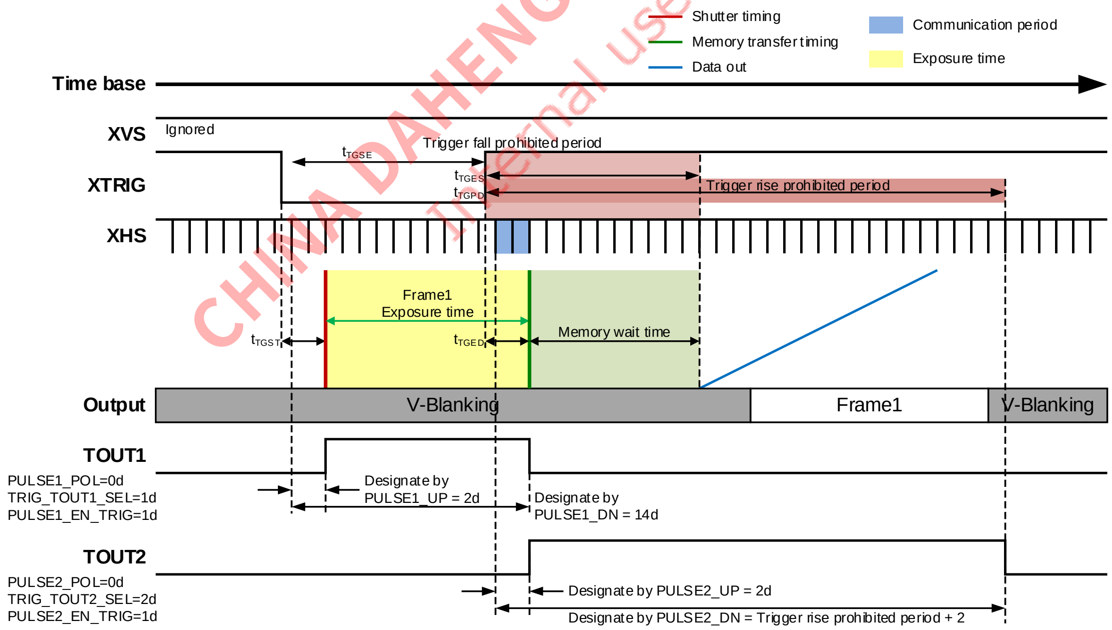

Image Drawing of Pulse Output Function in Global Shutter (Sequential Trigger Mode)

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Signal Output

Output Pin Settings

This sensor supports Low voltage LVDS serial (2 ch / 4 ch / 8 ch switching) DDR output.
In addition, the data rate per channel is adjustable. The table below shows the output format settings.

Register List of Output Settings

Register	Register details			Initial value	Setting value
	Chip ID	Address ( ) : I^2C	bit		
STBLVDS [3:0]	02h	05h (3005h)	[7:4]	0h	The un-using LVDS channel go into standby
FREQ [1:0]		1Bh (301Bh)	[1:0]	0h	Frame rate adjust
OPORTSEL [3:0]		1Ch (301Ch)	[7:4]	1h	Output channel selection (Refer the list of output setting below)

Output Pins for Low Voltage LVDS Serial

Output pins	Low voltage LVDS serial DDR output		
	2 ch	4 ch	8 ch
DLOPA1 / DLOMA1	Hi-Z	Hi-Z	Ch 7
DLOPB1 / DLOMB1	Hi-Z	Hi-Z	Ch 5
DLOPC1 / DLOMC1	Hi-Z	Ch 3	Ch 3
DLOPD1 / DLOMD1	Ch 1	Ch 1	Ch 1
DLOPE1 / DLOME1	Ch 2	Ch 2	Ch 2
DLOPF1 / DLOMF1	Hi-Z	Ch 4	Ch 4
DLOPG1 / DLOMG1	Hi-Z	Hi-Z	Ch 6
DLOPH1 / DLOMH1	Hi-Z	Hi-Z	Ch 8
DLCKP1 / DLCKM1	DCK1	DCK1	DCK1

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Low-voltage LVDS serial 2 ch / 4 ch / 8 ch output format is shown in the figure below.

When setting 2 ch, after four data of SAV is output in the order of CH1 to CH2 pixel data is repeatedly output in the same order and then four data of EAV is output in the same order to CH1 to CH2 respectively.

When setting 4 ch, after four data of SAV is output in the order of CH1 to CH4 pixel data is repeatedly output in the same order and then four data of EAV is output in the same order to CH1 to CH4 respectively.

When setting 8 ch, output in a format similar to the 2 ch and 4 ch output as shown below.

Data is sent MSB first. For details, see drive timing in each mode in the section of "Readout Drive Mode".

Output Format of Low voltage LVDS Serial 2 ch / 4 ch / 8 ch

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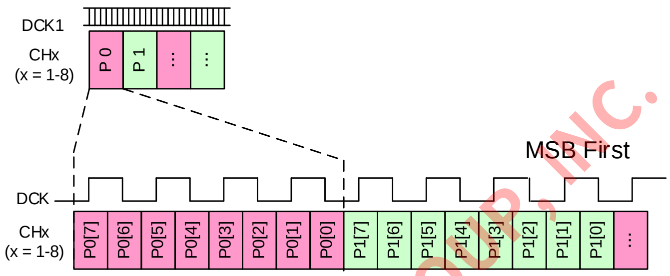
Output Pin Bit Width Selection

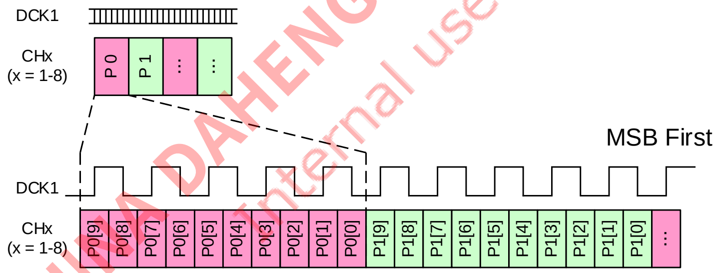
The output pin width can be selected from 8-bit, 10-bit or 12-bit output using register ADBIT, ODBIT. Sync code is output according to bit width setting of these register.

Register List of Bit Width Selection

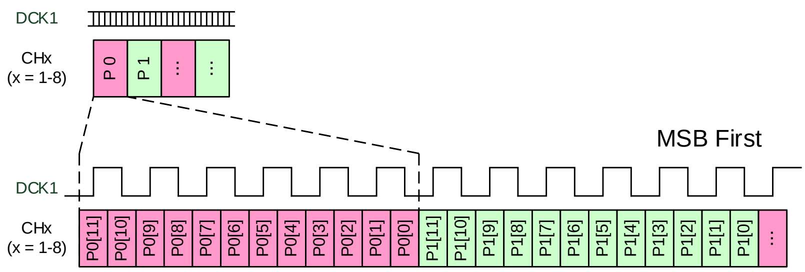
Register	Register details			Initial value	Setting value	Remarks
	Chip ID	Address ( ) : I²C	bit			
ADBIT	02h	0Ch (300Ch)	[1:0]	0h	0h: 10 bit 1h: 12 bit 2h: 8 bit	Set same value to both ADBIT and ODBIT
ODBIT		16h (3016h)	[1:0]	0h	0h: 10 bit 1h: 12 bit 2h: 8 bit	



Example of Data format in low-voltage LVDS serial 8-bit output



Example of Data format in low-voltage LVDS serial 10-bit output



Example of Data format in low-voltage LVDS serial 12-bit output

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Output Signal Range

The sensor output has either a 8-bit or 10-bit or 12-bit gradation, but output is not performed over the full range, and the maximum output value is the “FFh – 1” (8-bit output), the “3FFh - 1” (10-bit output) and the “FFFh - 1” (12-bit output). The minimum value is 001h. The output range for each output gradation is shown in the table below. The maximum level and the minimum level are output only in the sync code. See the item of “Sync Codes” in the section of “Operating Modes” for the sync codes.

Output Gradation and Output Range

Output gradation	Output value	
	Min.	Max.
8 bit	01h	FEh
10 bit	001h	3FEh
12 bit	001h	FFEh

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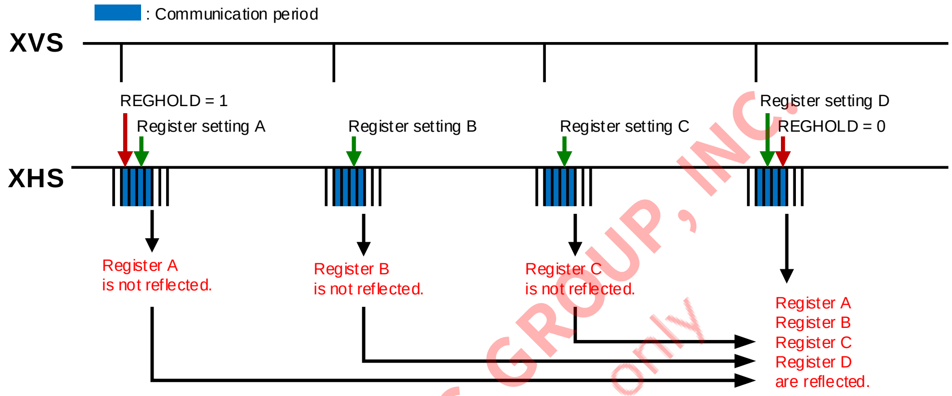
Register Hold Setting

Register setting can be transmitted with divided to several frames and it can be reflected globally at a certain frame by the register REGHOLD. Setting REGHOLD = 1 at the start of register communication period prevents the registers that are set thereafter from reflecting at the frame reflection timing. The registers that are set when setting REGHOLD = 1 are reflected globally by setting REGHOLD = 0 at the end of communication period of the desired frame to reflect the register.

Register List of Register Hold

Register	Register details			Initial value	Setting value
	Chip ID	Address ( ) : I^{2}C	bit		
REGHOLD	02h	08h (3008h)	[0]	0h	0h: Invalid 1h: Valid (Register hold)



Register Hold Setting

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Mode Transition

The Mode transition between operations is shown below. These examples shown in case that setting is completed within one communication timing.

List of Mode Transition

Transition			State
ROI	→	All-pixel	Via the Standby state is unnecessary
All-pixel	→	ROI	
- Transition between modes other than the above - Change the input frequency of INCK [*1] - Change the register setting noted “S” in the reflection timing column of the Register Map.			Via the standby state is necessary

[*1] When changing input INCK frequency, care should be taken not to be input pulses whose width are shorter than the High / Low level width in front and behind of the INCK pulse at the frequency change. If the pulses above generate at the frequency change, change INCK frequency during system reset in the state of XCLR = Low, and then perform system clear in the state of XCLR = High following the item of "Power on sequence" in the section of "Power on / off sequence". Execute initial setting again because the register settings become default state after system clear.

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Other Function

This sensor has the function as below. About detail, refer to each application note.

- Multi Frame Set Output mode (2 / 4 frame)
- Multi Exposure Trigger mode
- Multi Frame ROI (Multi Exposure + ROI) mode
- Driving Low Power Consumption at longtime exposure
- Simple Thermometer
- Gradation Compression
- Pattern Generator (Refer to Support Package)
- Additional Function of Synchronizing Sensors

Extension Function

Use these function after enough checks and evaluation.

- Black Level Auto Adjust Off
- Short Exposure Mode

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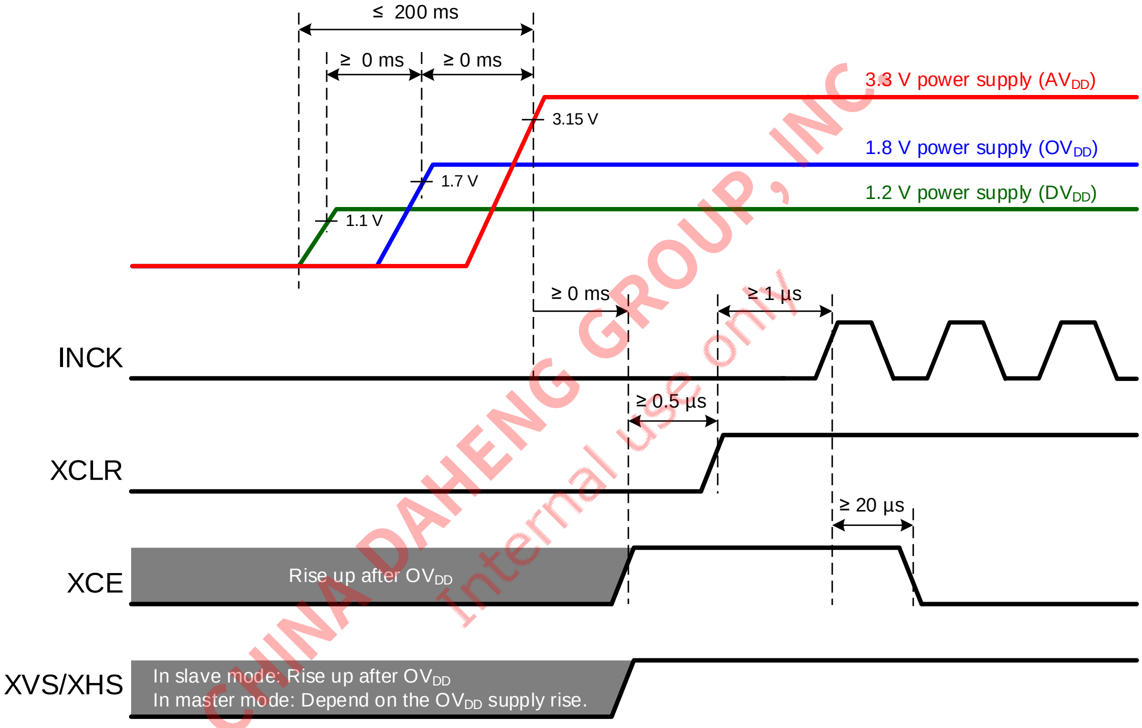
Power-on and Power-off Sequence

Power-on sequence

Follow the sequence below to turn On the power supplies.

1. Turn On the power supplies so that the power supplies rise in order of 1.2 V power supply (DV_{DD}) →1.8 V power supply (OV_{DD}) → 3.3 V power supply (AV_{DD}). In addition, all power supplies should finish rising within 200 ms.
2. The register values are undefined immediately after power-on, so the system must be cleared. Hold XCLR at Low level for 500 ns or more after all the power supplies have finished rising. (The register values after a system clear are the default values.)
   In addition, hold XCE to High level during this period. Rise XCE after 1.8 V power supply (OV_{DD}), so hold XCE at High level until INCK is input.
3. Start the input of INCK after turning the level of XCLR into the high.
4. Make the sensor setting by register communication after the system clear. A period of 0 µs or more should be provided after setting XCLR High before inputting the communication enable signal XCE.



Power-on Sequence

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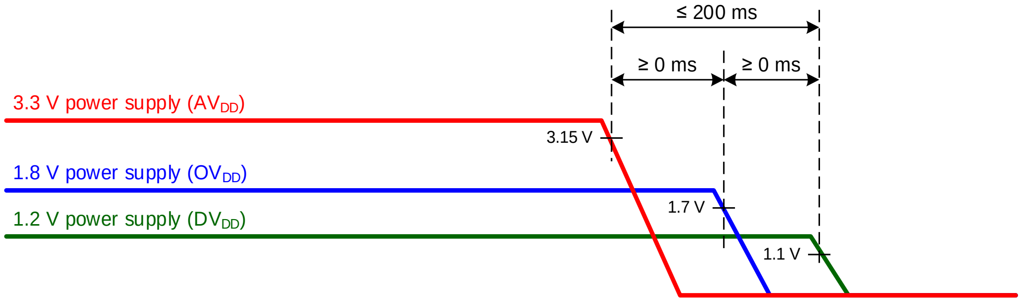
Power-off Sequence

Turn Off the power supplies so that the power supplies fall in order of 3.3 V power supply (AV_{DD}) → 1.8 V power supply (OV_{DD}) → 1.2 V power supply (DV_{DD}). In addition, all power supplies should finish falling within 200 ms.
Set each digital input pin (INCK, XCE, SCK, SDI, XCLR, XMASTER, XTRIG, SLAMODE, XVS, XHS) to 0 V or high impedance before the 1.8 V power supply (OV_{DD}) falls.



Power-off Sequence

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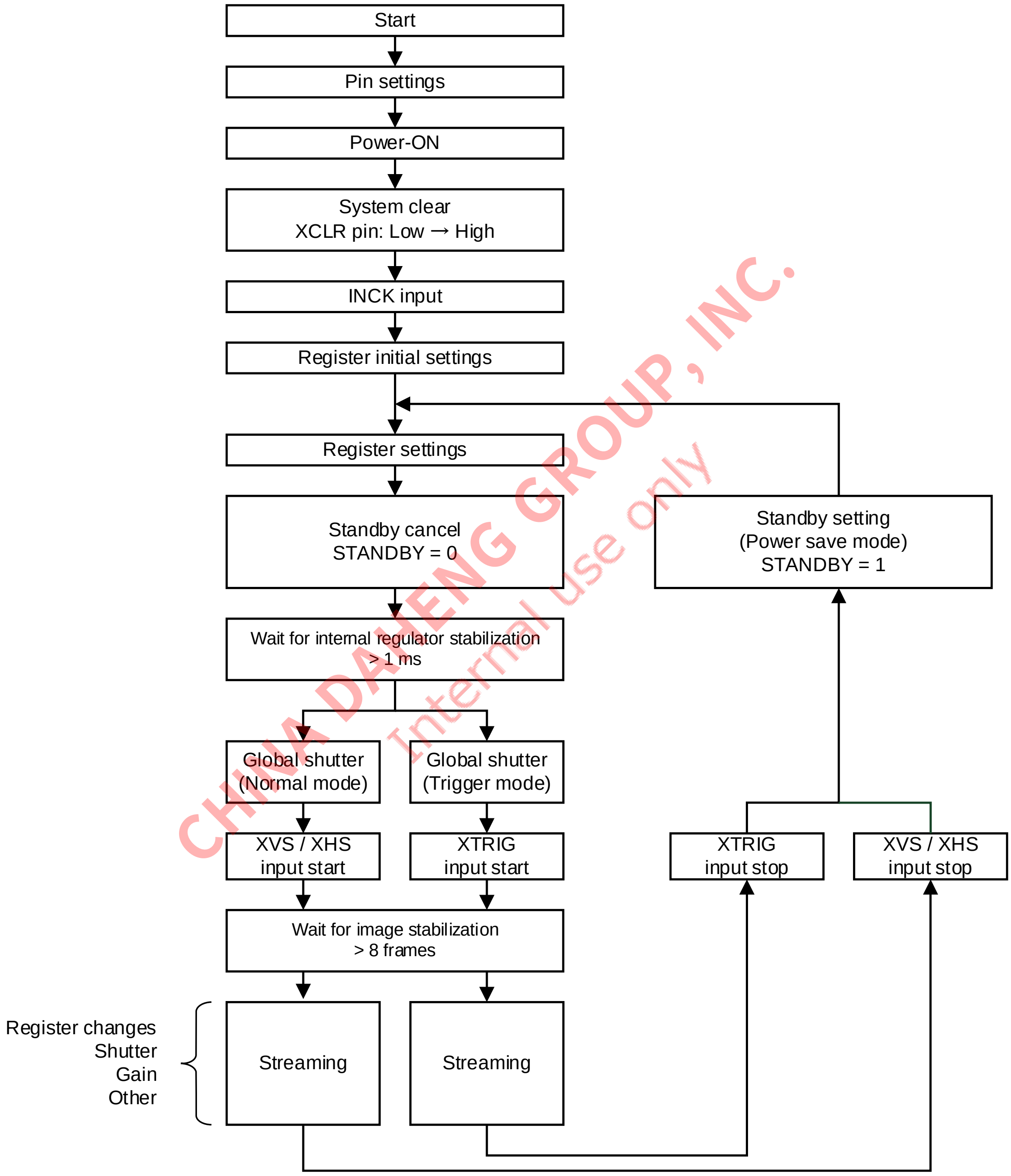
Sensor Setting Flow

Setting Flow in Sensor Slave Mode

The figure below shows operating flow in sensor slave mode.
For details of "Power on" to "System clear", see the item of "Power on sequence" in this section. For details of "Standby cancel" to "Wait for image stabilization", see the item of "Standby mode". “Standby setting (power save mode) can be made by setting the STANDBY register to “1” during “Operation”.



Sensor Setting Flow (Sensor Slave Mode)

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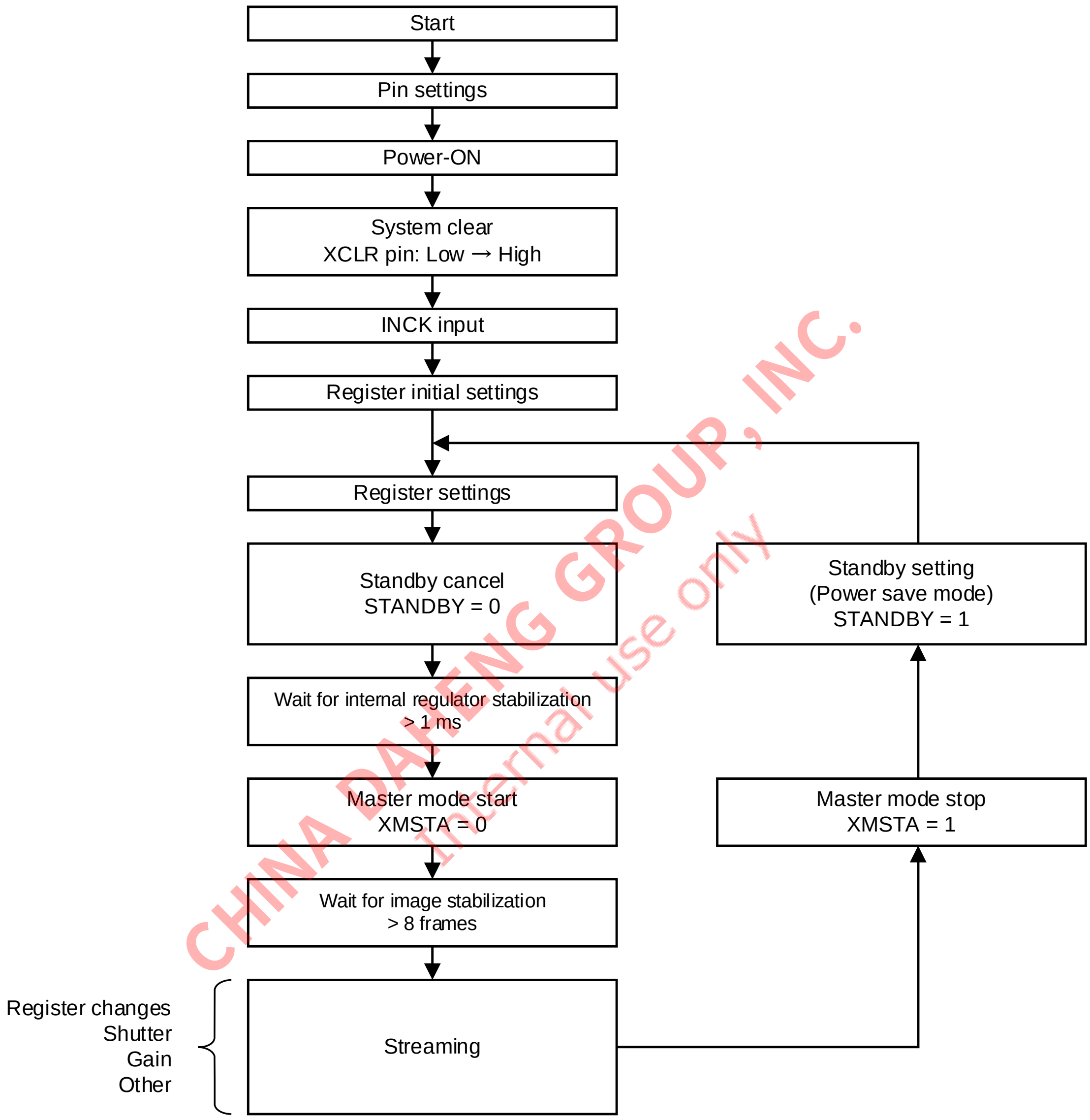
Setting Flow in Sensor Master Mode

The figure below shows operating flow in sensor master mode.
For details of "Power on" to "System clear", see the item of "Power on sequence" in this section. For details of "Standby cancel" to "Wait for image stabilization", see the item of "Standby mode". In master mode, “Master mode start” by setting the master mode start register XMSTA to “0” after “Wait for internal regulator stabilization”. “Standby setting (power save mode) can be made by setting the STANDBY register to “1” during “Operation”. This time, set "master mode stop" by setting XMSTA to "1".



Sensor Setting Flow (Sensor Master Mode)

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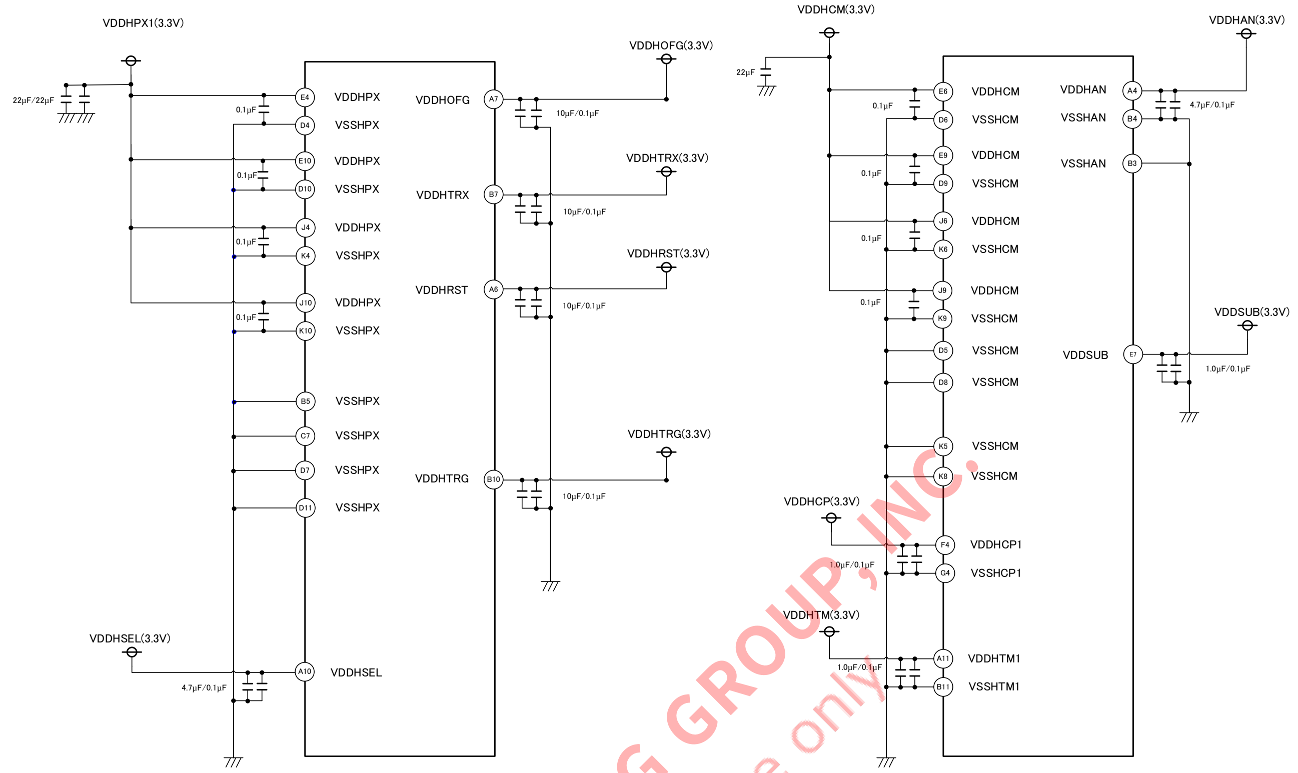
Peripheral Circuit

Analog Power Pins



Application circuits shown are typical examples illustrating the operation of the devices. Sony Semiconductor Solutions Corporation cannot assume responsibility for any problems arising out of the use of these circuits or for any infringement of third party and other right due to same.

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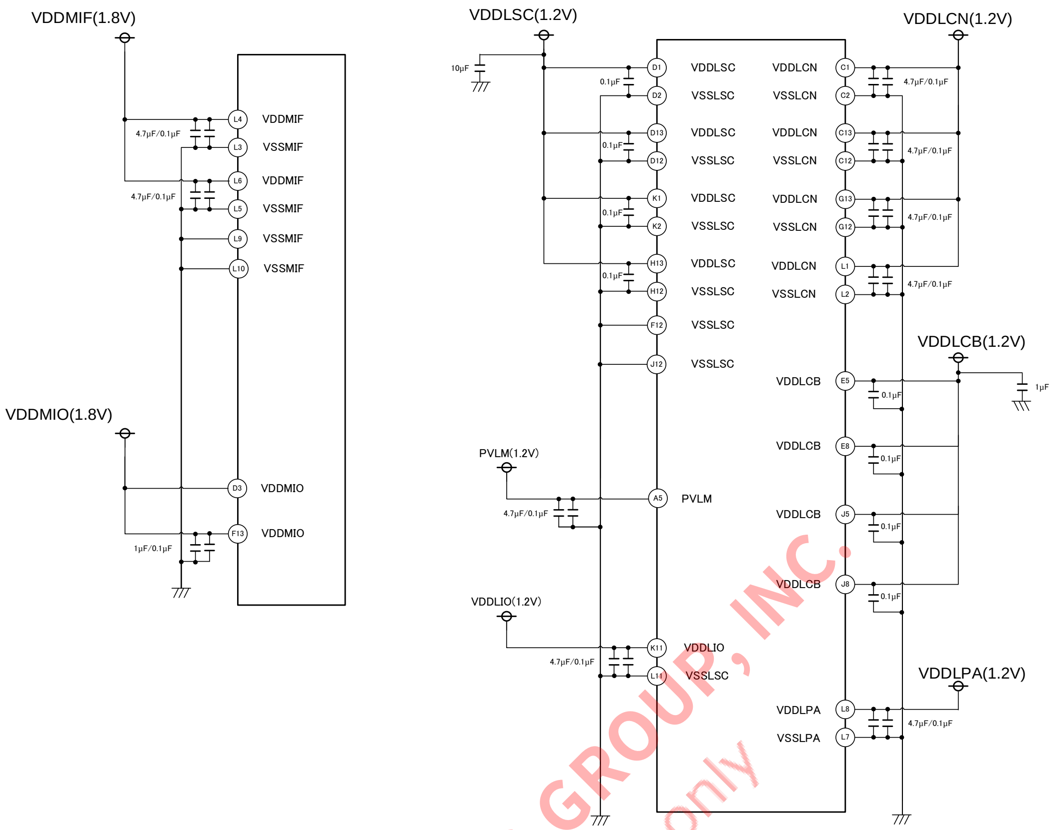
Digital Power Pins



Pin D3 is power pin, but this pin isn't affected by noise and it is no problem that it is connected without capacitor.

Pin E5, E8, J5, and J8 are analog power pins. But these pins can be connected to the digital power pins.
So, it describe on this page. These pins can be separated from the digital power pins.

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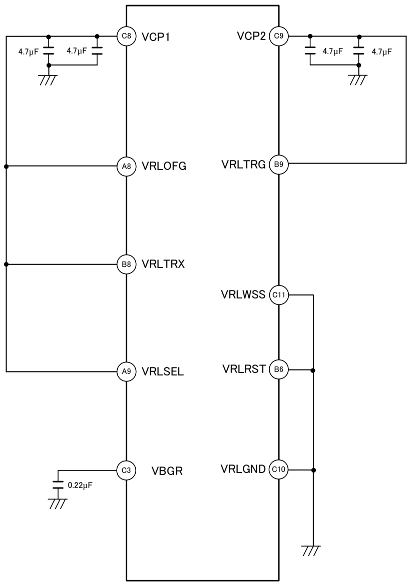
Analog Other Pins



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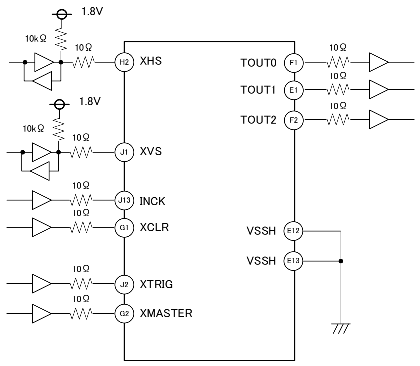
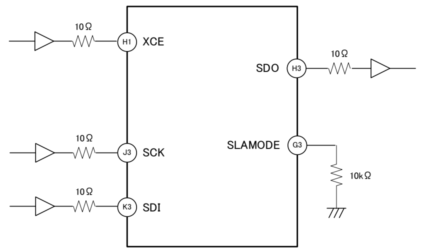
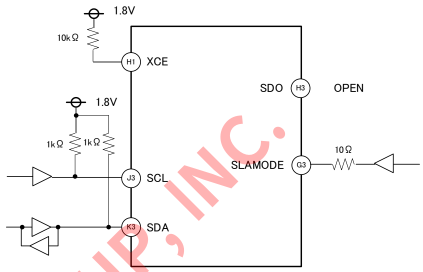
Digital I/O Pins



4-wire serial communication



I²C communication



Pin E12, E13 are 3.3 V GND. But, these pins are I/O terminal GND. So, these pins describe on this page.

Application circuits shown are typical examples illustrating the operation of the devices. Sony Semiconductor Solutions Corporation cannot assume responsibility for any problems arising out of the use of these circuits or for any infringement of third party and other right due to same.

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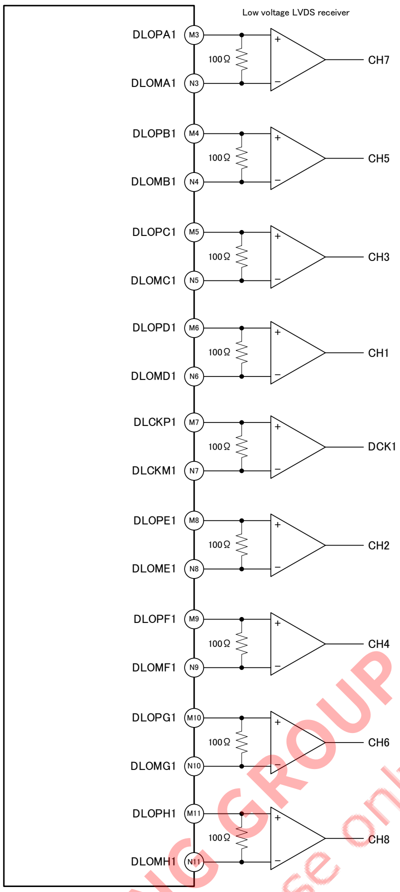
Output pins



Application circuits shown are typical examples illustrating the operation of the devices. Sony Semiconductor Solutions Corporation cannot assume responsibility for any problems arising out of the use of these circuits or for any infringement of third party and other right due to same.

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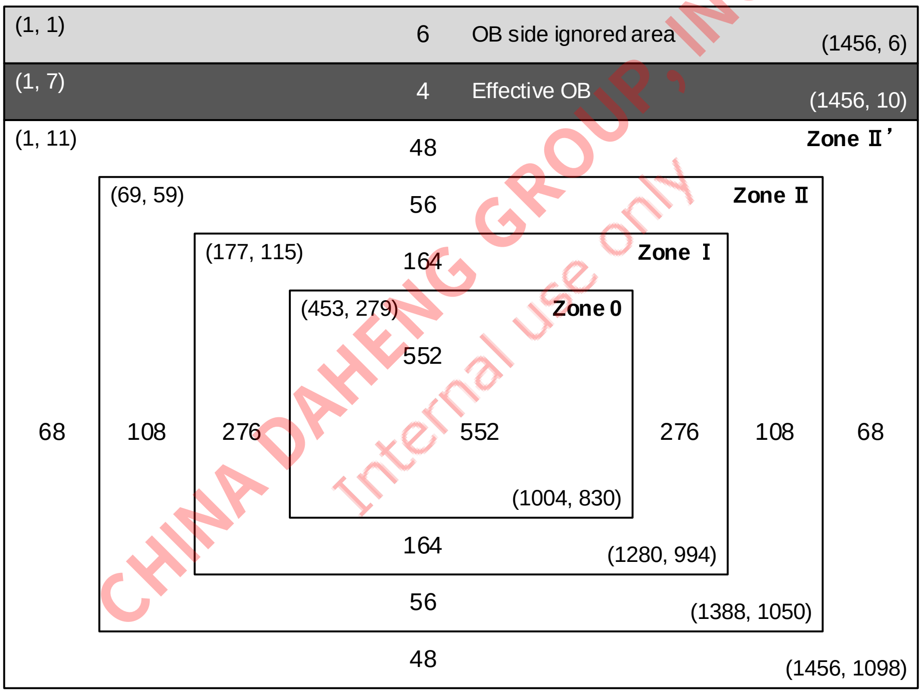
Spot Pixel Specifications

(Tj = 60 ˚C)

Type of distortion	Level	Maximum distorted pixels in each zone			Measurement method	Remarks
		0 to II'	Effective OB	Ineffective OB		
Black and white pixels at high light	30 % ≤ D	12	No evaluation criteria applied		1	
White pixels in the dark	5.6 mV ≤ D	137		No evaluation criteria applied	2	1/30 s storage
Black pixels at signal saturated	D ≤ 700mV	0	No evaluation criteria applied		3	

Note) 1. Zone is specified based on all-pixel drive mode
2. D…Spot pixel level
3. See the Spot Pixel Pattern Specifications for the specifications in which pixel and black pixel are close.

Sport Pixel Zone Definition



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Notice on White Pixels Specifications

After delivery inspection of CMOS image sensors, cosmic radiation may distort pixels of CMOS image sensors, and then distorted pixels may cause white point effects in dark signals in picture images. (Such white point effects shall be hereinafter referred to as "White Pixels".) Unfortunately, it is not possible with current scientific technology for CMOS image sensors to prevent such White Pixels. It is recommended that when you use CMOS image sensors, you should consider taking measures against such White Pixels, such as adoption of automatic compensation systems for White Pixels in dark signals and establishment of quality assurance standards.
Unless the Seller's liability for White Pixels is otherwise set forth in an agreement between you and the Seller, Sony Semiconductor Solutions Corporation or its distributors (hereinafter collectively referred to as the "Seller") will, at the Seller's expense, replace such CMOS image sensors, in the event the CMOS image sensors delivered by the Seller are found to be to the Seller's satisfaction, to have over the allowable range of White Pixels as set forth above under the heading "Spot Pixels Specifications", within the period of three months after the delivery date of such CMOS image sensors from the Seller to you; provided that the Seller disclaims and will not assume any liability after you have incorporated such CMOS image sensors into other products.
Please be aware that Seller disclaims and will not assume any liability for (1) CMOS image sensors fabricated, altered or modified after delivery to you, (2) CMOS image sensors incorporated into other products, (3) CMOS image sensors shipped to a third party in any form whatsoever, or (4) CMOS image sensors delivered to you over three months ago. Except the above mentioned replacement by Seller, neither Sony Semiconductor Solutions Corporation nor its distributors will assume any liability for White Pixels. Please resolve any problem or trouble arising from or in connection with White Pixels at your costs and expenses.

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[For Your Reference] The Annual Number of White Pixels Occurrence

The chart below shows the predictable data on the annual number of White Pixels occurrence in a single-story building in Tokyo at an altitude of 0 meters. It is recommended that you should consider taking measures against the annual White Pixels, such as adoption of automatic compensation systems appropriate for each annual number of White Pixels occurrence.
The data in the chart is based on records of past field tests, and signifies estimated number of White Pixels calculated according to structures and electrical properties of each device. Moreover, the data in the chart is for your reference purpose only, and is not to be used as part of any CMOS image sensor specifications.

Example of Annual Number of Occurrence

White Pixel Level (in case of integration time = 1/30 s) (Tj = 60 °C)	Annual number of occurrence
5.6 mV or higher	4 pcs
10.0 mV or higher	2 pcs
24.0 mV or higher	1 pcs
50.0 mV or higher	1 pcs
72.0 mV or higher	1 pcs

Note 1) The above data indicates the number of White Pixels occurrence when a CMOS image sensor is left for a year.

Note 2) The annual number of White Pixels occurrence fluctuates depending on the CMOS image sensor storage environment (such as altitude, geomagnetic latitude and building structure), time (solar activity effects) and so on. Moreover, there may be statistic errors. Please take notice and understand that this is an example of test data with experiments that have being conducted over a specific time period and in a specific environment.

Note 3) This data does not guarantee the upper limits of the number of White Pixels occurrence.

For Your Reference:

The annual number of White Pixels occurrence at an altitude of 3,000 meters is from 5 to 10 times more than that at an altitude of 0 meters because of the density of the cosmic rays. In addition, in high latitude geographical areas such as London and New York, the density of cosmic rays increases due to a difference in the geomagnetic density, so the annual number of White Pixels occurrence in such areas approximately doubles when compared with that in Tokyo.

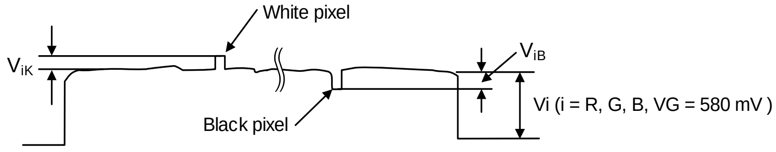
Material_No.03-0.0.9

Measurement Method for Spot Pixels

After setting to standard imaging condition II, and the device driver should be set to meet bias and clock voltage conditions. Configure the drive circuit according to the example and measure.

1. Black or white pixels at high light
   After adjusting the luminous intensity so that the average value VG of the Gb / Gr signal outputs is 580 mV, measure the local dip point (black pixel at high light, V_{iB}) and peak point (white pixel at high light, V_{iK}) in the Gr / Gb / R / B signal output Vi (i = Gr / Gb / R / B), and substitute the value into the following formula.

   Spot pixel level D = ((V_{iB} or V_{iK}) / Average value of Vi) × 100 [%]



Signal output waveform of R / G / B channel

2. White pixels in the dark
   Set the device to a dark setting and measure the local peak point of the signal output waveform, using the average value of the dark signal output as a reference.

3. Black pixels at signal saturated
   Set the device to operate in saturation and measure the local dip point, using the OB output as a reference.

Signal output waveform of R / G / B channel

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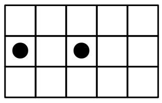
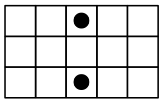
Spot Pixel Pattern Specification

White Pixel, Black Pixel and Bright Pixel are judged from the pattern whether they are allowed or rejected, and counted.

List of White Pixel, Black Pixel and Bright Pixel Pattern

No.	Pattern	White pixel Black pixel Bright pixel
1		Rejected
2		Rejected

Note) 1. "● " shows the position of white pixel, black pixel and bright pixel.
White pixel, black pixel and bright pixel are specified separately according the pattern.
(Example: If a black pixel and a white pixel is in the pattern No.1 respectively, they are not judged to be rejected.)
2. When one or more spot pixels indicated "Rejected" is selected and removed.
3. Spot pixels other than described in the table above are all counted including the number of allowable spot pixels by zone.

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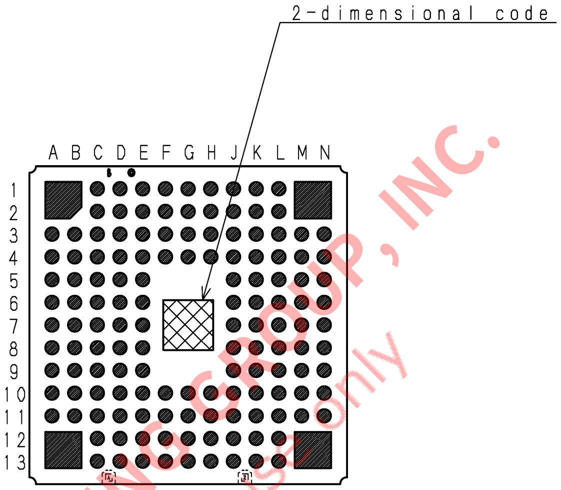
Marking



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Note: Following characters enter into "Y", and "Z". (No Au coat)

Y: In English upper case character, One character

Z: Number, single number

DRAWING No. AM-C273LQR(2D)

Notes On Handling

1. Static charge prevention

Image sensors are easily damaged by static discharge. Before handling be sure to take the following protective measures.

(1) Either handle bare handed or use non-chargeable gloves, clothes or material.
Also use conductive shoes.
(2) Use a wrist strap when handling directly.
(3) Install grounded conductive mats on the floor and working table to prevent the generation of static electricity.
(4) Ionized air is recommended for discharge when handling image sensors.
(5) For the shipment of mounted boards, use boxes treated for the prevention of static charges.

2. Protection from dust and dirt

Image sensors are packed and delivered with care taken to protect the element glass surfaces from harmful dust and dirt. Clean glass surfaces with the following operations as required before use.

(1) Perform all lens assembly and other work in a clean environment (class 1000 or less).
(2) Do not touch the glass surface with hand and make any object contact with it.
If dust or other is stuck to a glass surface, blow it off with an air blower.
(For dust stuck through static electricity, ionized air is recommended.)
(3) Clean with a cotton swab with ethyl alcohol if grease stained. Be careful not to scratch the glass.
(4) Keep in a dedicated case to protect from dust and dirt. To prevent dew condensation, preheat or precool when moving to a room with great temperature differences.
(5) When a protective tape is applied before shipping, remove the tape applied for electrostatic protection just before use. Do not reuse the tape.

3. Installing (attaching)

(1) If a load is applied to the entire surface by a hard component, bending stress may be generated and the package may fracture, etc., depending on the flatness of the bottom of the package. Therefore, for installation, use either an elastic load, such as a spring plate, or an adhesive.
(2) The adhesive may cause the marking on the rear surface to disappear.
(3) If metal, etc., clash or rub against the package surface, the package may chip or fragment and generate dust.
(4) Acrylate anaerobic adhesives are generally used to attach this product. In addition, cyanoacrylate instantaneous adhesives are sometimes used jointly with acrylate anaerobic adhesives to hold the product in place until the adhesive completely hardens. (Reference)
(5) Note that the sensor may be damaged when using ultraviolet ray and infrared laser for mounting it.

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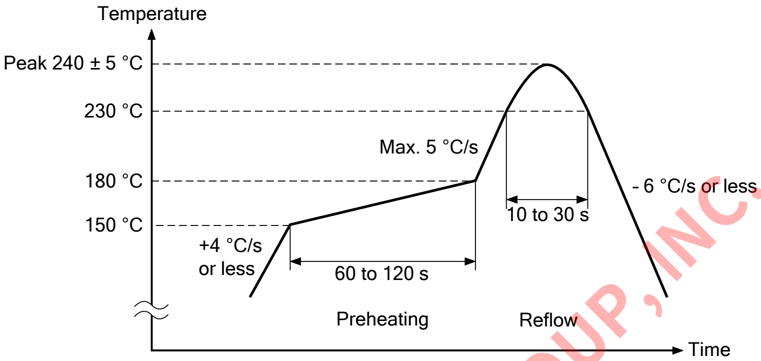
4. Recommended reflow soldering conditions

The following items should be observed for reflow soldering.

(1) Temperature profile for reflow soldering

Control item	Profile (at part side surface)
1. Preheating	150 to 180 °C 60 to 120 s
2. Temperature up (down)	+4 °C/s or less (- 6 °C/s or less)
3. Reflow temperature	Over 230 °C 10 to 30 s Max. 5 °C/s
4. Peak temperature	Max. 240 ± 5 °C



(2) Reflow conditions

(a) Make sure the temperature of the upper surface of the seal glass resin adhesive portion of the package does not exceed 245 °C.

(b) Perform the reflow soldering only one time.

(c) Finish reflow soldering within 72 h after unsealing the degassed packing.
Store the products under the condition of temperature of 30 °C or less and humidity of 70 % RH or less after unsealing the package.

(d) Perform re-baking only one time under the condition at 125 °C for 24 h.

(e) Note that condensation on glass or discoloration on resin interfaces may occur if the actual temperature and time exceed the conditions mentioned above.

(3) Others

(a) Carry out evaluation for the solder joint reliability in your company.

(b) After the reflow, the paste residue of protective tape may remain around the seal glass.
(The paste residue of protective tape should be ignored except remarkable one.)

(c) Note that X-ray inspection may damage characteristics of the sensor.

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5. Others

(1) Do not expose to strong light (sun rays) for long periods, as the color filters of color devices will be discolored.

(2) Exposure to high temperature or humidity will affect the characteristics. Accordingly avoid storage or use in such conditions.

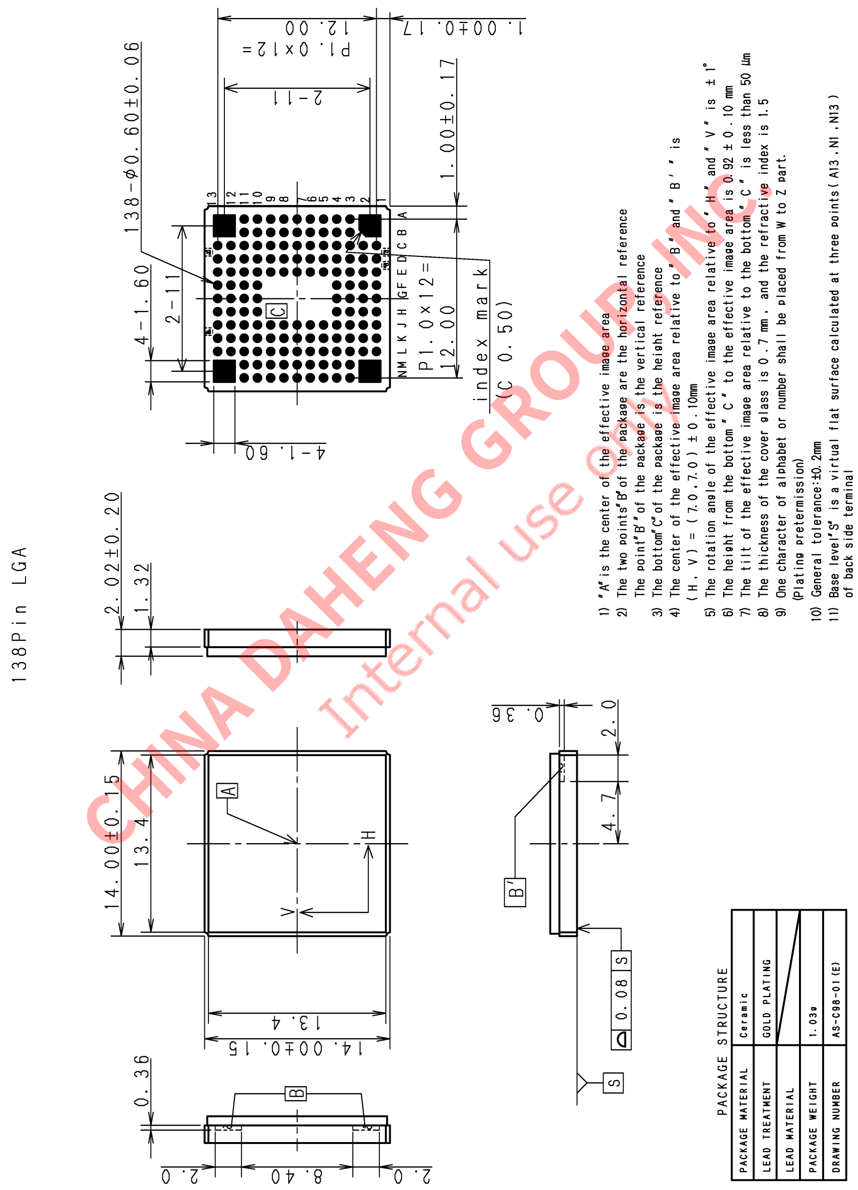
(3) This product is precision optical parts, so care should be taken not to apply excessive mechanical shocks or force.

(4) Note that imaging characteristics of the sensor may be affected when approaching strong electromagnetic wave or magnetic field during operation.

(5) Note that image may be affected by the light leaked to optical black when using an infrared cut filter that has transparency in near infrared ray area during shooting subjects with high luminance.

Package Outline

(Unit: mm)



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List of Trademark Logos and Definition Statements

Pregius

* Pregius is a trademark of Sony Corporation. The Pregius is global shutter pixel technology for active pixel-type CMOS image sensors that use Sony's low-noise CCD structure, and realizes high picture quality.

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Revision History

Date of change	Revision	Page	Contain of Change
28-Oct-16	0.1	—	First edition
9-Dec-16	0.2	12, 28	Correction: Each slave addresses of sensor of I^2C.
		83	Delate: The additional function of saturation in item of other function.
31-Aug-17	E17806	1	Delete : “Preliminary” in the title
		1	Delete : Note of correction concerning each register of data sheet
		7	Update: Optical Center figure
		14	Update: TBD in the table (“DC Characteristics” and “Power Consumption”)
		19	Update: TBD in the table (DLCK, DLO)
		21	Update: Spectral Sensitivity Characteristics figure
		22	Update: TBD in the table (Image Sensor Characteristics)
		24	Update: TBD in the number 2 -4 item in “Measurement Method”
		26, 29	Correction: Communication prohibited period (20XHS => 14XHS)
		33	Delete: Note of correction concerning the register map
		45	Correction: Description of the values of data rate in example of note *1 (4.592 => 4.752)
		57	Correction: Description of width of the window (“Minimum width of the window” => “Minimum output width”) (“Width of no overlap area” => “Minimum horizontal output width”) (“Width of no overlap area ≥ 4d” => “Minimum vertical output width ≥ 4d”) (“without overlap” => “maximum vertical output width ”)
		65 to 67, 69	Update: TBD (t_{OFFSET}) in the page (13.73 (TBD) =>14.26)
		66	Update: The value of the actually exposure in the List of Exposure Setting (t_{OFFSET}:14.26)
		67	Correction: The value of t_{TGPD} in the parameter List (1128 => 1130, 584 => 586)
		68	Correction: Note and the figure of VINT_EN = 0h in Interrupt Operation
		69	Update: TBD in the parameter List
		69	Correction: The value of ROI mode of t_{TGPD} in the parameter List (V_{TR} => V_{TR} + 12)
		71	Correction: Trigger input prohibited period (20H => 14H)
		74	Correction: OPORTSEL [4:0] of the register name in the table ([4:0] => [3:0])
		90	Update: TBD in the table (Spot Pixel Specifications)
		91	Update: TBD in the table (Annual number of white pixels occurrence)
		92	Update: TBD in the page (Measurement method for Spot Pixels)
		94	Update: Marking figure.
		97	Update: Package Outline figure.
		—	First edition (Official version)
13-Dec-17	E17806A7Z	50	Correction: Description of ch number of LVDS serial output in Drive Timing Chart

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Date of change	Revision	Page	Contain of Change
31-May-19	E17806B95	10	Correction: Pin No "D12"
		29	Correction: prohibited period
		33	Add: Single Write to Random Location, Sequential Write Starting from Random Location
		35	Correction: Reflection timing for TRIGEN
		36	Correction: Reflection timing for VREVERSE and HREVERSE
		41	Correction: Reflection timing for OVERLAP_ROI_EN
		42	Correction: Reflection timing for BLKLEVEL
		51	Correction: Drive Timing Chart for Serial Output
		52	Correction: Details of Image Drawing
		57	Correction: Image Drawing of Designated Areas
		70	Correction: Parameter List of Global Shutter
		97	Update: Notes On Handling
		98	Update: Package Outline

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